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Contents

<u>1</u>	
Introduction to SigXplorer	11
Finding Information about SigXplorer	
What is SigXplorer?	
Invoking SigXplorer	
Invoking SigXplorer with a Clean Canvas	
Invoking SigXplorer by Extracting a Topology	
Exploring SigXplorer	
Measurements Tab	
SigXplorer Workflows	18
Changing Your View of the Canvas and Windows	21
Re-sizing the Canvas	
Working with Foldable Windows	22
Working with Toolbars	
<u>2</u>	
Working with Topologies	27
Creating a Topology	
Creating a Topology from Scratch	
Adding Elements	
Placing Elements	
Wiring Elements	
Common Editing Operations	
Capturing Canvas Images	
What Are DataTips?	
Editing in Context	
Modifying Parameters for Topology Elements	
Default Values for Parameters IOCall Stimulus Parameters	
icacen Sumunic Parameiere	/11

Wiring the Topology	12
T-point Elements	
Scheduling a Topology	15
Rules for Generic Topology Schedules 4	
Managing LayerStacks	
Changing to a Different LayerStack	
Extracting a Topology5	54
0	
<u>3</u>	
Preparing for Simulations	55
Exploring the SigXplorer User Interface 5	56
Common Clock Simulation	57
Introduction5	57
Setting Analysis Preferences 5	57
Setting Stimuli and Running Simulations 6	30
Performing Parametric Sweeps 6	32
Specifying Part Parameter Values for Sweeping	3
Controlling Sweep Sampling and Coverage6	36
Sweep Results 6	
About Sweep Case Data7	70
Saving Sweep Cases 7	70
Restoring and Deleting Sweep Cases 7	72
Viewing Sweep Case Waveforms	⁷ 4
Waveform Labels	⁷ 4
Crossprobing 7	75
Setting Advanced Measurement Parameters	⁷ 6
Measuring and Controlling Glitch 7	7
Eye Diagram Measurements 7	78
Weak Driving Control	30
Full Wave Field Solvers	31
Coplanar Waveguide Support8	32
<u>4</u>	
Assigning Constraints in SigXplorer8	\ F
Introduction	90

Defining Constraints	
Setting Constraints 8	38
Mapping ECSets to Nets using Mapping Tags 8	39
Defining the MappingTag Parameter in SigXplorer	90
<u>5</u>	
Common Clock Interface	95
Introduction	96
Timing Diagram Display in SigWave	97
Adding a Clocked IOCell MacroModel	
Editing a Clocked IOCell MacroModel	
Simulating a Clocked IOCell MacroModel	
<u>6</u>	
Source Synchronous Interface10	21
Introduction	ງ2
Understanding Source Synchronous Custom Measurements	
Marking Strobe and Data Pins	
Creating a New Strobe Pin Group	
Editing Existing Strobe Pin Groups	
Source Synchronous Topology Files	
Setup and Hold Timing Measurements	
Cotap and Hone Firming Micagaremonto	,
<u>7</u>	
Serial Link interface 10	
Overview of Channel Analysis -Serial Link Simulation	
Using the Algorithmic Modeling Interface11	
Translating IBIS Models11	13
Using MacroModel11	16
Adding an AMI Model using the Context-Sensitive Menu Command1	18
Displaying AMI Models11	19
Enabling and Disabling AMI Models	23
Setting a Primary Channel	24
Correlating Channel Simulations	27

Running Channel Analysis from SigXplorer	130
Channel Analysis Characterization and Simulation	130
Common Area	
Characterization Tab	131
Stimulus Tab	132
Preferences Tab	133
Output Tab	134
Advanced Features Tab	135
Incorporating Crosstalk Effects into Channel Analysis	136
Channel Analysis Directory Structure	
8	
Working with Signal Models and Libraries	141
About Signal Models	141
Introduction to Simulation Models	
Device Models	
Interconnect Models	143
Managing Device and Interconnect Models	146
Consuming Signal Models	
Specifying Library Search Order	
Setting Working Libraries	
Managing DML Libraries	
Translating Models	
<u>9</u>	
Device Modeling	163
IOCell	163
<u>Introduction</u>	164
Viewing the Waveform for a Stimulus	165
Defining Terminal Information	166
Defining Measurement Information for Custom and Tristate Stimuli	168
Defining Terminal Offset and Skew for Custom Stimuli	169
ESPICE Device Models	171
Introduction	172
Setting Pin Order	172

12
<u>S-Parameters</u> 213
Introduction
S-Parameter Generation
Defining Ports
Time Domain Analysis
Typical Use Models
Viewing Frequency Response Using S-Parameters
Generating an S-Parameter Black Box224
13
Custom Measurements
Introduction
Measurement Expressions
Exporting and Importing Custom Measurements
Custom Measurement Editor Message Reference

1

Introduction to SigXplorer

Topics in this chapter include

- Finding Information about SigXplorer on page 12
- What is SigXplorer? on page 13
- <u>Invoking SigXplorer</u> on page 15
- Exploring SigXplorer on page 17
- SigXplorer Workflows on page 18
- Changing Your View of the Canvas and Windows on page 21
- Working with Toolbars on page 25

Introduction to SigXplorer

Finding Information about SigXplorer

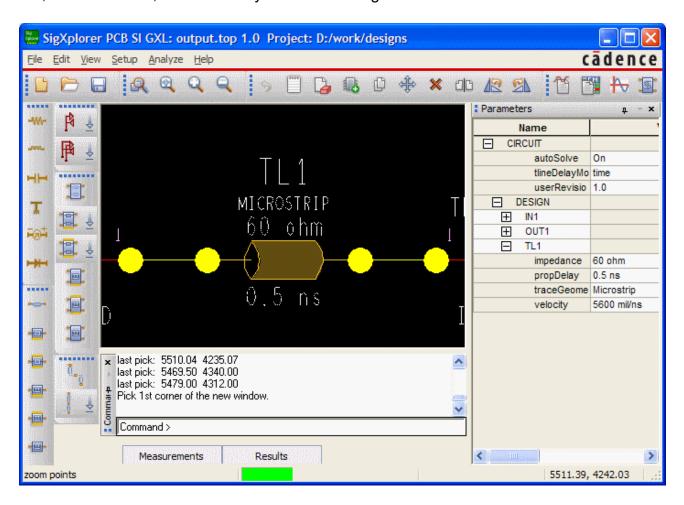
The SigXplorer documentation set consists of online books accessible from Cadence Help in both HTML and PDF formats. You access documentation from SigXplorer's *Help* menu.

Refer to	for this level of information	
Allegro SI SigXplorer User Guide	This book is for users who want to know how to use SigXplorer in the high-speed design flow. It complements the information	
(this book)	in the Allegro SI SigXplorer Command Reference.	
Allegro SI SigXplorer Command Reference	This book contains descriptions and procedures for all commands, organized by menu-sequence. If you click <i>Help</i> in a dialog, or highlight a menu command and press F1, the command description from this book appears. It complements the information in the <i>Allegro SI SigXplorer User Guide</i> .	
<u>Allegro PCB SI</u> <u>User Guide</u>	This book contains reference information about TLsim, the analysis engine used by SigXplorer.	

Introduction to SigXplorer

What is SigXplorer?

SigXplorer is an enhanced, SPICE-based simulation tool that aids you (signal integrity engineers) in exploring, identifying, and solving the adverse analog effects of a digital system. You can use SigXplorer to design the latest high-speed computer interfaces, including serial link, common clock, and source-synchronous designs.



SigXplorer provides access to signal models through a common interface to native Device Modeling Language (DML), and seamless access to IBIS, generic SPICE, HSPICE, and Spectre signal models. The Touchstone and Quad signal models are also supported.

Introduction to SigXplorer

The easy-to-use interface of the tool lets you visually:

- construct (or extract) interconnect topology of a circuit,
- set and sweep a range of circuit parameters for devices (buffers, differential pairs, discretes, and vias), characterize them,
- and generate interconnect (actual or ideal).

This enables you to execute *what-if* scenarios on critical high-speed signals in your board, package, or system-in-package design.

You can define parameters for ideal transmission-line models (faster, but less accurate), trace models (slower, but more accurate), vias, and circuit elements that you add to your topology. You can also define IO cell stimulus to drive simulations and specify what to measure.

There are two 2D transmission line solvers, the quasi-static bem2d and FSVia characterize vias (narrowband, wideband, and s-parameter). The simulation output appears in the *Results* window of the SigXplorer interface, as a comprehensive set of reports, and as a graphical waveform rendition.

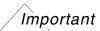
You can capture the constraints that you set in a topology file, and then export it to Constraint Manager for importing as an Electrical Constraint Set (ECSet). This ECSet can then be applied to similar nets in your design, such as members of a bus.

Introduction to SigXplorer

Invoking SigXplorer

This section describes the different methods you can use to invoke SigXplorer.

You can invoke SigXplorer (also called Topology Editor) with a clean canvas or by extracting a topology from a layout tool.



The version of SigXplorer that runs depends on the license you have.

Invoking SigXplorer with a Clean Canvas

- In Windows, do one of the following:
 - □ Choose *Start Run*, and type *sigxp*.
 - Choose Start Programs Cadence Release 17.4-2019 Allegro Products – SigXplorer.
- In UNIX, type sigxp in a Shell window.

-or-

⇒ From a layout tool, choose Tools – Topology Editor.

SigXplorer opens with an empty canvas.

Invoking SigXplorer by Extracting a Topology

From Constraint Manager

- **1.** In Constraint Manager, select a worksheet in the Net folder.
- **2.** Right-click on the net of the topology you want to extract and from the pop-up menu, choose *SigXplorer*.

SigXplorer launches and the topology appears on the SigXplorer Canvas.

From an SI layout tool

1. In your SI layout tool, choose *Analyze – Probe*.

The Signal Analysis dialog appears.

Introduction to SigXplorer

- **2.** Select the net of the topology you want to extract.
- 3. Click View Topology.

SigXplorer launches and the topology appears on the SigXplorer Canvas.

Introduction to SigXplorer

Exploring SigXplorer

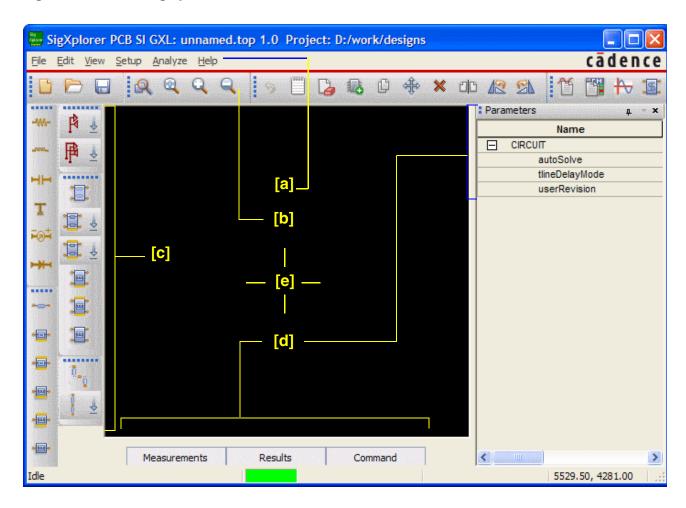
As depicted in Figure <u>1-1</u>, SigXplorer includes the canvas [e], where you graphically construct your topology, and supporting windows [d] for working with *Measurements, Results*, *Commands*, and *Parameters*.



See <u>"Working with Topologies"</u> on page 25 and <u>"Preparing for Simulations"</u> on page 53 for information on the *Parameters* window.

See "Preparing for Simulations" on page 53 for information on the *Commands*, *Measurements*, and *Results* windows.

Figure 1-1 The SigXplorer Canvas



Introduction to SigXplorer

Command access is provided through menus <code>[a]</code> and icons <code>[b]</code>. You also have direct access to signal models (discretes, traces, buffers, transmission lines, and vias) through icons <code>[c]</code>. Passing the cursor over any of the tabs at the bottom of the screen, <code>Command</code>, <code>Measurements</code>, and <code>Results [d]</code>, unfolds the window for viewing or editing. The Parameters window can also be dragged to the bottom as a tab to create more space on the canvas <code>[e]</code>.

Measurements Tab

The Measurements tab contains four sections, EMI, Reflection, Crosstalk, and Custom. There is a pull-down menu for each section which includes all standard measurements available for the first three sections. All the currently available custom measurement expressions are available under the Custom section. User-defined custom measurements appear alphabetically, following the standard measurements.

Note: The Measurements tab is grayed out for Cadence SiP Layout XL.

The status bar text at the bottom left of the window displays the active command. The middle of the status bar is colored red during simulation, and green when finished. The right-most status bar text shows the horizontal and vertical coordinates of your mouse pointer.

SigXplorer makes extensive use of context-sensitive pop-up menu (right-click) for easy access to element parameters and commands. See <u>Editing in Context</u> on page 34 for more information.

SigXplorer Workflows

You can use SigXplorer in the flows as depicted in Figure 1-2 below:

Design Database Constraint Manager SigXplorer Reports Electrical Constraint Set Signal Integrity i 🛅 Timing IC Package Routing SiP Model Editor SigXplorer SigWave br_sems JA_device 13, 39071.79 🗻 Rise M Poll

Figure 1-2 The SigXplorer Flow

SigXplorer Flows

■ Exploration

In the exploration flow, your focus is on setting up access to libraries, developing signal models, and performing extensive *What-If* analysis. You may not have access to a design database, but you can speculate how a particular component and its interconnect will behave in your topology. You will simulate for *reflection*, *crosstalk*, and *EMI*, derive constraints, and then save them in a topology template file for later reuse.

Tools you use in the Exploration flow include *SigXplorer* and *SigWave*.

■ Pre-Route Analysis

In the pre-route analysis flow, your focus is on extracting a signal from a placed component in a PCB, Package, or System-in-Package (SiP) database (fully or partially routed), modifying various components and pin buffers, as well as interconnect, and then setting a range of sweepable parameters to simulate them in TLsim, SigXplorer's native simulator. Depending on the simulated results, you may decide to modify parameters, measurements, or simulation settings, or add a termination scheme. You can also use

Introduction to SigXplorer

the imported cross-section, and modify it to see the effects on your topology. You capture constraints in a topology template file and import it to Constraint Manager as an Electrical Constraint Set (ECSet) to refresh the design.

Note: The SigXplorer environment also supports the HSPICE and Spectre (Unix only) simulation engines.

Tools you use in the pre-route analysis flow include *SigXplorer*, *SigWave*, *Constraint Manager*, and a PCB, Package, or SiP layout tool.

■ Post-Route Verification

In the post-route verification flow, your focus is on extracting a signal from a PCB, Package, or SiP database (fully routed), setting sweepable parameters, and simulating the topology. You use the *Results* window of SigXplorer, built-in reports, and SigWave to verify that the integrity of the signal meets your requirements.

Tools you use in the post-route verification flow include *SigXplorer* and *SigWave*.

Introduction to SigXplorer

Changing Your View of the Canvas and Windows

The easiest way to zoom in and out, and move (roam or pan) across the canvas, is using the middle mouse button.

You can pan a topology (move across a topology in the canvas) to view different parts in it. To pan a topology, you need to hold the cursor inside the canvas, and then click and hold the middle mouse button as you drag the cursor across the topology. As long as the mouse button remains pressed, you can move all areas of the topology into full view.



Use the arrow keys on your keyboard to pan in the desired direction.

To zoom in or out, rotate the scroll wheel of the mouse. <u>Table 1-1</u> on page 21 displays the SigXplorer icons and keyboard shortcuts you can use to perform various zoom functions.

Table 1-1 Zoom Functions

Choose View -	Shortcut	Function
Zoom By Window		Magnifies the display so that the specified, bounded, region fills the canvas.
Zoom Fit	F2	Changes the display so that the topology fills the canvas
Zoom Center	ΓZ	Changes the display so that the topology is left justified and centered vertically within the canvas
Zoom In	Q	Magnifies the topology to make it larger and display less of it in the canvas.
	F11	
Zoom Out	Q	Shrinks the topology to display more of it in the canvas
	F12	

Introduction to SigXplorer

Choose View – Shortcut Function

Zoom Previous SHIFT+F11 Displays the previous zoomed view of the topology

on the canvas

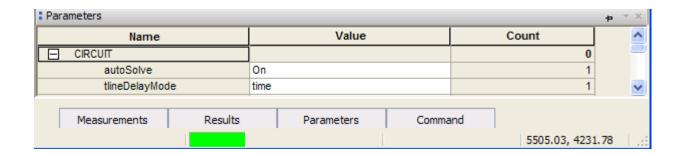
Re-sizing the Canvas

You can move the border between the spreadsheet window and the canvas to increase or decrease the view. You need to drag the edge of the border of the spreadsheet with your mouse, and then move the divider left or right, as required.

Working with Foldable Windows

The foldable windows are particularly useful on a single monitor setup because they provide more work space, while giving you the option of seeing the window information by hovering your mouse over their respective tabs: *Command, Measurements, Results.*

Passing the cursor over any of the tabs unfolds the window for viewing or editing. As you move the cursor off of the tab, the corresponding window retracts. By default, the *Parameters* window appears on the right of the application window. To create more workspace, you can drag it to the bottom of the screen. When you pin the window, it retracts to the bottom as a tab. As you hover the mouse pointer over each tab, the corresponding window appears.



Introduction to SigXplorer

Persistent Windows

Rather than having a window retract when you move your cursor away from it, you can make the visibility of the window persistent by passing your cursor over a tab, and then clicking the pin.



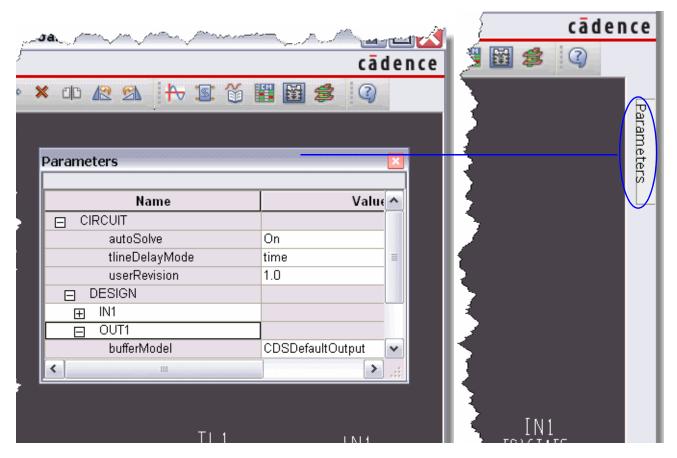
You can click the pin again (unpin) to make it retractable, or click x to close a pinned window.

Note: If you close a window once, you must choose View - Window - [Window Name] to restore its visibility.

Introduction to SigXplorer

Undocking Windows

If you have pinned a window (see <u>Persistent Windows</u> on page 23), you can relocate it by dragging it by its title border anywhere on your desktop. You can unpin the window to make it retractable.





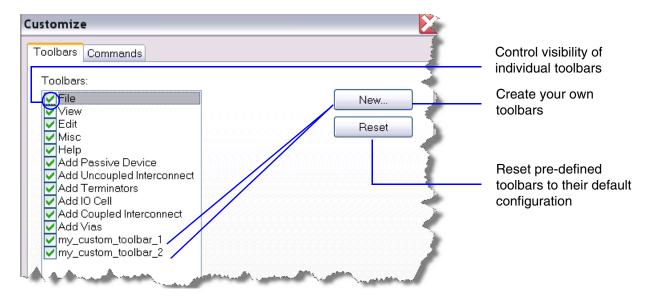
To restore windows to their default locations (*Command, Measurements, Results* at the bottom of the canvas and *Parameters* to the right), choose *View – Reset UI to Cadence Default*.

Introduction to SigXplorer

Working with Toolbars

SigXplorer contains many icons for quick access to commands. Icons are logically organized by function into toolbar groups. You can selectively show or hide toolbar groups (see Figure 1-3).

Figure 1-3 Customize Dialog (Toolbars tab)

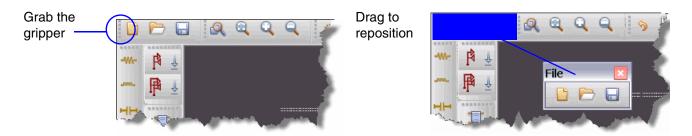


Toolbars can also be repositioned (undocked) within or outside the canvas, anywhere in your workspace, independent of other toolbar groups. You can also change the member icons of a pre-defined toolbar group by adding or removing icons. For maximum flexibility, you can create your own custom toolbar groups (see <u>Figure 1-4</u> on page 26).

Introduction to SigXplorer

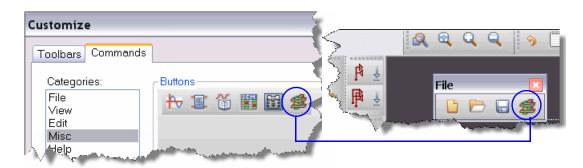
Figure 1-4 Customize Dialog (Commands tab)

Inducting a Toolbar



Redefining a Toolbar

Drag icon to toolbar





To learn the name of a toolbar group, undock it.

With the *Commands* tab active, as shown in Figure <u>1-4</u>, you can drag any icon from a predefined toolbar (that surrounds the canvas) to remove the icon from that toolbar group. To restore a deleted icon to its pre-defined toolbar, choose *View – Reset UI to Cadence Default*.

2

Working with Topologies

Topics in this chapter include:

- Creating a Topology on page 28
- Common Editing Operations on page 31
- Modifying Parameters for Topology Elements on page 37
- Wiring the Topology on page 42
- Scheduling a Topology on page 45
- Managing LayerStacks on page 50
- Extracting a Topology on page 54

Working with Topologies

Creating a Topology

There are three use models for working with topologies in SigXplorer:

- Create a new circuit topology from scratch
- Open an existing topology saved from an earlier session
- Extract a topology from a PCB, IC Package, or SiP database (see Extracting a Topology on page 54)

Creating a Topology from Scratch

You create a topology (in a Constraint-driven flow) by:

- **1.** Adding Elements or models from the Cadence default libraries or from user-defined libraries.
- 2. Placing each element in the SigXplorer canvas.
- **3.** Wiring the elements.

Using SigXplorer, you capture the net schedule (see <u>Scheduling a Topology</u> on page 45), impedance, delay, and termination of a net, and save it to a topology template. A single topology template can control an entire bus. You package the constraints as an electrical CSet (ECSet), which applies to every net. This eliminates the need to create a topology for each net of the bus.

Working with Topologies

Adding Elements

You add elements (models) to the topology using the Add Element Browser window. To display this window, use one of the following three methods:

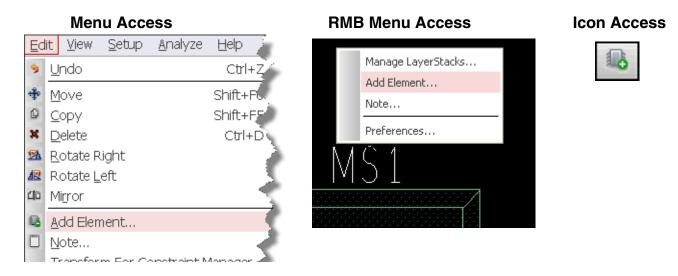
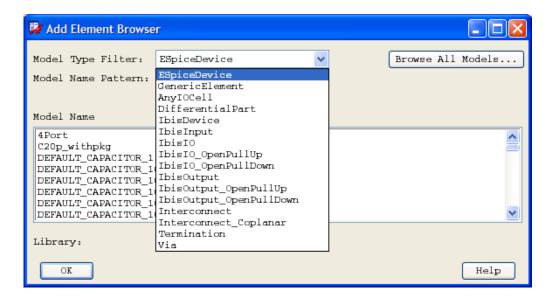


Figure 2-1 Add Element Browser



Placing Elements

When you select a model in the Model Name list, the corresponding symbol for the model is attached to the end of your cursor as you drag it to the canvas. The element is instantiated

Working with Topologies

with each click that you make on the canvas. You must right-click and choose *End Add* from the pop-up menu to stop instantiating the selected element on the canvas.

Wiring Elements

You wire or connect elements on a canvas by selecting yellow dots on each part. To continue a connection, you need to double-click on the wire stub.

You can edit the topology using any of the editing features available in the SigXplorer interface. For more information, see the <u>SigXplorer Command Reference</u>.

Working with Topologies

Common Editing Operations

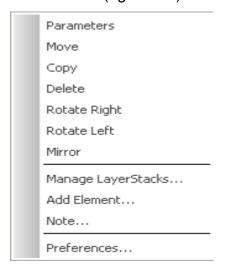
As you develop your topology, you need to be aware of SigXplorer's useful editing techniques, such as moving, copying, deleting, rotating, and mirroring elements on the canvas. Rotating and mirroring parts can improve the readability of topologies or fix issues where connections are crossed.

Along with keyboard shortcuts, and icons, there are two menus, which help you perform editing operations on a selected element on the canvas.





Context Menu (right-click)



Selecting Elements

To perform an edit operation on elements (move, copy, delete, rotate, or mirror), you must first select them on the canvas.

Working with Topologies

Note: You can do Ctrl+click to add to, or remove from, a group of selected elements.

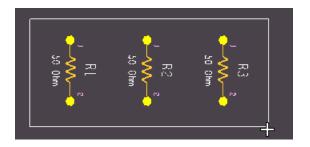
Single-element Selection

Click an element to select it.

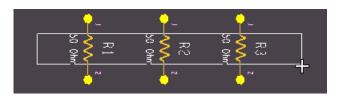
The middle resistor is selected,
as indicated by the change in
color.



Multiple-element Selection (enveloping)



Multiple-element Selection (swipe)



Moving, Copying, and Deleting Elements

To move an element:

- 1. Click the element.
- 2. Drag and drop the element to anchor it elsewhere on the canvas in a single operation.

To move multiple elements:

- **1.** Click the first element.
- 2. Keeping the Ctrl key pressed click the other elements.
- 3. Once you have selected the elements you want to move, drag them to the new location.

To copy an element:

- **1.** Select the element.
- **2.** Keeping the *Ctrl* key pressed move the element.
- 3. Click to anchor the element elsewhere on the canvas.

Working with Topologies

To copy multiple elements, after you have selected the elements, click the location where you want to copy the elements. Ensure that the *Ctrl* key is pressed all the while.

To delete an element:

- **1.** Select the element.
- 2. Choose *Delete* from the *Edit* menu OR right-click the element and choose *Delete* from the pop-up menu

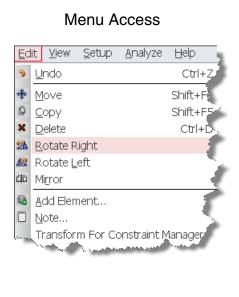


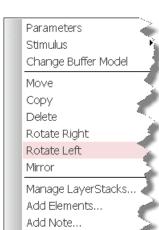
You can also press the *Ctrl—D* key combination to delete a selected element on the canvas. To delete multiple elements, select the elements keeping the Ctrl key pressed and then press the *Ctrl—D* key combination.

Working with Topologies

Rotating Elements

SigXplorer can rotate an element on the canvas 90° clockwise, or counter-clockwise. If an element has been rotated in one direction, it can only be rotated in the opposite direction. Therefore, an element cannot be rotated upside down.



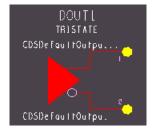


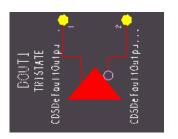
RMB Access

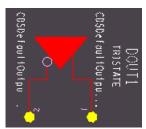












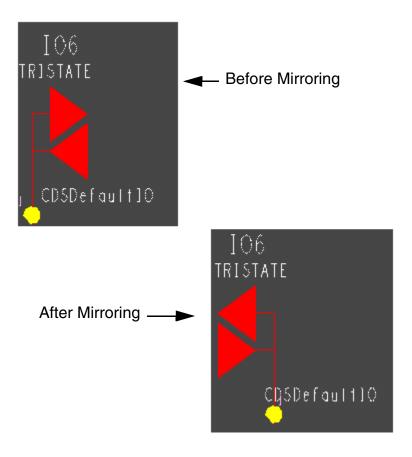
Mirroring Elements

To mirror an element, select it and choose *Mirror* from the *Edit* menu or the context-menu. You can also click the Mirror Selected icon on the toolbar after selecting the element on the canvas.



Working with Topologies

For mirroring multiple elements, you must first use one of the multiple-element selection techniques.



Capturing Canvas Images

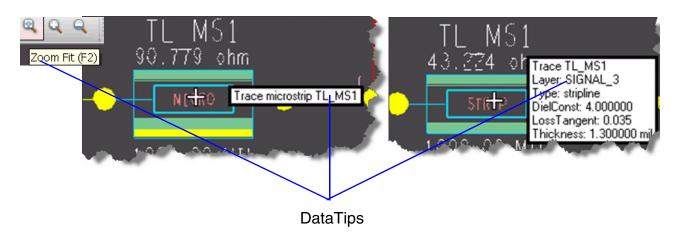
You can create images of the canvas for pasting in documents or graphic editors. To capture an image of the canvas, do the following:

- 1. Choose File Capture Canvas Image.
- 2. Open the target application, such as Microsoft Word or MS Paint and paste the captured image by choosing *Edit Paste* or *Paste* from the RMB menu.

Working with Topologies

What Are DataTips?

SigXplorer uses datatips or tooltips to reveal information about icons and elements on the canvas. A datatip can be as concise as the brief usage tip that appears when you hover your cursor over an icon, or as detailed as parameters set on a trace model.





Briefly hover your mouse cursor over an icon to display a datatip describing the purpose of the icon.

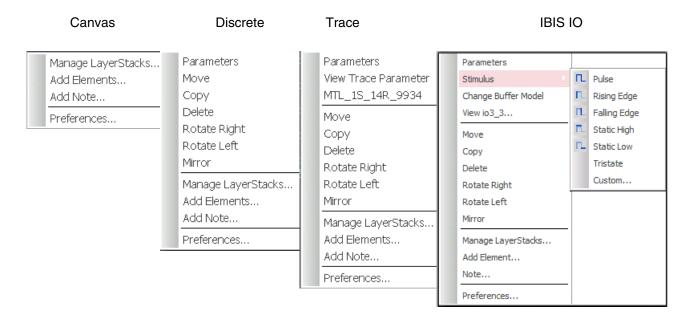
Editing in Context

SigXplorer supports right-click access to commands in the context or pop-up menu. Commands in this pop-up menu vary in context, depending on what is selected—an element on the canvas, or the canvas itself.)

Notice that the *Preferences* command is listed last and the *Parameters* command is listed first (except when you right-click on the canvas). General editing commands are clustered together and element-specific commands are listed at the top (see <u>Context-Menu Commands</u> (based on selection) on page 37).

Working with Topologies

Figure 2-2 Context-Menu Commands (based on selection)



Modifying Parameters for Topology Elements

In SigXplorer, circuit data and element parameters (and their values) are maintained in the *Parameters* window. When you place an element on the topology, you see both the symbol and associated text fields that describe default parameters and other information associated with the element (see Figure 2-3). After simulating, you edit this data to further refine the circuit design.

Working with Topologies

Parameters д - > Name Value Coun CIRCUIT On autoSolve tlineDelayMode userRevision 1.0 DESIGN +101 +102 TL_MS1 101d1Constant TRESTATE d1LossTangent 0.035 d1Thickness 10.00 MIL d1FreqDepFile d2Constant TL MSJ d2LossTangent 0 90.779 ohm 0.00 MIL d2Thickness d2FreqDepFile 5000.00 MIL Trace microstrip TL_MS1 5000 00 MIL traceConductivity 595900 mho/cm traceEtchFactor 90

Figure 2-3 A Placed Element on the Canvas (Parameters Window Undocked)

You can modify the following parameter information:

Name (Reference Designator or RefDes)

If you click the label <code>TL_MS1</code>, for example to select the RefDes, the Parameters window opens to display all the parameters associated with the element and the value for each. The selected RefDes parameter is highlighted and ready for editing. After you complete the editing, the updated data is reflected in both the <code>Parameters</code> window and the canvas.

Value

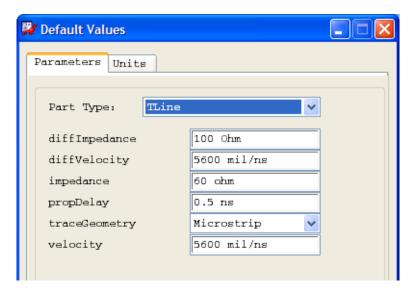
To highlight the associated row for an element in the *Parameters* window, click the value of the element in the canvas and specify a new parameter value. After you complete the editing, the updated data is reflected in both the *Parameters* window and the canvas.

Default Values for Parameters

When you place an element on the canvas, a default set of parameter values are assigned to the element. You can modify these default values for component models, interconnect

Working with Topologies

models, and terminator models, using the Default Values dialog (Setup - Defaults). For more information, see <u>SigXplorer Reference</u>.



Note: When you modify a default value, it becomes the new value of the element whenever you place the symbol on the canvas.

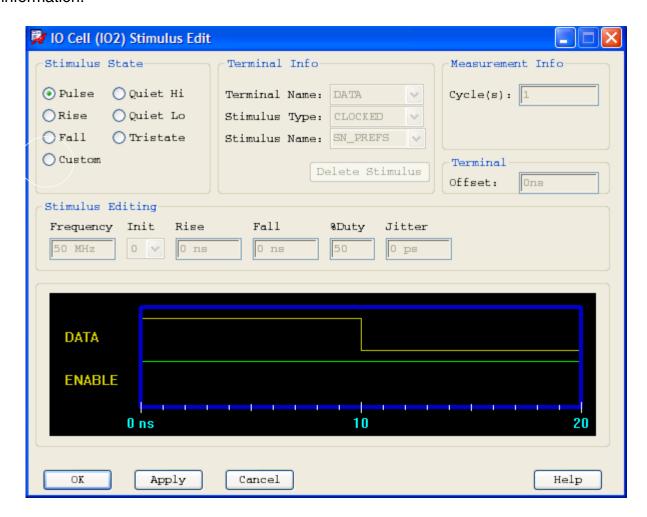
Working with Topologies

Using the *Default Values* dialog, you can:

- Select any of the generic component models, interconnect models, and termination models available in the *Model Browser*.
- Display the parameters for the element and the default value associated with each parameter.
- Modify the default parameter values.

IOCell Stimulus Parameters

The *Parameters* window does not contain the stimulus data for IOCell parts. You use the *IOCell Stimulus Editor* to modify this information. See <u>SigXplorer Reference</u> for more information.



Working with Topologies

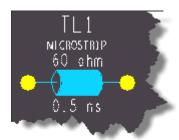


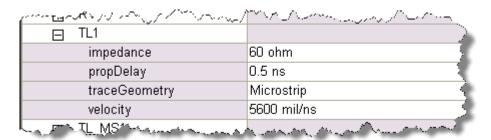
You can access the IO Cell Stimulus Editor by choosing Stimulus from the pop-up menu when you right-click on the IO component.

Working with Topologies

Wiring the Topology

An ideal transmission line (TL or Tline) element in SigXplorer is characterized by *impedance*, *propDelay*, *traceGeometry*, and *velocity* values, which you can view in the *Parameters* window. Of these four, the *fundamental* parameters are *impedance* and *velocity*.





The *propDelay* parameter, as an indication of trace length, is defined in nanoseconds, while *velocity* is defined in mils-per-nanoseconds.

The traceGeometry parameter does not affect simulations, but allows you to set default velocity values to any microstrip or stripline transmission lines you add to your topology. Knowing the parameters of *impedance* and *velocity/propDelay*, you can infer L and C per unit length to define an ideal (loss less) transmission line.

Advantages of using a lossless transmission lines in pre-layout simulations are faster simulation times when compared to MS/SL, and slower absorbtion rate of reflection, particularly when simulating very long trace lengths for a termination scheme. Once you have established a satisfactory base, you may substitute the lossless transmission lines for microstrip or stripline models.

To wire a topology, click the pin of a topology element (see <u>Figure 2-4</u> on page 43). As you move the cursor, a wire moves with the cursor away from the pin. Click the destination pin on another element. A wire is drawn between the elements. Click another pin to extend the wire.

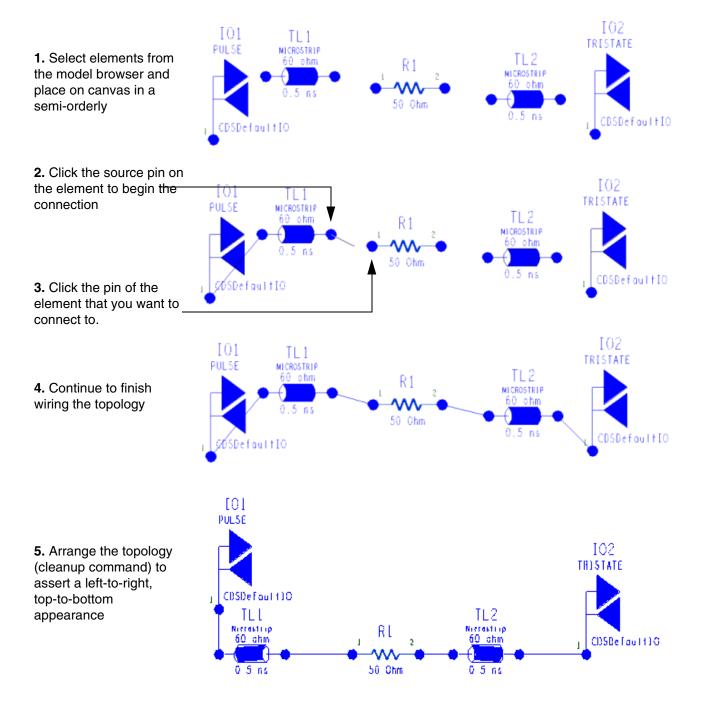
Note: To delete a wire from the topology, click on the wire anywhere, except where it meets the pin of an element.

SigXplorer provides the following two methods for wiring a topology:

- Pin-to-Pin Method as shown in <u>Figure 2-4</u> on page 43
- Pin-over-Pin Method as shown in Figure 2-5 on page 44

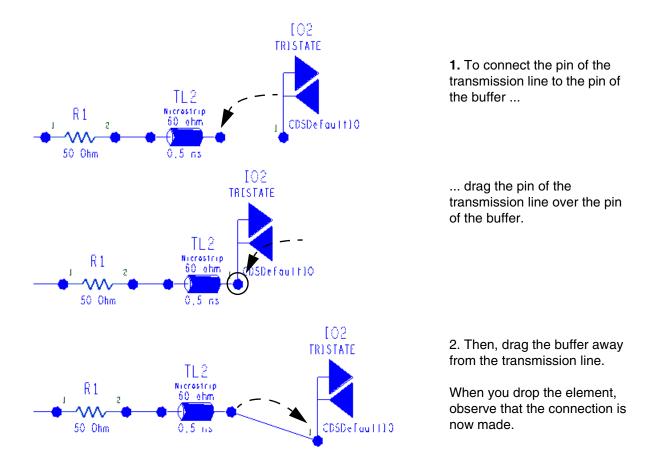
Working with Topologies

Figure 2-4 Wiring a Topology: Pin-To-Pin Method



Working with Topologies

Figure 2-5 Wiring a Topology: Pin-Over-Pin Method

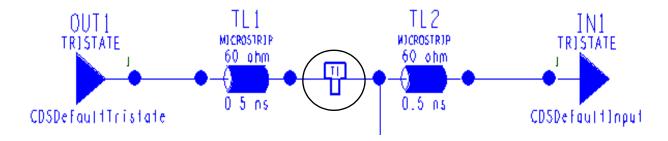


T-point Elements

SigXplorer automatically places a T-point element at the junction of two or more transmission lines (TLines) with no other pins on the node, as shown in <u>Figure 2-6</u> on page 45. T-points represent pin-to-tee and tee-to-tee constraints. Symbols visually indicate T-point instances in the topology. You select these references in the <u>Set Topology Constraints</u> dialog to specify TLine (prop delay, impedance, and relative prop delay) constraints.

Working with Topologies

Figure 2-6 T-Point Elements in SigXplorer



Scheduling a Topology

There are two methods of scheduling a topology. You can wire the topology interactively and create a template schedule or automatically schedule the topology by selecting from a set of generic templates.

Using a generic schedule is advantageous, because it is a fast way to create a topology. In this method, you first place the IOCells on the canvas, and then select a schedule. All of the necessary TLines immediately add and connect to the IOCell pins. If you decide not to select a generic schedule, you need to add and connect each TLine to form the net schedule.

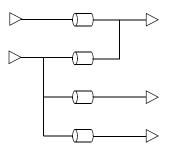
When you extract a topology template with a generic schedule into Constraint Manager, the electrical constraint set stores the specified type of schedule as a *ratsnest schedule* constraint in the constraint set. When you assign the constraint to a net, the ratsnest schedule constraint performs the specified type of ratsnesting for that net.

The ratsnest schedule of pins of the net, assigned by the constraint set, is not necessarily the same as the order of the pins as seen in SigXplorer. The ratsnest schedule depends upon the placement of the pins. The topology, simulated in SigXplorer, might not be the same as the topology assigned to the net on the board. To ensure that the net follows the schedule, apply a generic schedule, and then interactively edit any of the TLine connections, as necessary. This changes the schedule type from the selected generic schedule to a template schedule.

Working with Topologies

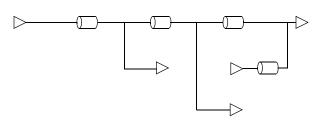
The following are the schedule types available in SigXplorer:

Min Spanning Tree



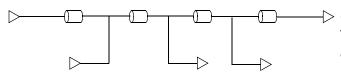
Connects all pins together with minimum connection lengths. Any pin can connect to any number of other pins. This schedule starts at the primary driver and selects the closest pin to this driver and connects it to the driver through a TLine. The search continues by selecting the next unscheduled pin that is closest to any of the scheduled pins and connecting it with a TLine to the pin to which it was closest. This continues until all pins are connected.

Daisy Chain



Connects pins of the topology with minimum connection lengths, only allowing each pin to connect to a maximum of *two* other pins. This schedule starts with the primary driver, and then the closest pin to this driver is connected with a TLine. The closest pin to the last pin scheduled is connected with a TLine. This continues until all pins are connected.

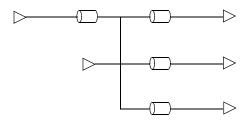
Source Load Daisy Chain



Similar to a daisy chain schedule, except that all driver pins connect first, followed by all receiver pins.

Working with Topologies

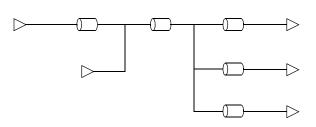
Star



Connects driver pins, which are daisychained together, and then all of the receiver pins connect to the last driver pin.

For Star topologies, the driver pins are scheduled in a daisy chain and then all the receivers are connected to one of the ends of the daisy chain. Each of the driver pins are selected as the start point for the daisy chain. The one that creates the shortest total ratsnest line length for the net is selected.

Far End Cluster



Similar to a star schedule, except that the last driver pin connects to a T-point to which all of the receivers connect.

In a Far-End schedule, the T-point is selected as the mean X,Y point of all the receiver pins.

Note: You can control the Star and Far-End schedules with the DENSE_COMPONENT property. This property is assigned to a component. If a net contains any driver pins on components with this property, only those pins will be considered as the start point for the daisy chain.

Rules for Generic Topology Schedules

The following are general rules to follow for any type of generic schedule:

■ When automatically scheduling the pins in a topology, the only restriction on allowable elements is when the topology defines a differential pair. In this case, the inverting and non-inverting signals must contain the same number and types of pins.

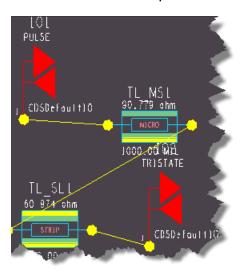
Working with Topologies

- A message prompts for permission to delete all unmatched pins. All the other types of elements are scheduled.
- The proximity of the pins to each other determines the scheduling.
- If all the pins are drivers, the selected schedule is a daisy chain.
- If all the pins are receivers and the schedule is a far-end cluster, all the pins are connected to a T-point.
- If all the pins are receivers and the schedule is a star, all the pins are connected to one of the receiver pins.
- All types of scheduling start with sequencing the pins with the primary driver.
 - ☐ If the topology only contains one driver IOCell, it is considered the primary driver.
 - ☐ If there are multiple drivers, the active one is selected.
 - ☐ If there are multiple active drivers, one of the active drivers is selected.
 - ☐ If there are no active drivers, one of the non-active drivers is selected.
 - ☐ If there are no drivers, but there is a non-active bidirectional pin, the bidirectional pin is selected.
 - If a topology contains no drivers or bi-directional pins, then a warning appears, and the schedule type resets to template and no changes occur.
- Any terminator, correctly connected to a pin, remains intact during scheduling.

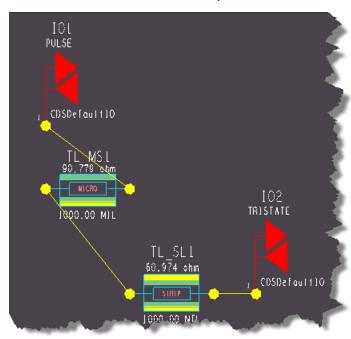
Working with Topologies

■ After you assign a schedule to a topology, use the cleanup command to redraw the topology on the canvas (*Edit - Cleanup*).

Before Cleanup



After Cleanup



Managing LayerStacks

SigXplorer supports multiple layers, which you can create from scratch, or import from a PCB, IC Package, or System-in-Package (SiP) database. Managing LayerStacks includes:

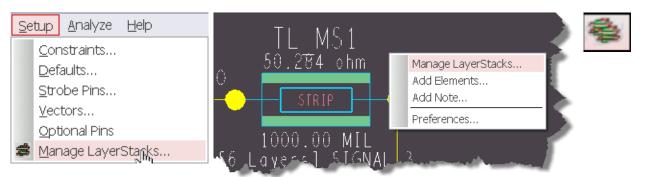
- Moving an element, such as a trace model, among different layers
- Modifying trace width or length
- Experimenting with dielectric constant, loss tangent, materials, and layer thickness values to solve for optimum impedance

Note: You can export LayerStacks that you create to a technology file (.tcf).

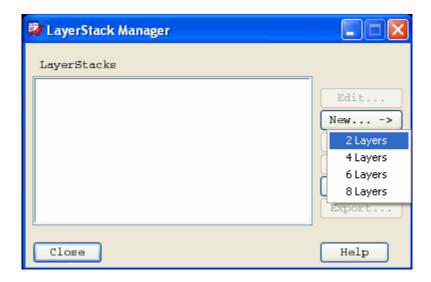
To create a new LayerStack:

1. Launch the LayerStack Manager dialog using any one of the following methods.

Menu Access RMB Access Icon Access



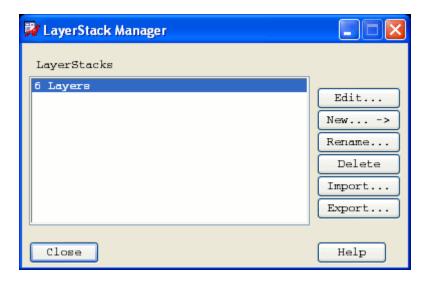
2. Choose New.



Working with Topologies

- 3. Select from 2-, 4-, 6-, or 8-layer defaults to seed your stackup.
- 4. Specify a name for the LayerStack and click OK.

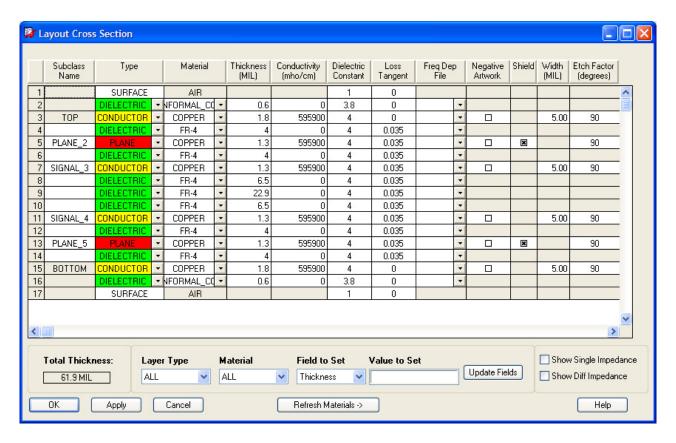
The new LayerStack is listed in the LayerStack Manager dialog.



At this point, you can *rename* the default LayerStack that you selected, which is a good idea if you intend to add or remove layers.

Working with Topologies

When you click a LayerStack and choose *Edit*, the *Layout Cross Section* dialog appears.



SigXplorer uses the same Layout Cross Section dialog as the SI layout tools.

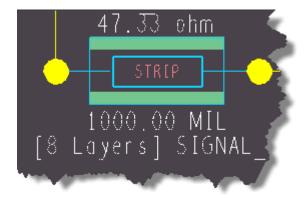
Changing to a Different LayerStack

The RMB (pop-up) menu (Figure <u>2-7</u>) shows how to disassociate an element from a LayerStack, and how to associate it with a different LayerStack.

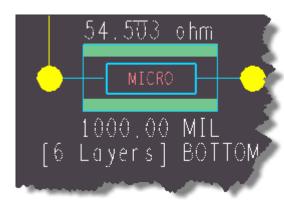
Figure 2-7 Changing Layers



Original [8 Layers]



Modified [6 Layers]

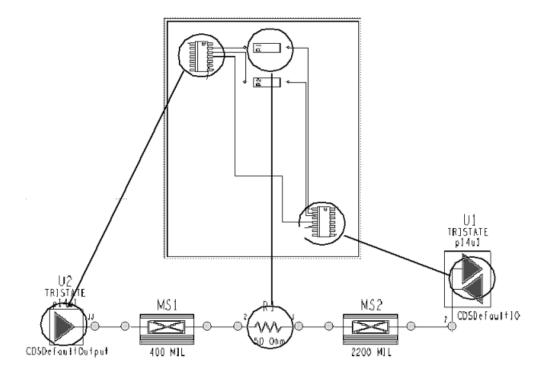


In Figure <u>2-7</u>, the trace model was relocated from an 8-layer, stripline LayerStack to a 6-layer, microstrip LayerStack. Note the change in the label of the trace model, and the change in impedance values.

Working with Topologies

Extracting a Topology

You extract a net topology from the SI layout tool (directly, or through Constraint Manager) into SigXplorer to see if it meets signal integrity requirements. If not, you can modify the topology until it does meet the requirements.



The $\underline{SI\ Design\ Setup}$ command ($Setup-SI\ Design\ Setup$ in the SI layout tool) is a utility used to bridge the physical design representation in the SI layout tool with the equivalent electrical design representation in SigXplorer, by guiding you through the steps necessary to ensure a clean net extraction from the SI layout tool's database.

Preparing for Simulations

3

Preparing for Simulations

Topics in this chapter include:

- Exploring the SigXplorer User Interface on page 56
- Common Clock Simulation on page 57
- Performing Parametric Sweeps on page 62

Preparing for Simulations

Exploring the SigXplorer User Interface

Using SigXplorer you can create a circuit topology in the canvas and create or modify the supporting data in the integrated spreadsheet.

For more information on menu commands and procedures, see <u>Allegro SI SigXplorer</u> <u>Command Reference</u>.

To set up and perform simulations, you need to use commands accessed through menus and the toolbar, as shown in <u>Table 3-1</u>.

Table 3-1 Performing Simulations

То	Choose
Prepare for simulation	Set – Defaults from the Menu or the Parameters tab
Perform simulation	Analyze – Simulate
Monitor progress of the simulation	Command tab
View simulation results	Results tab or open SigWave to view the waveforms

Preparing for Simulations

Common Clock Simulation

Introduction

Once you have a valid topology displayed in the canvas, you are ready to simulate. You can use default simulation parameters to control how the simulation performs, or you can modify the simulation parameters before you start the simulation.

The simulation results appear as data in spreadsheet format and as waveforms. After viewing the simulation results, you can modify the circuit topology and simulation parameters and then re-simulate to examine the effects of your changes.

Repeat this process until the circuit meets your requirements. For information on simulation and analysis, see the *Allegro PCB SI User Guide*.

Setting Analysis Preferences

To set the simulation preferences or to modify the simulation results, choose *Analyze – Preferences* from the SigXplorer menu.

The Analysis Preferences dialog consists of the following tabs:

Pulse Stimulus

Determines values for the pulse stimulus, including:

- Measurement Cycle
- Switching Frequency
- Duty Cycle
- Offset

S-Parameters

Determine:

- Transient Simulation Method
- DC Extrapolation Method
- (Enforce) Impulse Response Causality

Preparing for Simulations

Simulation Parameters

Determine simulation parameters, including:

- Fixed Duration
- Waveform Resolution
- (Default) Cutoff Frequency
- Buffer Delays
- (Save) Sweep Cases
- Algorithm Model Generation
- Simulator
- Solver

Simulation Modes

Select simulation modes to perform a single simulation or simulation sweeping, including:

- FTS Modes(s): Fast, Typical, Slow, Fast/ Slow, Slow/Fast
- Driver Excitation: Active_Driver, All_Drivers
- Fast/Typical/Slow Definitions

Measurement Modes

Select Measurement Modes to specify:

- Measure Delays At
- Receiver Selection
- Custom Simulation
- Drvr Measurement Location
- Rcvr Measurement Location
- Report Source Sampling Data
- Advanced Settings for:
 - Glitch control
 - Eye diagram measurements

September 2023 58 Product Version 23.1

Preparing for Simulations

EMI

Set preferences and defaults for EMI single net simulation, including:

- EMI Regulation
- Design Margin
- Analysis Distance

Measurement Location

Pin and/or die measurement location for driver and receiver can be determined from the DML model defined in the setup, from the external pin node, or from the internal die node, if present. You can set these choices in the <u>Analysis Preferences</u> dialog (*Analyze – Preferences*) or by using the <u>signoise</u> batch command.

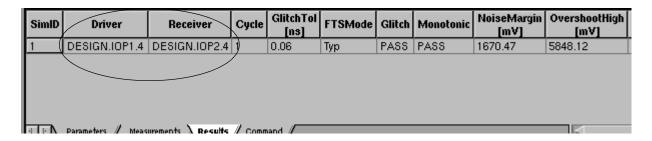
Note: Editing measurement locations in the defined DML model involves manually changing the DML file by adding or deleting the appropriate keywords using the correct syntax in the appropriate section. Pin and die measurement locations are made at the external pin node and internal die node, respectively.

The following convention is used in the Results spreadsheet to distinguish whether the measurement is being made at the pin pad or the die pad:

- If taken at the pin pad, the pin pad measurement name is identical to the pin name (for example, PIN5).
- If taken at the die pad location, the pin name is displayed with an i appended to it (for example, Pin5i).

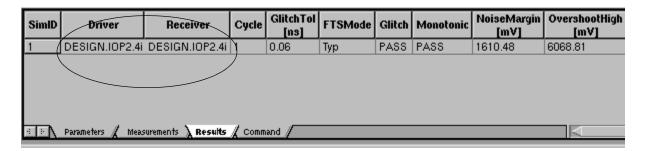
The following examples illustrate these results.

Figure 3-1 Pin Measurement Selection Report



Preparing for Simulations

Figure 3-2 Die Measurement Selection Report



For more information, see the <u>Allegro SI SigXplorer Command Reference</u>.

Setting Stimuli and Running Simulations

When you have added all the parts to (or extracted the parts into) the topology, you need to choose a stimulus type for the driver. You can specify only one IOCell at a time to be the driver. All the other IOCells must be set to tri-state.

There are several types of stimulus for a driver:

- Pulse
- Rise
- Fall
- Custom
- Quiet Hi
- Quiet Lo
- Tristate

You choose a stimulus based on the AC input used for simulation. The driver output for a pulse starts at the circuit low DC point, so you use the stimulus to determine the low point.

You then extract a selected net (ratsnest) from the board layout for exploration and topology development. This unrouted interconnect models after Manhattan distance estimates based on your initial placement.

You simulate and analyze the topology, making trade-off decisions that involve:

target impedance

Preparing for Simulations

- min/max length (or propagation delay)
- pin ordering
- termination strategy (and location on net)

When the simulation finishes, the Results tab pops to the top of the Spreadsheet and the SigWave window opens. The Results tab displays data for the simulation, and the SigWave window displays waveforms resulting from the simulation. You can examine the simulation results in the spreadsheet and in SigWave.

You then note what changes to make in the board design. You can modify the board by:

- adding components (terminators, etc.)
- swapping components
- moving components
- moving nets on microstrip layers to stripline layers
- adding shield or etch layers to the stackup
- varying trace geometry
- re-routing to a new pin order

When the simulation results are satisfactory, you can do one of the following:

- If you have extracted the topology into SigXplorer, you can upload the design into Allegro SI
- If you have created a new topology or opened a previous topology in SigXplorer, you can proceed by saving the constraints with the topology (see <u>Defining Constraints</u> on page 85).

Performing Parametric Sweeps

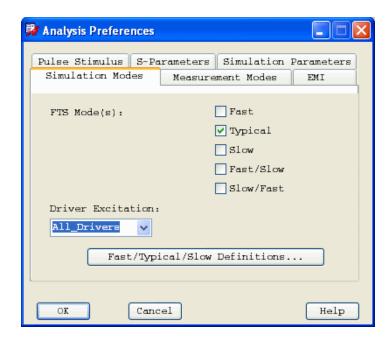
Simulation sweeping relies on combinations of the following criteria:

- Varying part parameter values
- Varying driver slew rates
- Sequencing active drivers

Sweeping by part parameter values involves covering a set or range of values (sweep count points) that you specify for eligible sweep parameters through a set of simulations. SigXplorer calculates the total number of simulations based on the number of sweep count points required for each sweep parameter.

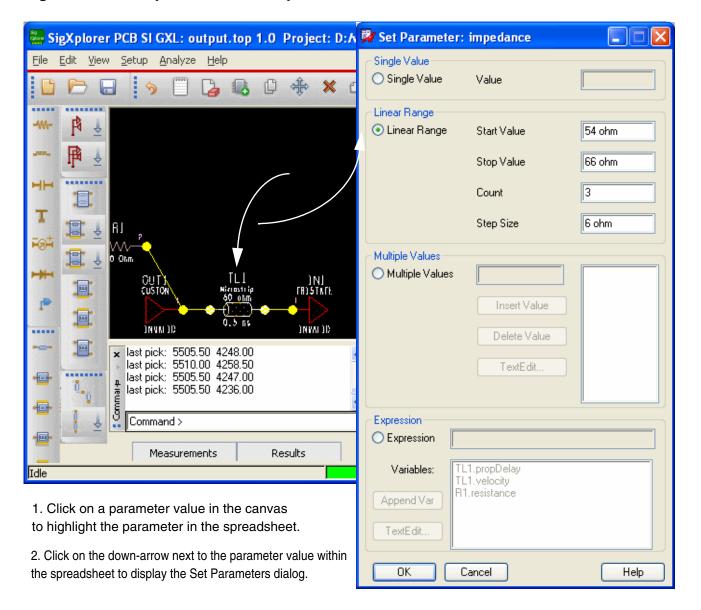
You sweep by driver slew rate by selecting a set of FTS Mode target rates from the <u>Simulation Modes</u> tab in the Analysis Preferences dialog.

You accomplish sweeping by sequencing active drivers by selecting *All Drivers* sweep mode to sequence through eligible IOCells with each one, in turn, driving a simulation.



When you specify multiple sweep criteria, SigXplorer uses a hierarchical ordering when performing the simulations. For example, if you select multiple FTS Modes, as well as several part parameter values for sweeping, then all part parameter sweeps execute for each selected FTS Mode. Additionally, if you also select All Drivers, then part parameter sweeps for each selected FTS Mode execute as each driver activates in sequence.

Figure 3-3 Sweep Parameter Setup



Specifying Part Parameter Values for Sweeping

All parameter attributes, including parameter that you can sweep, are accessible for viewing and editing through the Parameters tab of the SigXplorer spreadsheet.

Parameters that you can sweep include:

single number value

Preparing for Simulations

- linear range of number values specified as start and stop values and a step size for iterating from start (the minimum value) to stop (the maximum value).
- list of discrete number values
- expression string composed of operators, functions, and references to other parameters.

When you use an expression to define a parameter attribute that references a second parameter attribute defined as a range or list, the first parameter tracks the second parameter as it changes during simulation sweeping.

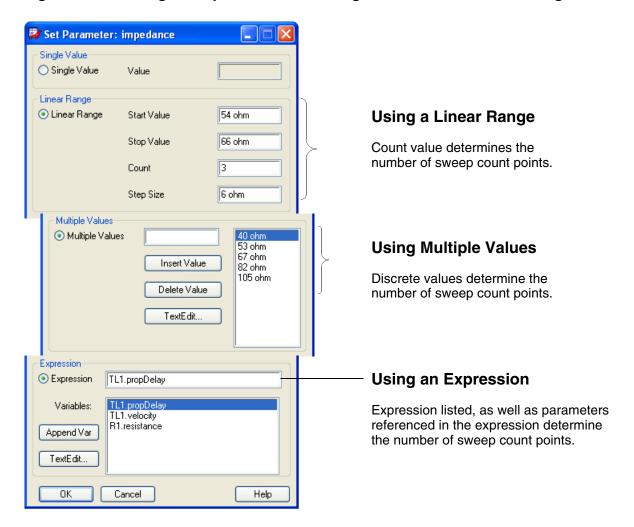
By defining an expression that references another parameter and adds a constant, you can track the first parameter with an offset.

When you delete a part, any references to the part parameter are no longer valid and appear in red within the spreadsheet.

Note: You can save a topology that contains invalid references, but you cannot simulate it.

Preparing for Simulations

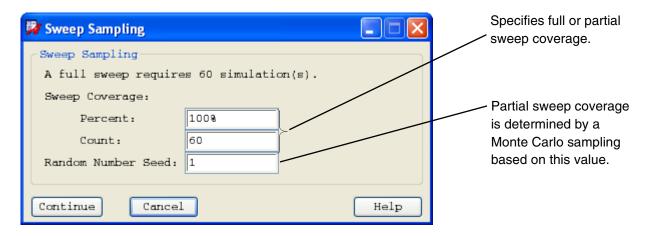
Figure 3-4 Setting Sweep Parameters using the Set Parameters Dialog



Controlling Sweep Sampling and Coverage

After you have set up to perform simulation sweeps, you can choose *Analyze — Simulate* to control sweep sampling in SigXplorer. The Sweep Sampling dialog appears before an active sweep begins.

Figure 3-5 The Sweep Sampling Dialog



You can specify full or partial sweep coverage in this dialog by:

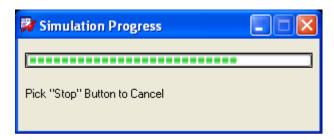
- defining sweep samples as a percentage of full coverage.
- specifying an explicit number of simulations.
- specifying a seed number for random sampling.

You obtain partial sweep coverage by randomly sampling the full solution space using Monte Carlo methods. To vary sample point sets, SigXplorer selects sweep count points based on the specified random number seed.

Preparing for Simulations

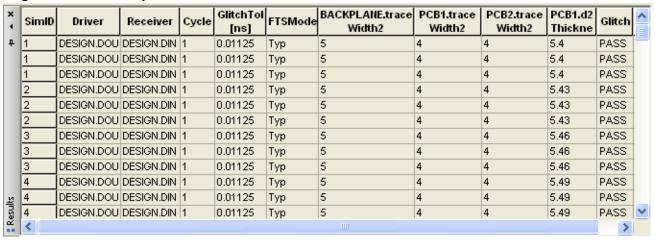
Sweep Results

When you click *Continue* on the Sweep Sampling dialog, the simulation begins and the Simulation progress dialog appears:



When you invoke parametric sweeping, SigXplorer initializes SigNoise which sweeps through the required series of simulations. Sweep results appear in the Results tab of the SigXplorer spreadsheet.

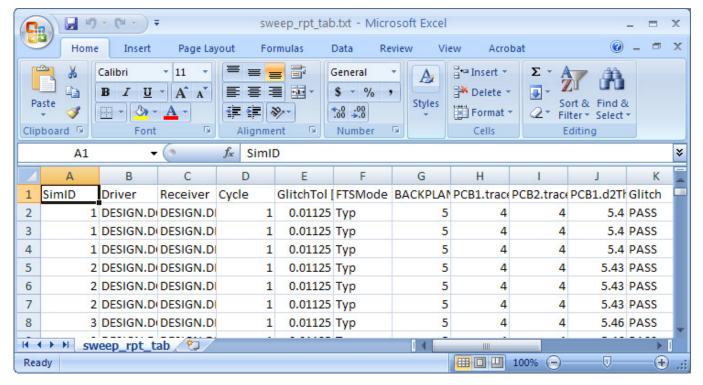
Figure 3-6 Sweep Results



The sweep report contains information on topology, swept elements, driver and load names, impedance, and delay variables. You can save simulation sweep results in a (Spreadsheet Tabbed Text) tab-delimited text file using the File - Export - Spreadsheet - Results menu command. The contents of this file can be imported into an external spreadsheet program such as Microsoft Office Excel as shown in Figure 3-7.

Preparing for Simulations

Figure 3-7 Sweep Results Exported to a Tab-Delimited Text File



Viewing Waveforms

The parametric sweep function does not produce waveforms directly. However, when viewing the sweep results in the Results tab, you can right-click a row in the spreadsheet and choose *View Waveform*. This will re-run that single simulation and open SigWave to display the resulting waveforms.

Preparing for Simulations

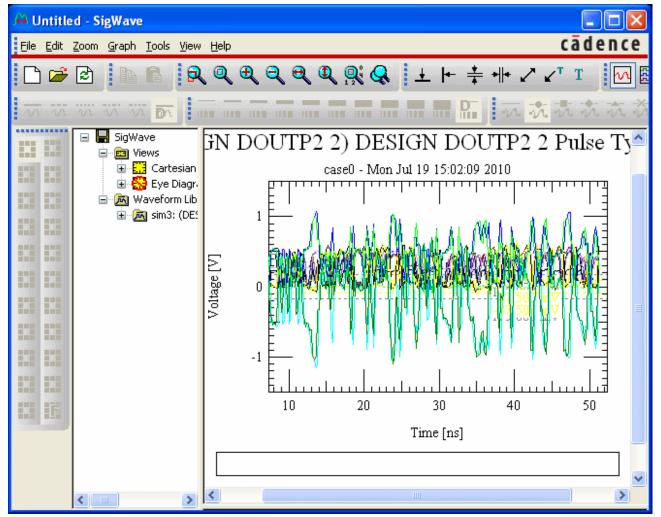


Figure 3-8 Waveform in SigWave

You can save and restore sweep simulation data. This enables you to view waveforms from any prior sweep iteration, eliminating the need to manually reset simulation parameters and perform re-simulations. You save the waveforms (*File – Save As* in SigWave) and the environment details in a case directory. Upon restoring the sweep case, you return to the same state, ensuring the data accuracy of the waveforms.

Caution

Saving waveforms from sweeps can consume large amounts of disk space.

Preparing for Simulations

About Sweep Case Data

Saved sweep cases comprise the following data:

- Waveforms
- Topology file
- SigNoise preferences
- Results spreadsheet

Saving Sweep Cases

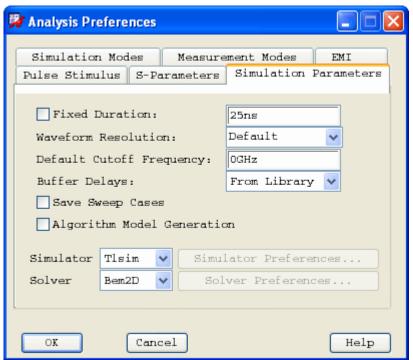
When you start SigXplorer, it uses a default case directory to save (single or sweep) simulation results. The data in the default case is temporary as it is automatically overwritten with the data from the next simulation. Before running a sweep simulation, you can elect to save sweep case data using the Analysis Preferences dialog in <u>Figure 3-9</u>.

To save sweep cases

- **1.** Choose *Analyze Preferences* in SigXplorer.
 - The Analysis Preferences dialog appears.
- 2. Select the Simulation Parameters tab.

Preparing for Simulations

Figure 3-9 Analysis Preferences Dialog



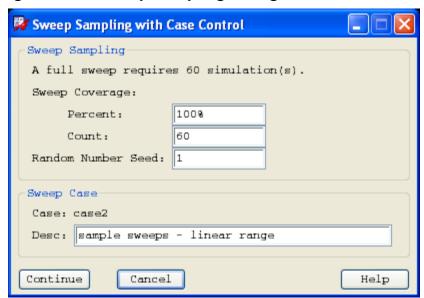
- 3. Click Save Sweep Cases.
- **4.** Select other tabs to set additional preferences for simulation sweeps.
- 5. Click OK.

Preparing for Simulations

Running the Simulation

Running a sweep simulation opens the **Sweep Sampling with Case Control** dialog as shown in <u>Figure 3-10</u>.dialog

Figure 3-10 Sweep Sampling Dialog



Within the Sweep Case area, the assigned case number appears along with a case description field to use to enter text regarding the sweep.

When you click *Continue*, the following events are triggered to preserve the current sweep simulation data and environment details:

- Current topology file and SigNoise preferences are saved in the current case directory.
- Sweep simulation starts, saving the resultant waveforms in the case directory. After the sweep finishes, the data from the Results spreadsheet is also saved in the case directory.

Note: Initiating a sweep simulation with the *Save Sweep Cases* preference enabled, the system assigns the *next unused* case (in this example, case2) as the directory for the saved sweep data.

Restoring and Deleting Sweep Cases

You can restore a saved sweep using the Import Sweep Case dialog shown in Figure 3-11

1. Choose File – Import – Sweep Case.

The Import Sweep Case dialog appears.

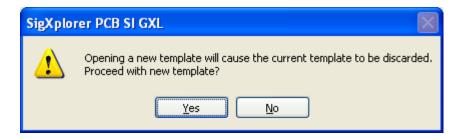
Preparing for Simulations

Figure 3-11 Import Sweep Case Dialog



2. Select the sweep case you want to restore from the list and click *Import Case*.

A message appears prompting you to save the current topology in SigXplorer



3. Click Yes.

The topology file from the selected case is loaded into SigXplorer, the Results spreadsheet data from the selected case is imported, and the SigNoise preferences are also restored from the selected case.

To delete a sweep case:

- **1.** Click the sweep case you wish to delete from the list.
- 2. Click Delete Case.

The case data is deleted and the case entry removed from the list.

Preparing for Simulations

Viewing Sweep Case Waveforms

To view a sweep case waveform:

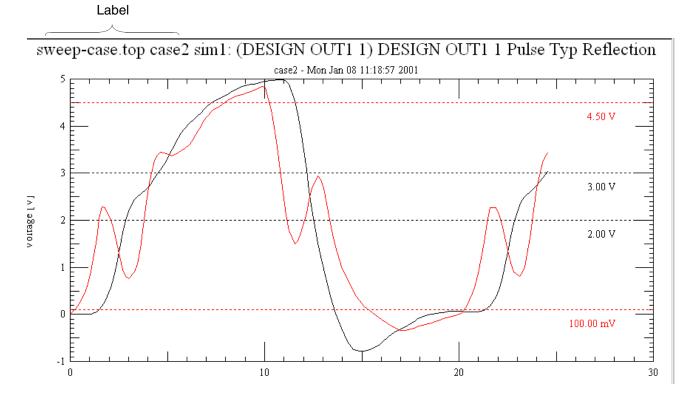
- 1. Right-click on the desired simulation row within the Results spreadsheet.
- 2. Click the View Waveform button.

The SigWave window appears displaying the resultant waveform of the selected simulation.

Waveform Labels

Each waveform has its own label to assist you in mapping the data in the SigXplorer spreadsheet and the SigWave window. The label is based on the topology and case names, as well as the spreadsheet row and simulation ID number of the respective waveform. <u>Figure 3-12</u> shows a waveform label.

Figure 3-12 Waveform Labeling



Preparing for Simulations

Crossprobing

Between two compatible applications, crossprobing enables you to highlight a design object in one application when you select the object in the other. You can crossprobe waveform objects in the SigWave window and simulation rows in the SigXplorer Results spreadsheet to enable guick and reliable identification of waveforms and the related spreadsheet data.

To crossprobe a SigXplorer Results Spreadsheet Row from SigWave

1. View a sweep case waveform from the Results spreadsheet.

If necessary, re-position the *SigWave* window so that the Results spreadsheet in *SigXplorer* and *SigWave* are displayed simultaneously.

- **2.** Click any one of the following waveform objects in the *SigWave* window:
 - Curve in the graphics pane.
 - □ Legend symbol (bottom of the graphics pane).
 - Symbol in the tree pane.

The corresponding Results spreadsheet row for the selected waveform is highlighted.

To crossprobe a SigWave waveform from a SigXplorer Results Spreadsheet Row

1. View a sweep case waveform from the Results spreadsheet.

If necessary, re-position the *SigWave* window so that the Results spreadsheet in *SigXplorer* and SigWave displays simultaneously.

2. Click on a simulation row within the Results spreadsheet of SigXplorer.

The corresponding waveform object in SigWave is highlighted.

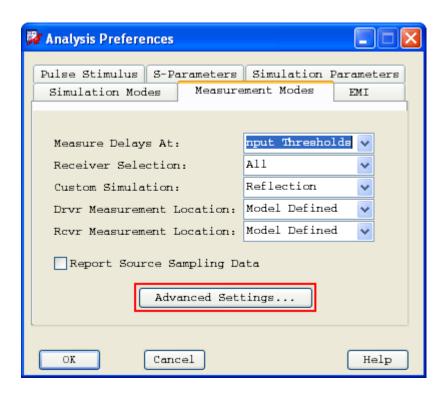
Setting Advanced Measurement Parameters

You can set measurement parameters which assist you in finding correct cycles in your waveform, such as governing glitch tolerance, and measuring eye opening and peak-to-peak jitter. You specify these settings in the Set Advanced Measurement Parameters dialog.

To access the Set Advanced Measurement Parameters dialog:

- **1.** Choose *Analyze Preferences*.
- 2. Select the *Measurement Modes* tab in the Analysis Preferences dialog.

Figure 3-13 Measurement Modes – Advanced Settings Control

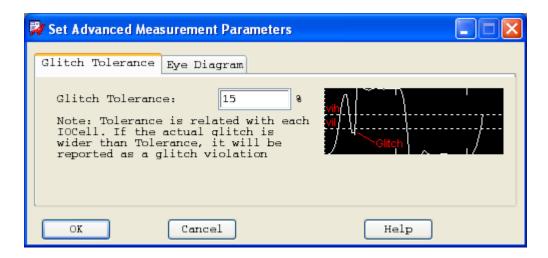


3. Click the Advanced Settings button.

The Set Advanced Measurement Parameters dialog is displayed.

Preparing for Simulations

Figure 3-14 Set Advanced Measurement Parameters Dialog



Measuring and Controlling Glitch

You can control glitch by setting a glitch tolerance percentage that can assist you in finding correct cycles in your waveform. The glitch tolerance setting is a relative percentage of the faster of the rising and falling edges of each IO cell buffer model you need to measure.

When a glitch occurs between the starting and ending points of a cycle, a glitch violation is reported if the value of the glitch exceeds the tolerance percentage specified in the *Glitch Tolerance* field (Figure 3-14). The glitch is *not* reported as a cycle.

When you import your board design as a topology file in SigXplorer, you can specify the glitch measurements you want to measure by selecting them in the *Reflection* category of the *Measurements* spreadsheet tab of SigXplorer:

Preparing for Simulations

Figure 3-15 Measurement Spreadsheet - Glitch Controls

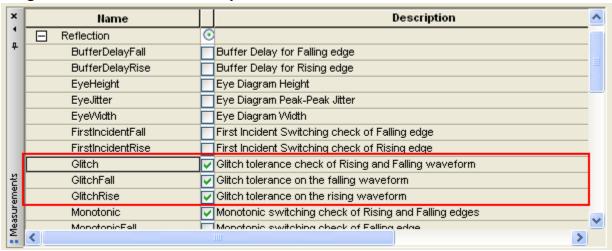


Table 3-2 Glitch Controls Description

Option	Description
Glitch	Is the tolerance check of the rising and falling waveform.
GlitchRise	Is the tolerance check on the rising waveform. If no glitch occurs in the rising waveform, the Results spreadsheet denotes a PASS in the GlitchRise column. If one does occur, it reports a FAIL.
GlitchFall	Is the tolerance check on the falling waveform. If no glitch occurs in the falling waveform, the Results spreadsheet denotes a PASS in the GlitchFall column. If one does occur, it reports a FAIL

Glitch tolerance values are saved in the topology file and in the sigxp.run case management directory. If the tolerance values in these locations differ, the tolerance in the topology file takes precedence.

Eye Diagram Measurements

Eye diagrams are a quick way of intuitively assessing the quality of a digital signal. Eye diagrams provide an accessible and intuitive view of parametric performance.

To measure the eye diagrams of drivers which have a custom stimulus (that is, a stimulus other than pulse, rise, fall, etc.), the horizontal and vertical eye opening, and peak-to-peak jitter within wave forms are included in the eye diagram measurements.

Preparing for Simulations

When you check the EyeHeight, EyeJitter, and EyeWidth items in the Reflection section of the *Measurements* spreadsheet, the measurements are displayed in the *Results* spreadsheet following the simulation.

The Eye Diagram tab in the Set Advanced Measurement Parameters dialog displays the current eye diagram parameter settings for the combinations of the drivers and receivers of the topology.

Figure 3-16 Eye Diagram Tab

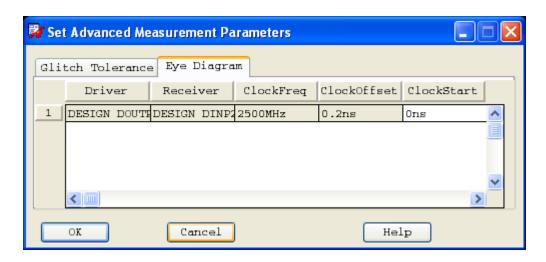


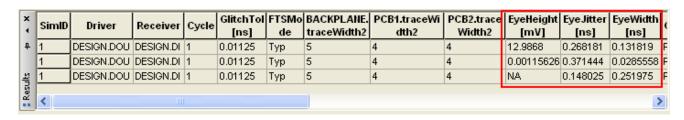
Table 3-3 Eye Diagram Controls Description

Option	Description
Driver/Receiver	Display the driver/receiver combinations in the topology
ClockFreq	Displays the value of the Custom Stimulus state set in the IOCell Stimulus Edit dialog
ClockOffset	Displays the value in nanoseconds of 1/2 the clock frequency value.
ClockStart	Lets you define the point in time when the eye pattern data should start. The default value is <i>Ons</i> . This field is editable.

When you select the *EyeHeight*, *EyeJitter*, and *EyeWidth* options in the *Reflections* section of the *Measurements* spreadsheet, and run the simulation, the Results spreadsheet is populated with the simulation result values.

Preparing for Simulations

Figure 3-17 Eye Diagram Measurements in the Results Spreadsheet

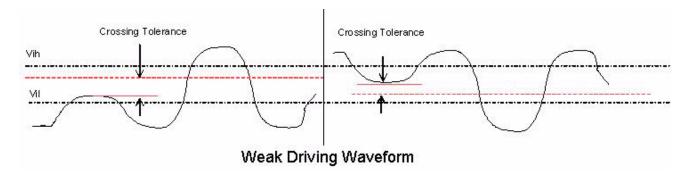


See the procedure for performing eye diagram measurement in the <u>SigXplorer Command Reference</u>.

Weak Driving Control

The weak driving control functionality automatically determines whether a cycle affected by a weak driver is counted or ignored. When the maximum point of the rising edge does not cross Vih (input logic high) but the differential of Vih to the maximum point is smaller than the crossing tolerance, the cycle is counted. When this differential is larger, the cycle is ignored. This is illustrated in Figure 3-18.

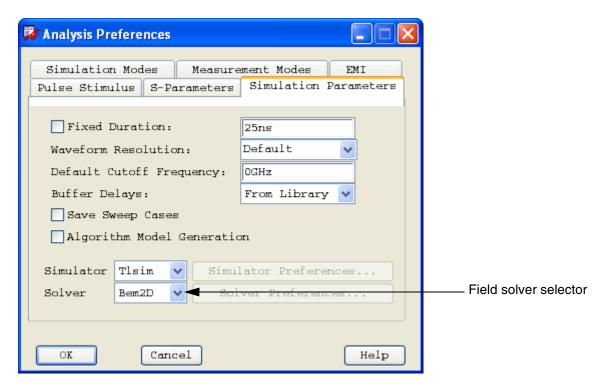
Figure 3-18 Weak Driving Control



Full Wave Field Solvers

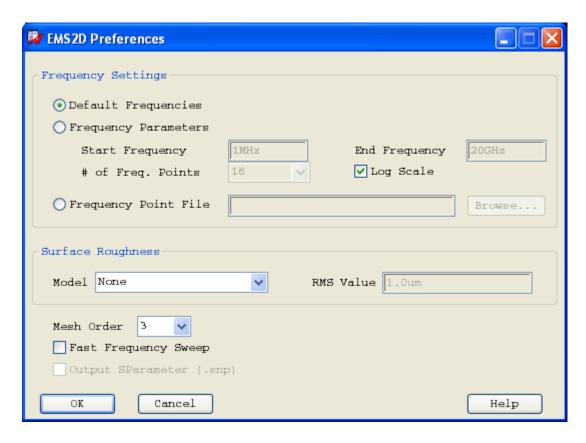
SigXplorer supports two field solvers, *Bem2d* and *Ems2d*. New models that you place in SigXplorer, either from PCB SI or by way of the *Add Element* functionality, attempt to use the solver selected in the *Simulation Parameters* tab of the Analysis Preferences dialog (shown in Figure 3-19). Pre-existing models will attempt to use the field solver type initially used to solve the model.

Figure 3-19 Field Solver Selection Control



Bem2d runs largely automatically, using default parameters. Ems2d allows you to set more preferences, by way of the EMS2D Preferences form. For details on all the controls and options in both these forms, see the online documentation available from the *Help* buttons.

Figure 3-20 EMS2D Preferences Form



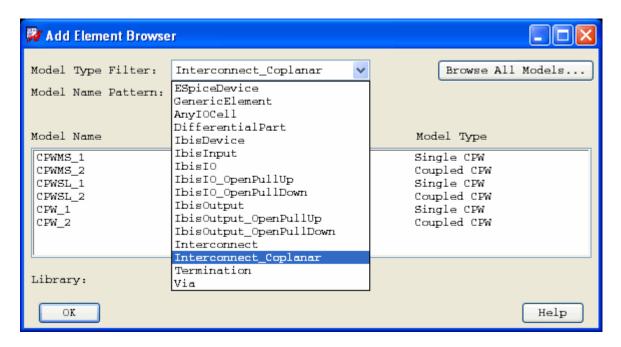
(For complete details on Edms2d and supporting components, see <u>"Dynamic Analysis with the EMS2D Full Wave Field Solver"</u> in the PCB SI User Guide.)

Coplanar Waveguide Support

SigXplorer provides full-time support for coplanar waveguide (CPW) structures in a topology, whether extracted from a board layout or added directly to the canvas from the Add Element Browser (Edit - Add Element), shown in Figure 3-21.

Preparing for Simulations

Figure 3-21 CPW Support in the Model Browser Form



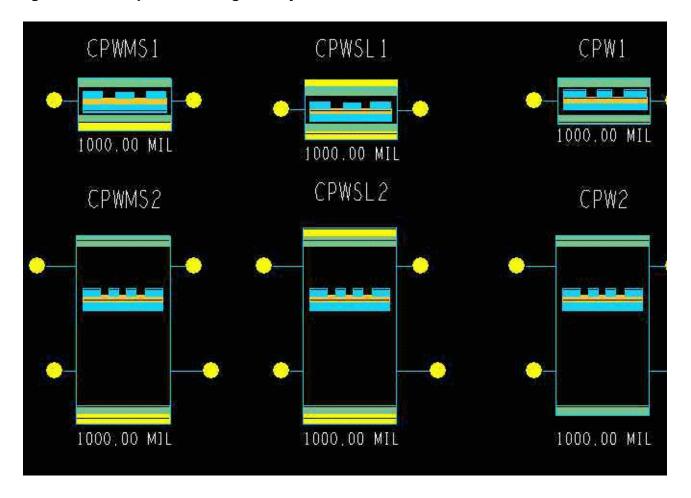
Six CPW structures are supported in SigXplorer:

CPW Structure	Description
Single microstrip	CPWMS1 two-pin symbol containing top and bottom dielectrics
Coupled microstrip	CPWMS2 four-pin symbol containing a bottom dielectric
Single stripline	CPWSL1 two-pin symbol containing top and bottom dielectrics
Coupled stripline	CPWSL2 four-pin symbol containing top and bottom dielectrics
SingleCPW	CPW1 two-pin symbol containing no dielectrics
DiffPair CPW	CPW2 four-pin symbol containing no dielectrics

The symbols for each are illustrated in Figure 3-22.

Preparing for Simulations

Figure 3-22 Coplanar Waveguide Symbols



4

Assigning Constraints in SigXplorer

Topics in this chapter include

- <u>Introduction</u> on page 86
- <u>Defining Constraints</u> on page 87
- <u>Setting Constraints</u> on page 88
- Mapping ECSets to Nets using Mapping Tags on page 89

Assigning Constraints in SigXplorer

Introduction

A constraint is a user-defined limit applied to an element in a design. In SigXplorer, you define topology template constraints. SigXplorer uses these constraint rules to drive both signal integrity and EMI analysis.

You can add user-defined constraints to a topology to store other supplementary constraints within a topology to later import into an electrical constraint set (ECSet) using Constraint Manager. You access these values from the design directly by the user or by other software systems.

As with all other constraints, any bus, differential pair, Xnet or net of the assigned ECSet inherits user-defined constraints. Although there are no pre-defined checks to handle these constraints, you could write a Skill routine that retrieves the constraint for a net and then performs a user-defined check. You could also have the Skill routine create a DRC marker. Alternately, these constraint values write to a file using the *extracta* program and then perform checks on the extracted data.

For more information on constraints, see the *Constraint Manager User Guide*.

Defining Constraints

You can define the following constraints in SigXplorer.

Switch-Settle Define switch and settle delay constraints between any driver -

receiver pin pair. The current rules and a list of pins appear, as

currently defined.

Propagation Delay Defines the delay in time or connection length restriction

between any two pins on a net or between any pin and a T-

point.

Impedance Defines the baseline impedance value and allowable tolerance

value above and below the baseline. An impedance constraint compares to the impedance of each cline segment of an

extended net.

Relative Propagation

Delay

Defines connections that are part of a match group. You can

specify relative propagation delays between nets and within a net, as well. Assigning the PROPAGATION_DELAY property to one of the connections in a match group restricts all other

connections in the group.

Differential Pair Assigns differential pair rules to differential pair objects in a

board design. Since a differential topology can contain two separate Xnets, SigXplorer does not allow a single Xnet constraint definition between pins on different Xnets.

Max Parallel Defines the maximum parallelism constraint between nets.

This dialog tab shows the current coupled length and distance

gap rules of the current template.

Wiring Define topology scheduling parameters as well as physical and

EMI constraint rules.

User - Defined Define supplemental constraints for later use.

Signal Integrity Define crosstalk, noise, and physical constraint rules.

Usage Displays application-specific information on constraint usage

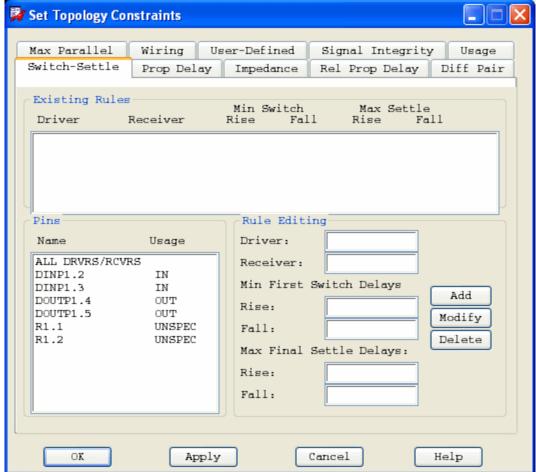
for the current topology analysis.

Setting Constraints

You create and modify topology constraints in SigXplorer using the Set Topology Constraints dialog (See <u>Figure</u> on page 88).

See <u>Allegro SigXplorer Reference</u> for detailed information on how to set constraints in SigXplorer.

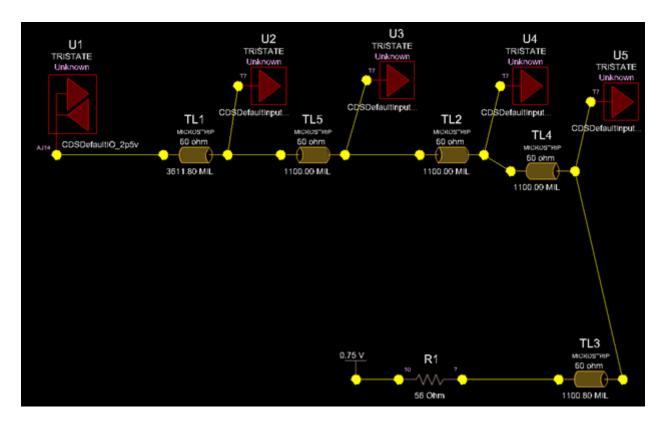
Figure 4-1 Set Topology Constraints Dialog



To write the modified constraint values back to the design database (Constraint Manager), choose *File – Update Constraint Manager* in SigXplorer.

Mapping ECSets to Nets using Mapping Tags

When an ECSet is applied to target nets in Constraint Manager, the pins in the ECSet are mapped to the component pins in the design for those nets. If the pins of two or more components share the same pinuse and signal model, the components are distinguished by their RefDes. This mapping works fine if the corresponding RefDes exists in the target design. However, when the ECSet is reused or applied in a different design, where the same RefDes might not exist, incorrect mapping of ECSets in Constraint Manager occurs.



To address this issue, a pin parameter is used to uniquely identify a pin and thereby remove any ambiguity in the application of ECSets. This unique tag is used to lock the mapping between the ECSet and its associated nets and is not impacted by placement or RefDes changes. Tags can be defined:

■ In a design prior to ECSet extraction or ECSet application. Tags can be set directly in the schematic or the layout by adding the ECSET_MAPPING_TAG property on the component or pins in Design Entry HDL or System Connectivity Manager, or PCB Editor.

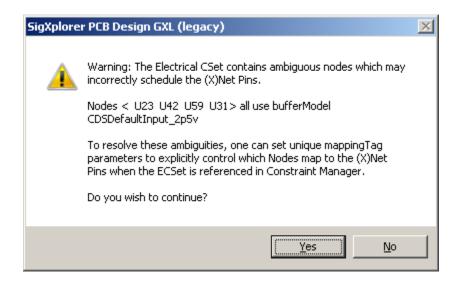
For details, see *Defining Tags on a Component/Pin in the Design* in the <u>Mapping ECSets to Nets using Tags</u> chapter of Constraint Manager User Guide.

Assigning Constraints in SigXplorer

■ In SigXplorer and then applied in the design to pins to which the ECSet is mapped as explained in the following section.

Defining the MappingTag Parameter in SigXplorer

A pin parameter, *mappingTag*, is used to uniquely identify a pin. The topology file supports the mappingTag parameter which can be defined for all non-discrete nodes. When you extract a topology from Constraint Manager and then update it with an ECSet containing ambiguous nodes that are not tagged in SigXplorer, the following warning appears:



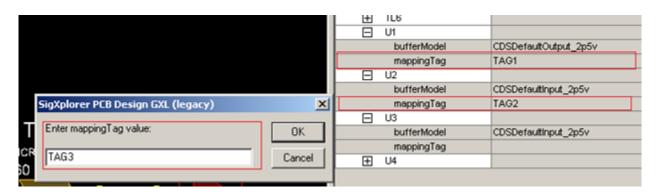
Selecting No aborts the Update Constraint Manager command, and lets you set the mappingTag parameter for the ambiguous nodes. Else, Constraint Manager is updated with the existing (ambiguous) data.

To specify a value for the mappingTag parameter:

1. In the Parameters window, select the arrow icon on the value column of the *mappingTag* parameter for a node.

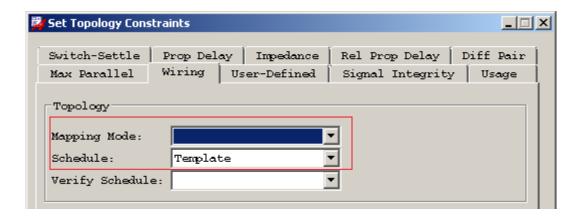
Assigning Constraints in SigXplorer

2. Specify a uniquely identifying value in the resulting input box and click *OK*.



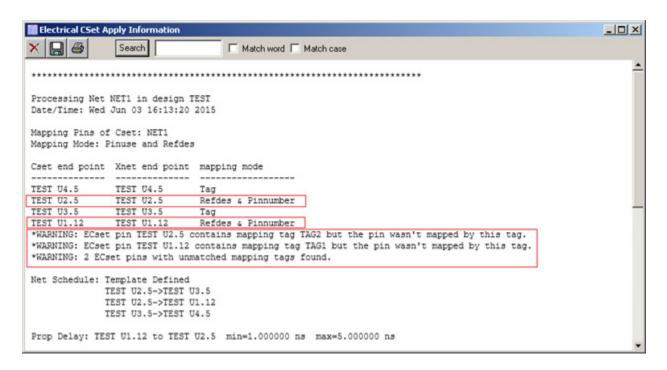
Important

Before you update Constraint Manager with the updated ECSet, you need to ensure that the Mapping Mode field in the Wiring tab of the Set Topology Constraints dialog is cleared of any values and the Schedule is set as Template.



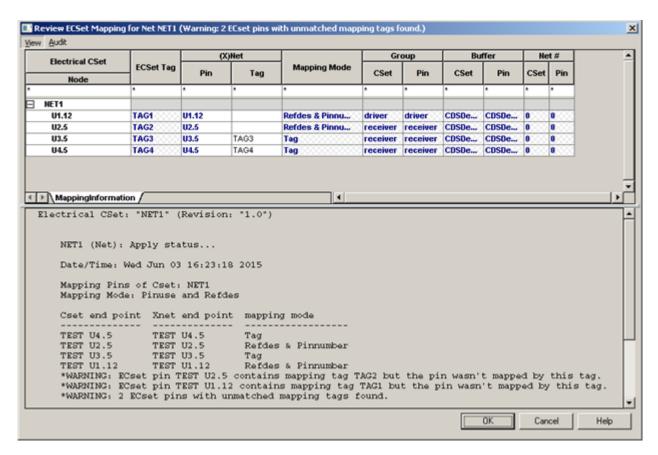
Assigning Constraints in SigXplorer

When the ECSet with the mappingTag values is applied to target nets in Constraint Manager, the ECSet Apply log is displayed with information about the changes.



Assigning Constraints in SigXplorer

You then need to run Audit on the ECSet in Constraint Manager and assign the tags in the ECSet to the appropriate pins in the design in the Review ECSet Mapping dialog.



For more information, see the <u>Mapping ECSets to Nets using Tags</u> in Constraint Manager User Guide.

Allegro SI SigXplorer User Guide Assigning Constraints in SigXplorer

Common Clock Interface

5

Common Clock Interface

Topics in this chapter include

- Introduction on page 96
- Adding a Clocked IOCell MacroModel on page 97
- Editing a Clocked IOCell MacroModel on page 97
- Simulating a Clocked IOCell MacroModel on page 100

Introduction

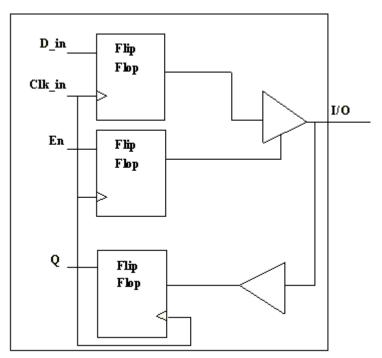
SigXplorer helps you to prototype and design high-speed bus topologies. You can create target bus topologies with multiple drops where each drop, in turn, takes and releases control of the bus based on the stimuli you define for each IOCell on the bus. This allows you to see true dynamic effects over several cycles that include bus turn-around, data-dependent noise effects, and inter-symbol interference.

The following features enable you to support high speed buses:

- Clocked IOCell MacroModels with integrated edge-triggered D-flip flops driving the IO buffers, as shown in <u>Figure 5-1</u>.
- Custom stimulus definition with the IOCell Stimulus Editor, so you can specify excitation of clock, data, and enable input pins of Clocked IOCell MacroModels.
- Custom measurement of setup, hold, and noise margins.
- Simulation waveform viewing in SigWave's timing-diagram mode.

In combination with coupled traces, you can explore the effects of neighbor nets through crosstalk and reflection simulations.

Figure 5-1 Internal View of IOCell Clocked MacroModel

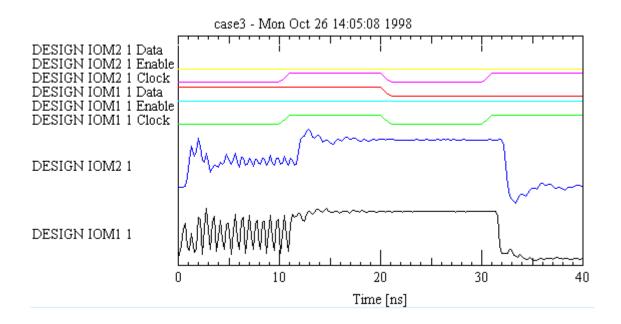


Common Clock Interface

Timing Diagram Display in SigWave

SigWave displays data, and enable and clock signals, in a stacked configuration, for a driver and a receiver in bus mode, as seen in <u>Figure 5-2</u>.

Figure 5-2 Timing Diagram Display in SigWave



Adding a Clocked IOCell MacroModel

To add a clocked IOCell macro model, do the following:

- **1.** Choose *Edit Add Element*.
 - The Add Element Browser is displayed.
- **2.** From the *Model Type Filter* list, choose *IbisIO*.
- **3.** Select the desired IOCell model and drag it to the Topology Canvas for placement. For example, *CDSDefaultIO_CLK* from the Standard Cadence Library.
- 4. Click OK.

Editing a Clocked IOCell MacroModel

For the driver in a differential pair, you can edit the following attributes:

Common Clock Interface

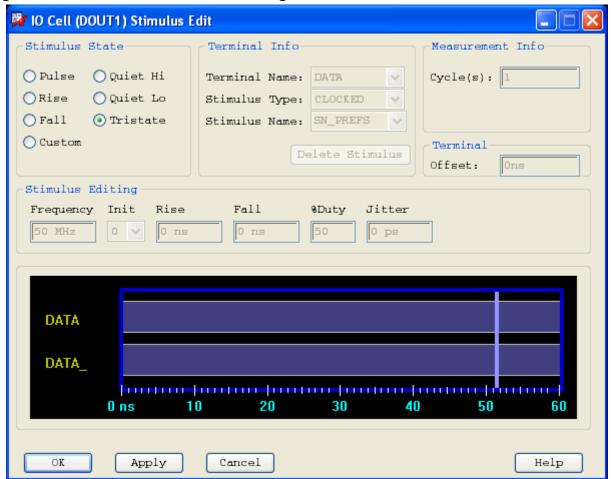
- RefDes (or part name)
- Setup and hold times and sample period
- Stimulus parameters for clock, data, and enable signals

To Modify Stimulus Parameters

1. In the canvas, click the stimulus associated with the IbisIO part symbol. For example, the stimulus might be Pulse or Tristate.

The IOCell Stimulus Editor opens for the IbisIO with the current stimulus data displayed in the data fields.

Figure 5-3 IO Cell Stimulus Edit Dialog



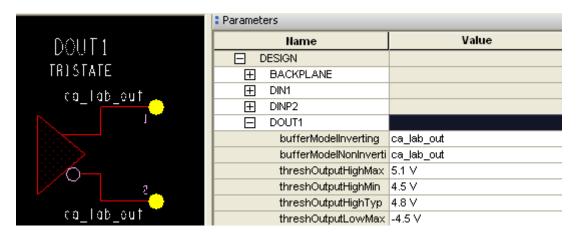
2. In the IOCell Stimulus Editor, make the appropriate edits to the clock, data, and enable signals in the Stimulus Editing section of the dialog.

Common Clock Interface

3. Click Apply or OK.

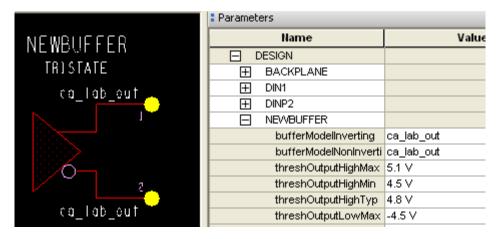
To Modify the RefDes Associated with the IbisIO

1. In the canvas, click the RefDes, or part name, associated with IbisIO symbol.



The *Parameters* tab opens with the data for the selected IbisIO expanded and the RefDes in the Name column highlighted for editing.

2. Enter the new RefDes and click Enter.



The new RefDes replaces the old in both the Name column of the spreadsheet and with the part symbol in the canvas.

Common Clock Interface

To Modify Setup and Hold Times and the Sample Period

- 1. In the canvas, click the stimulus associated with the IbisIO part symbol. For example, the stimulus might be Pulse or Tristate. The IOCell Stimulus Editor opens for the IbisIO with the current stimulus data displayed in the data fields.
- 2. In the Measurement Info area of the IOCell Stimulus Editor, edit the Setup and Hold times and the Measurement Cycle.
- 3. Click Apply or OK.

See <u>Device Modeling</u> on page 161 for more information.

Simulating a Clocked IOCell MacroModel

➤ Choose Analyze – Simulate to start the simulation.

During the simulation, messages display in the Command tab. When the simulation is complete, the Results tab displays the simulation result data. The SigWave window opens to display the differential waveforms.

6

Source Synchronous Interface

Topics in this chapter include

- Introduction on page 102
- Marking Strobe and Data Pins on page 104
- Creating a New Strobe Pin Group on page 105
- Editing Existing Strobe Pin Groups on page 106
- Source Synchronous Topology Files on page 107
- Setup and Hold Timing Measurements on page 107

Source Synchronous Interface

Introduction

When you work with source synchronous bus applications, you need to have more control over measurement data than that supplied by the IOCell Stimulus Editor (Common Clock). Using the Stimulus Editor, you set the cycle of the data signal on which to take measurements. For source synchronous timing applications, you need to be able to take custom measurements on the data signals during a specified cycle of an associated strobe signal.

In order to control measurements in this way you need to be able to:

- Identify a strobe, or reference, signal, and mark a strobe pin on the signal.
- Mark receivers as data pins and group the data pins with the strobe pin.
- Determine the correct time point on the strobe signal to use as the basis for measurement of the data pins.
- Make the indicated custom measurements on the data pins relative to the strobe pins at the appropriate time.

Source synchronous timing measurements are available only for use with custom measurements. All standard measurements still base the measurements cycle on the data signal itself.

Source Synchronous Interface

Understanding Source Synchronous Custom Measurements

When a topology includes at least one strobe pin, it is considered a source synchronous topology and custom measurements are taken for each data pin relative to the strobe pin associated with it. You overlay the waveform for each data pin with the waveform of its associated strobe pin. Timing windows are set for the two waveforms based on the cycles of the strobe pin, and measurements are taken for the data pin.

For example, receiver $\mathtt{U2.1}$ is the data pin and $\mathtt{U2.3}$ is the strobe pin. The measurement cycle is set as cycle 3 in the IOCell Stimulus Editor. Since a strobe pin exists in the topology, the topology is a source synchronous topology and measurements for the data pins are taken relative to the strobe pin.

For strobe pin U2.3 and data pin U2.1, measurements are taken at data receiver U2.1 using the third cycle of strobe pin U2.3 as the baseline.

With measurements taken at a voltage threshold of 2.5V for both active edges of the third cycle of the strobe signal, the markers shown are used, since they mark the rising and falling edges of the strobe pin's third cycle.

For the rising edge, the setup measurement starts with the marker at $23 \,\mathrm{ns}$ (at the strobe pin's rising edge). Look for the data pin's previous transition through $2.5 \,\mathrm{V}$, which happens at about $15 \,\mathrm{ns}$. This produces a setup margin of $23-15=8 \,\mathrm{ns}$

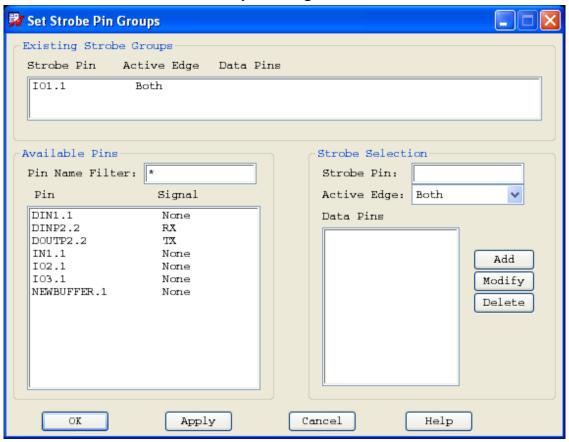
The hold margin measures the difference between the 23ns marker (at the strobe pin's rising edge) and the data pin's next transition through 2.5V, which happens at about 27.5ns. This produces a hold margin of 27.5 - 23 = 4.5ns.

Similarly, falling edge measurements key off the marker at 28ns and produce setup and hold margins of 1 and 12ns, respectively.

Marking Strobe and Data Pins

Choose *Setup – Strobe Pins* to display the Set Strobe Pin Groups dialog where you mark and group strobe and data pins and enable the appropriate source synchronous timing measurements. When the Set Strobe Pin Groups dialog opens, any strobe pin groups that currently exist display in the *Existing Strobe Groups* list box.

Figure 6-1 The Set Strobe Pin Groups Dialog



When you open the dialog, all data editing fields in the *Strobe Selection* area are empty. The *Available Pins* list box displays by pin name all pins in the topology that are not currently marked as strobe or data pins.

See <u>Allegro SI SigXplorer Reference</u> for detailed information on the Set Strobe Pin Groups dialog.

Source Synchronous Interface

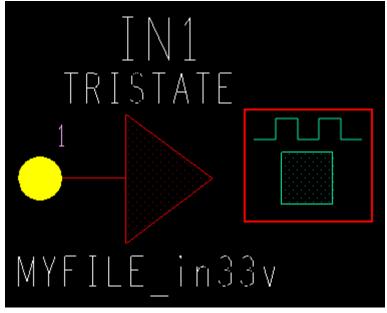
Creating a New Strobe Pin Group

When you create a new strobe pin group, you select pins from the *Available Pins* list box and mark them as, first, the strobe pin, followed by one or more data pins for the strobe pin group. The *Available Pins* list box displays the signal associated with each available pin, or *None*, if there is no signal associated with the pin. A pin's signal is a property of the IBIS Device simulation model associated with the pin.

- 1. Select a pin in the *Available Pins* list. When there are no pins displayed in the *Strobe Selection* area, the first pin selected from the *Available Pins* list box is marked as a strobe pin.
 - As you select pins, they move from the *Available Pins* list box to the *Strobe Pin* field and *Data Pins* list box in the *Strobe Selection* area. The pins are also marked as the strobe pin and as data pins.
- 2. Specify the active edges on the strobe signal when data pin measurements trigger in the *Active Edge* field. You can choose from *Rising*, *Falling*, and *Both*.
 - For most source synchronous designs, data measures on both the rising and falling edges.
- **3.** In the *Available Pins* list box, select the data pins. When a strobe pin displays in the *Strobe Selection* area, each additional pin selected from the *Available Pins* list box is marked as a data pin.
 - Each selected pin moves from the *Available Pins* list box, to the *Data Pins* list box in the *Strobe Selection* area.
- **4.** Click *Add* to create the strobe pin group when you finish editing.
 - The strobe pin group is added to the *Existing Strobe Groups* list box.
- **5.** Choose *OK* or *Apply* to add the strobe pin groups displayed in the *Existing Strobe Groups* list box to the topology.

The topology is marked as a source synchronous topology and the symbols associated with the Strobe and Data pins change in the canvas to indicate that they are strobe or data pins.

Figure 6-2 IOCell Marked as a Strobe Pin



Editing Existing Strobe Pin Groups

You can modify or delete an existing strobe pin group in the Set Strobe Pin Groups dialog. To modify an existing strobe pin group:

- 1. Select a strobe pin group from the *Existing Strobe Groups* list box.
 - The names of the strobe pin and the data pins and the active edges data fill the editing fields in the *Strobe Selection* area.
- 2. Make modifications to the data fields in the *Strobe Selection* area.
- Click Modify to update the strobe pin group.
 The modified pin group is displayed in the Existing Strobe Groups list box.
- **4.** Choose *OK* or *Apply*.

To remove an existing strobe pin group:

- 1. Select a strobe pin group from the *Existing Strobe Groups* list box.
 - The names of the strobe pin and the data pins and the active edges data fill the editing fields in the *Strobe Selection* area.
- **2.** Choose *Delete* to remove the strobe pin group from the *Existing Strobe Groups* list box.

Source Synchronous Interface

The strobe pin group is removed from the *Existing Strobe Groups* list box and appears in the *Available Pins* list box again.

3. Choose OK or Apply.

Source Synchronous Topology Files

A topology is source synchronous when it contains strobe pins. This flags the topology so that during simulation, custom measurements for pins marked as data pins are taken with respect to the strobe pins waveform rather than its own.

<u>Figure 6-2</u> on page 106 shows a canvas symbol for an IOCell marked as a strobe pin. <u>Figure 6-3</u> on page 107 shows a symbol for an IOCell marked as a data pin.

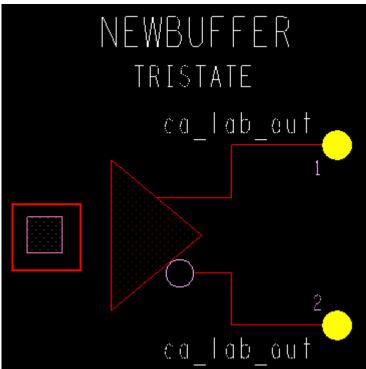


Figure 6-3 IOCell Marked as a Data Pin

Setup and Hold Timing Measurements

For setup and hold timing margin measurements, use the CrossingTime waveform function. This function facilitates taking measurements with reference to a timing threshold by returning the required crossing time before or after the timing threshold.

Allegro SI SigXplorer User Guide Source Synchronous Interface

Serial Link interface

Topics in this chapter include:

- Overview of Channel Analysis -Serial Link Simulation on page 110
- <u>Using the Algorithmic Modeling Interface</u> on page 113
 - Adding an AMI Model using the Context-Sensitive Menu Command on page 118
 - □ <u>Displaying AMI Models</u> on page 119
 - □ Enabling and Disabling AMI Models on page 123
 - □ Setting a Primary Channel on page 124
- Correlating Channel Simulations on page 127
- Running Channel Analysis from SigXplorer on page 130
- Incorporating Crosstalk Effects into Channel Analysis on page 136
- Channel Analysis Directory Structure on page 139

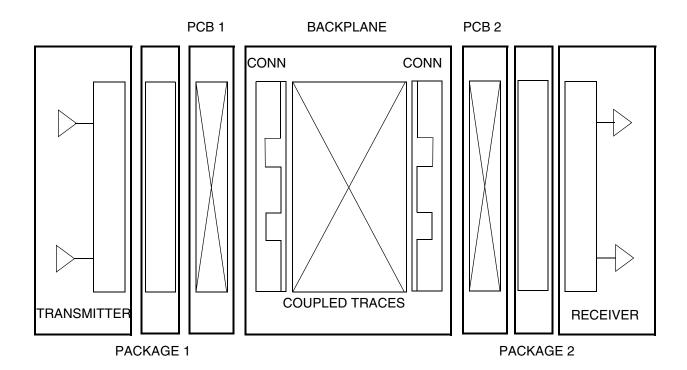
Overview of Channel Analysis -Serial Link Simulation

For serial data running at rates over 1 Gigabit per second (Gbps), the chip-to-chip signal path of the differential pair is often referred to as the *channel*. This channel may be made up of multiple printed circuit boards (PCBs), packages, connectors, and backplanes. The Channel Analysis (CA) functionality in SigXplorer provides the capabilities to aid in the design and analysis of interconnect to support gigahertz data rates.

A channel may be made up of multiple printed circuit boards (PCBs), packages, connectors, and backplanes. Channels can also include coupling from other noise sources. For example, the inclusion of neighboring differential pairs. The end goal is to design a channel whose measured eye pattern seen at the receiver meets its requirements for eye opening and jitter. If these requirements are not met, the data link's integrity may be insufficient to meet the desired bit error rate (BER) criteria for the specific application.

Note: The Channel Analysis feature is available with *Allegro PCB SI GXL (legacy)* and *Allegro PCB Multi-Gigabit Option*.

Figure 7-1 Archetypal Serial Data Channel



Designing this type of high-performance interconnect to support multi-Gigahertz (MGH) data rates presents many challenges. You need to model devices and interconnect in extreme detail to maintain accuracy. Due to the parasitic influence of the channel on the incoming bit

Serial Link interface

stream, you often need to simulate a very large number of bits in order to capture the full effects of inter-symbol interference (ISI) and to accurately simulate the resulting eye pattern. The required number of bits is often far beyond the performance capabilities of traditional circuit simulation. In addition, many MGH drivers utilize pre-emphasis, which can feature multiple programmable taps. Determining the optimum way in which to program the settings for these taps can be a daunting task, and is totally dependent on the channel itself.

With this in mind, Channel Analysis (CA) functionality in SigXplorer provides the following key capabilities to aid in the design and analysis of interconnect to support gigahertz data rates:

High capacity channel simulation

The ability to simulate extremely large bit streams through the channel to predict realistic eye patterns.

Algorithmic Modeling Interface (AMI)

Supports the introduction of complex algorithms from EDA and IC vendors to the modeling process while protecting intellectual property. AMI works in conjunction with statistical analysis.

Statistical analysis

A series of calculations performed to statistically analyze channel interference at various BERs typically for the purpose of estimating total jitter at low bit error rates. You can display the results in bathtub curves or eye contours. This functionality provides an alternative to the simulation option.

Tap optimization

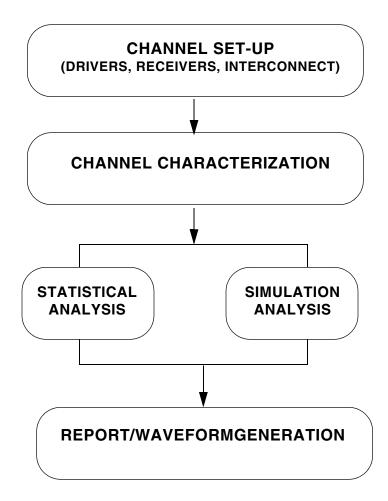
The ability to determine the optimum settings for a given number of taps to drive a specific interconnect channel.

Support for single-ended driver and receiver models.

Figure <u>7-2</u> illustrates the high-level components of the Channel Analysis functionality in SigXplorer.

Serial Link interface

Figure 7-2 Channel Analysis Work Flow



Serial Link interface

Using the Algorithmic Modeling Interface

Simulating a high speed serial link with driver and receiver from different vendors is a challenging task for designers. The challenge lies in the fact that the models supplied by different vendors are seldom compatible. Also, traditional SPICE-based analysis cannot simulate millions of bits required to accurately predict serial link results.

To address these issues, the IBIS ATM standards committee developed a standard to model high speed serial links, the Algorithmic Modeling Interface (AMI). AMI was designed to characterize pre-emphasis, equalization, and clock recovery in a transceiver. In addition to characterization, AMI aims at delivering fast time domain simulation results on a vendor independent platform just like IBIS.

AMI has been incorporated in the CA work flow and it facilitates the integration of vendorspecific modeling algorithms. AMI is also approved as part of the IBIS modeling specification.

This section covers the following topics:

- Translating IBIS Models
- Using MacroModel
- Adding an AMI Model using the Context-Sensitive Menu Command
- Displaying AMI Models
- Enabling and Disabling AMI Models

Translating IBIS Models

Cadence's Signal Integrity solution provides complete support for IBIS AMI models. You can use an IBIS model file for simulation after translating it to a dml file format. SigXplorer provides you with the option to translate IBIS models into DML models. See <u>Translating Models</u> on page 154 for more information on translating models.

To translate an IBIS model into a DML model, do the following:

- **1.** Choose *Analyze Model Browser* to launch SI Model Browser.
- 2. Select the IBIS Models tab.
- 3. Click *Model Editor* to view the AMI section of the IBIS file.

Serial Link interface

Figure 7-3 AMI section of the IBIS file

```
1.32000599E-9
                             1.14281301E-3
99
                -307.76084168E-6
     1.80000825E-9
                            -395.37667180E-6
                                        -245.00905420E-6
.00
01
  [Algorithmic Model]
02 Executable Linux_gcc3.3_32 V5_GTP_AMI_Tx.so V5_GTP_AMI_Tx.ami
  [End Algorithmic Model]
04
06
                   MODEL DQ HALF (Reduced-Strength IO Driver)
```

Notice the Algorithmic Model section represented by [Algorithmic Model], [End Algorithmic Model]. Three entries that follow the executable sub parameter are:

Platform_Compiler_Bits File_Name Parameter_File

Table 7-1 AMI section in the IBIS file

AMI Argument

[Algorithmic Model], [End Algorithmic Model]

Platform_Compiler_Bits

Description

Begins and ends an Algorithmic Model section, respectively

Includes a string without white spaces, consisting of three fields separated by an underscore:

- Name of the operating system followed by its version, compiler and its version, and the number of bits for which the shared object library is compiled.
- The second field consists of the name of the compiler followed optionally by its version.
- The third field is an integer indicating the platform architecture.

Note: If the version of either the operating system or the compiler contains an underscore, it must be converted to a hyphen (-) to ensure that underscore is only present as a separation character in the entry.

Provides the name of the shared library file (vendor executable). The shared object library should be in the same directory as the IBIS (.ibs) file.

File Name

Serial Link interface

AMI Argument Parameter_File Provides the name of the parameter file (.ami). This is an external file, which resides in the same directory as the .ibs file and the shared object library file. The .ami file consists of reserved and model-specific (user-defined) parameters for use by the EDA tool and for passing parameter values to the model. (Figure 7-5 on page 116)

- 4. Close Model Editor.
- **5.** In the SI Model Browser, select the IBIS model file from the *IBIS File Name list*.
- 6. Click Translate.

The IBIS models are translated into DML models.

7. Click one model in the IBIS Models tab and then click the *DMI Models* tab.

The same (translated) model appears selected in the DML tab.

- **8.** Click *Model Editor* to view the translated model.
- **9.** In Model Editor, scroll down to the *ami* section and view the details.

Notice that in the translated file (devices.dml), the name of the DLL, the location, and the parameters for the model are present. These parameters are originally stored in the input file (.ami).

Figure 7-4 An excerpt from the ami section of the devices.dml file

```
(V5 GTP AMI Tx
952
953
         (Description "sample transmitter model" )
954
         (Model Specific
955
          (Process 0 )
956
          (Tx_Equalization 0 )
957
          (Tx_Strength 0 ) )
         (Path "/home/user12/ami/samples")
958
959
         (Reserved_Parameter
960
          (GetWave_Exists True )
961
          (Ignore_Bits 2 )
962
          (Init_Returns_Impulse True )
963
          (Max_Init_Aggressors 25 )
964
          (Use_Init_Output False ) )
965
         (amiPlatformInfo
966
          (Linux
967
           (Bits 32 )
           (Complier "gcc3.3" ) ) ) )
968
```

Serial Link interface

Figure 7-5 An excerpt from the input ami file

- Close Model Editor.
- **11.** Choose *Analyze Preference*.
- **12.** Choose *EMS2D* as it is more accurate and preferred at higher data rate.
- 13. Click Simulate.
- 14. Next, run Channel Analysis and view the waveform in SigWave.

See <u>Running Channel Analysis from SigXplorer</u> for the information required to run Channel analysis. You can edit values of parameters in the devices.dml file to try out different variations.

Using MacroModel

The modeling algorithm files provided to you by a model developer are DLL files. To implement the functionality:

- **1.** Copy the DLLs (there can be more than one) into a directory in the CA search path.
- 2. Edit the DML files you are using to include an AMI section that references the DLLs, as shown and described below.

Serial Link interface

(chcdr))

Note: In the DML excerpt shown above, the keyword ami is used to identify the modeling algorithms in the $signal_optlib_dir$ path defined in the Path - Signoise section of the Allegro User Preferences Editor in Allegro PCB SI.

Two DLLs are referenced, chffefilt and chcdr. For the first DLL, chffefilt, the params keyword describes a set of specific parameters passed to the DLL as a character string in the dllcontrols argument of the ami initialization call.

Note: You can disable the Clock and Data Recovery (CDR) option from an AMI model, if available. Some AMI models have a switch to disable the CDR in the model. There are other models that do not have the switch. SigXplorer can bypass the CDR and automatically figure out the best sample point for the data (to determine if they are high or low). This is particularly useful when the you need to debug the simulation results with the AMI models in the flow.

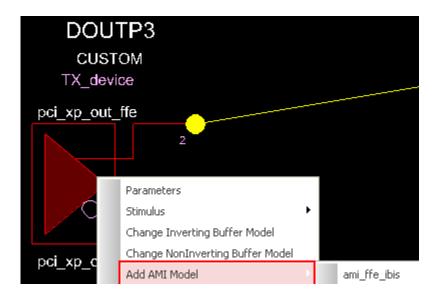
3. Run *Channel Analysis*.

Serial Link interface

Adding an AMI Model using the Context-Sensitive Menu Command

In addition to editing and translating an IBIS/dml file and then using that device in the simulation to add an AMI model to a device, you can use the context-sensitive menu command to add an AMI model to an IO buffer.

The default location of the AMI model is the AMI models that are shipped with the tool is your_installation_directory>\share\pcb\channelanalysis\ami\toolkit).
You can also add a directory path in the env file using the AMI_MODEL_PATH variable.



Serial Link interface

Displaying AMI Models

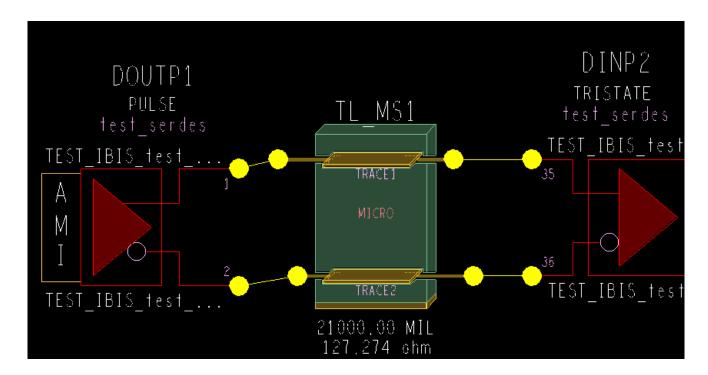
With the rapid generation and consumption of Algorithmic Model Interface (AMI) models, it has become imperative to use and consume the AMI parameters associated with these models in a visually appealing manner.

- Visually Displayed AMI Model
- Visually Displayed AMI Parameters
- AMI Parameters Information in Devices.dml

Note: AMI models and their graphical display are only supported for IBIS Diffpair Devices. If other I/O parts are present on the canvas, *Channel Analysis* is performed without AMI parameters.

Visually Displayed AMI Model

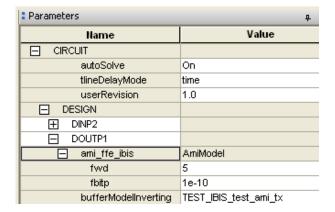
SigXplorer visually displays a (packaged) buffer model which has an AMI model attached to it. The following figure shows how a TX buffer model appears if it has an AMI mode associated with it.



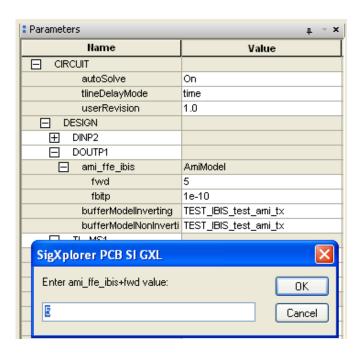
Serial Link interface

Visually Displayed AMI Parameters

When you click the graphical representation of the AMI model on the canvas, the Parameters window is populated with the model-specific parameters associated with that AMI model.



You can also edit any AMI parameter in the Parameters window depending on the permissible values.

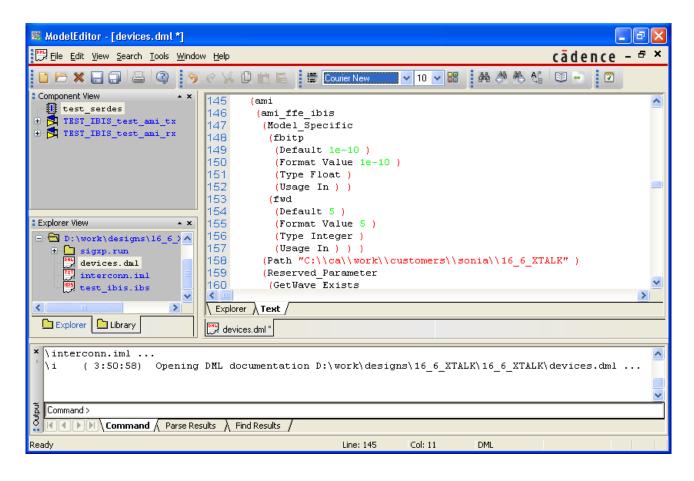


At the time of loading the topology, the default instance of the parameter-value pairs are saved. The values are updated if you make any changes in the Parameters window. If the topology file (.top) file is saved with a modified parameter value, the value is accessed by Channel Analysis at run time.

Serial Link interface

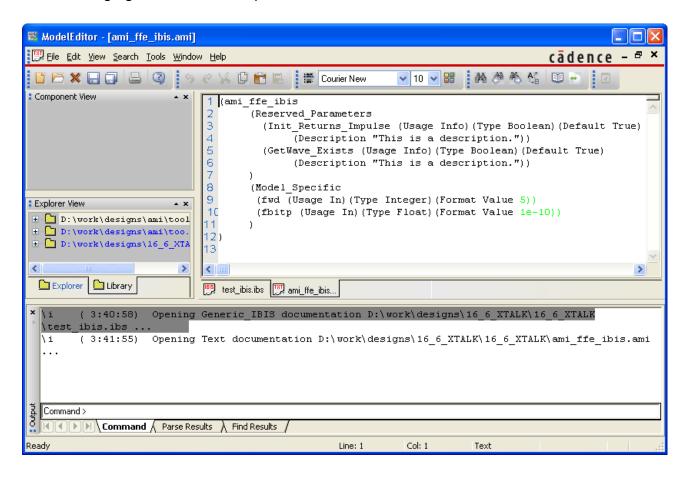
AMI Parameters Information in Devices.dml

For every part on the SigXplorer canvas, the original AMI parameter file is contained within the device.dml file.



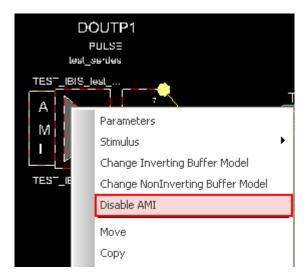
Serial Link interface

The following figure shows a sample AMI file.

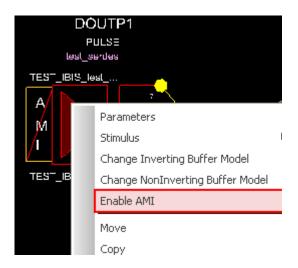


Enabling and Disabling AMI Models

SIgXplorer provide you with a command to disable and enable an AMI model on an IBIS device, Tx or Rx. After disabling the AMI model on a device, you can run simulations without taking the AMI model into account. The *Disable AMI* command, which appears on the popup menu when you right-click a device comes in handy when you want to establish a baseline simulation result with the analog buffers and the channel but without the AMI model.



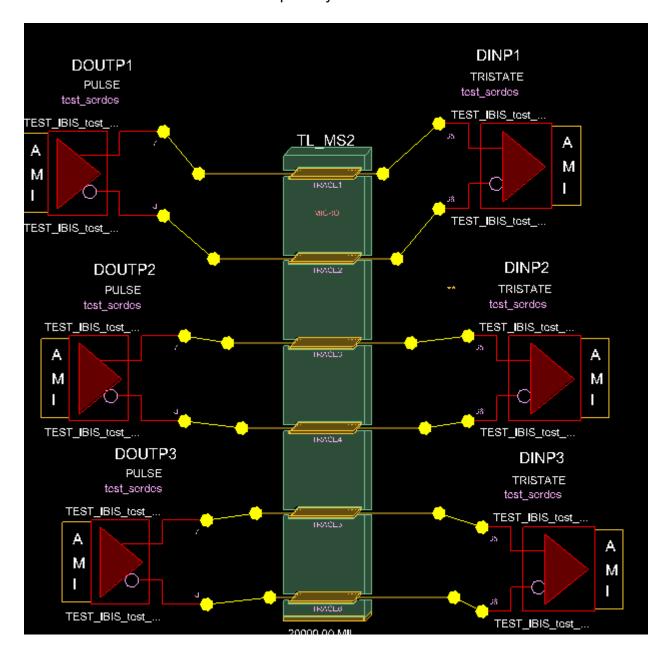
When you disable an AMI model, a slanted line appears across the AMI model icon graphic indicating that it is disabled. You can re-enable AMI model on a device using the *Enable AMI* command, which appears on a device on which AMI was previously disabled.



Serial Link interface

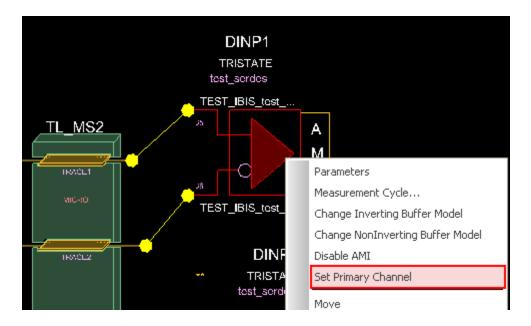
Setting a Primary Channel

In case of multiple driver/receiver pairs, single-ended or differential pair, that are electrically connected to each other through a coupled trace, SigXplorer automatically picks the driver/receiver in the center as the primary channel (net). In case of an even number of driver/receiver pairs any one of the middle pairs can be selected. If there are three differential pairs, the second net is selected to be the primary net.

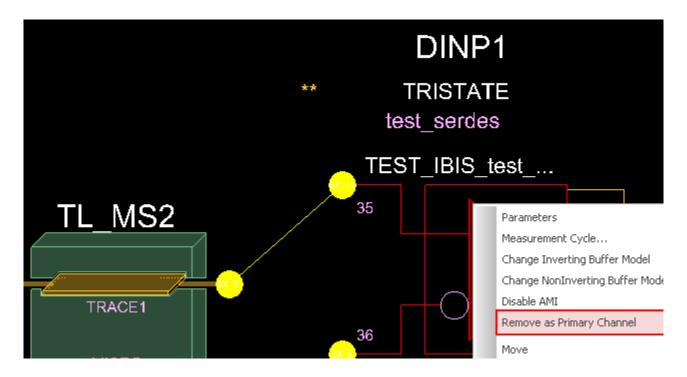


Serial Link interface

You can manually change the primary channel from the pop-up menu which appears when you right-click a receiver. Choose the *Set Primary Channel* command from the pop-up menu. The primary channel is marked with two asterisks next to the receiver.



You can also remove the status of primary channel by assigning the primary channel status to another receiver or by removing it from the receiver which you had previously assigned the default receiver.



Serial Link interface

This functionality applies only to input devices and buffers—single ended and differential pair—that are connected to coupled traces, such as TLine, Microstrip, and Stripline. When you modify the default receiver, the default property is saved as a property on the part instance in the .top file.

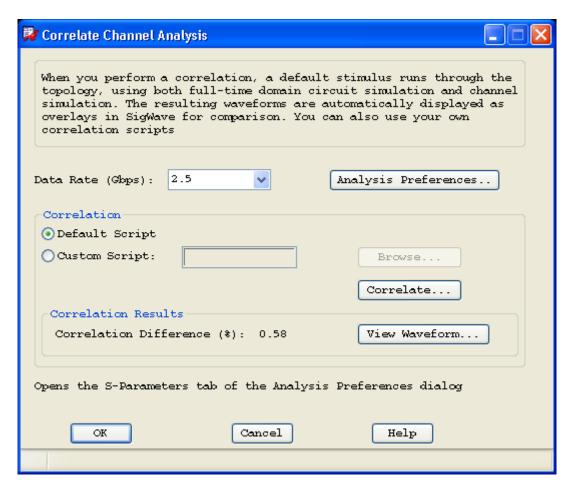
Serial Link interface

Correlating Channel Simulations

You can run correlations using default or custom scripts. A default stimulus is run through the topology using full-time domain circuit simulation and channel simulation. The resulting waveforms are automatically displayed as overlays in SigWave for comparison. You can also use your own correlation scripts.

1. Choose Analyze – Correlate Channel Simulation.

The Correlate Channel Analysis dialog appears.



2. Specify whether you want to use the default script located at:
 <installation_directory>\share\pcb\chsim\chcorr.lsp or use a custom script saved as a .txt file.

Serial Link interface

3. Click the *Correlate* run the correlation.

```
C:\WINDOWS\system32\cmd.exe

... starting correlation ...

characterizing channel DESIGN.DINP1.3i_DESIGN.DINP1.4i_diff -> DESIGN.DOUTP1.1

stim ....

... new characterization will take a few minutes ..

... simulations will be performed using tlsim

... done characterizing..

... generating prbs random bits for correlation ..

... running time domain simulation

... running channel simulation ' chsim chcorr.clm '

... simulations completed .. the waveforms are in ' net.sim ' and ' chan.sim '

... starting wave form comparison computations ...

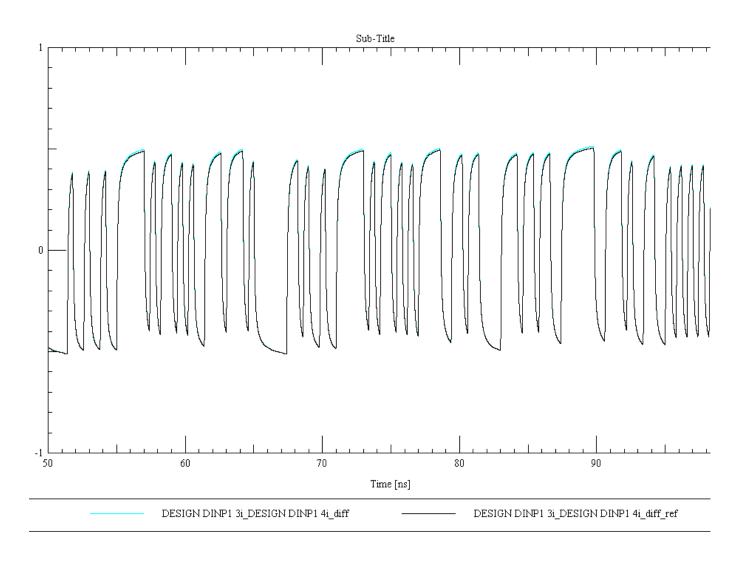
... The error between channel simulation wave forms and time domain simulation waveform is

... ' 0.584011527235.' ...based on 25000 wave points

... Outputting correlated sim file ' corr.sim ' ....
```

When the correlation task completes, the Correlation difference percentage is displayed in the GUI and the waveform opens in SigWave. The correlation difference percentage is updated in the *Correlation Channel Analysis* dialog.

Serial Link interface



Refer to the *Correlate Channel Simulations* section of the *Allegro SI SigXplorer Reference* guide for more information.

Serial Link interface

Running Channel Analysis from SigXplorer

You access the Channel Analysis GUI by choosing *Analyze – Channel Analysis* in SigXplorer. You can also run Channel Analysis in the batch mode from the command prompt. This section describes the controls you set when you run CA in GUI mode.

Channel Analysis Characterization and Simulation

The Channel Analysis GUI consists of five tabs and a common section:

- Characterization Tab
- Stimulus Tab
- Preferences Tab
- Output Tab
- Advanced Features Tab

Common Area

The common area in the Channel Analysis GUI consists of the following controls and fields:

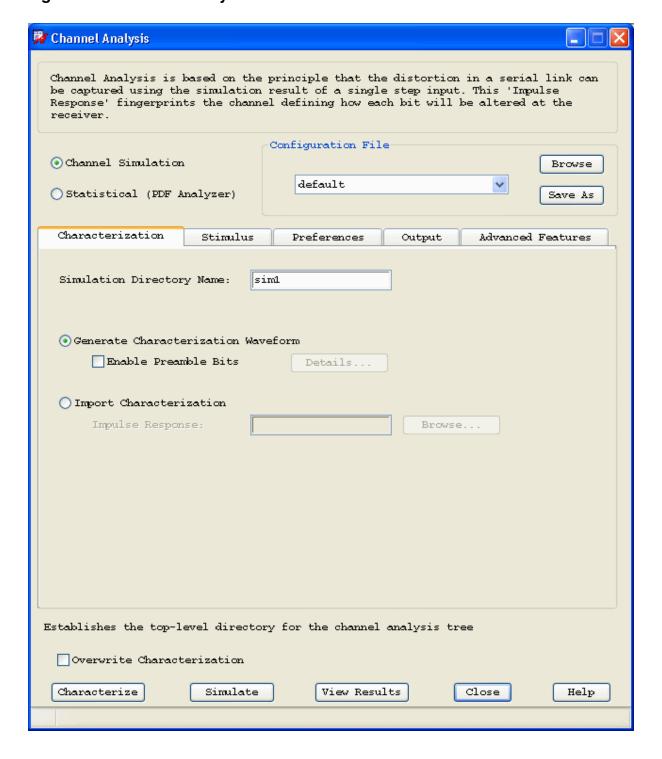
- Channel Simulation
- Statistical (PDF Analyzer)
- Configuration File
- Characterize
- Simulate
- View Results

Refer to Allegro SI SigXplorer Reference Guide for details on the controls.

Serial Link interface

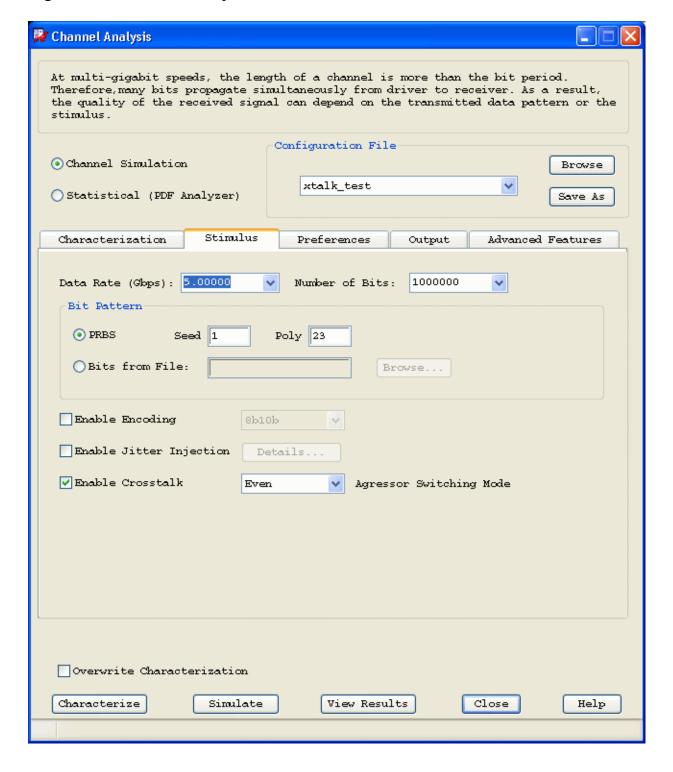
Characterization Tab

Figure 7-6 Channel Analysis GUI: Characterization Tab



Stimulus Tab

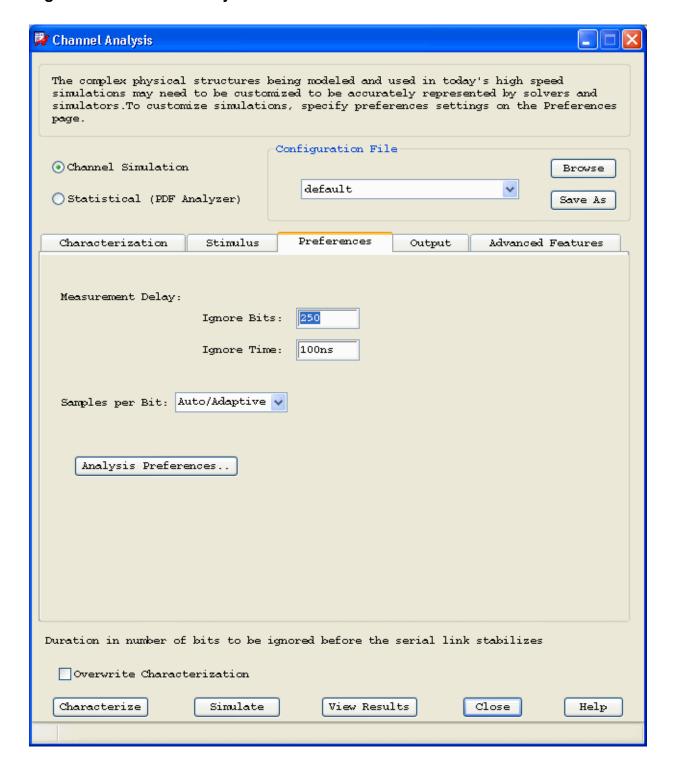
Figure 7-7 Channel Analysis GUI: Stimulus Tab



Serial Link interface

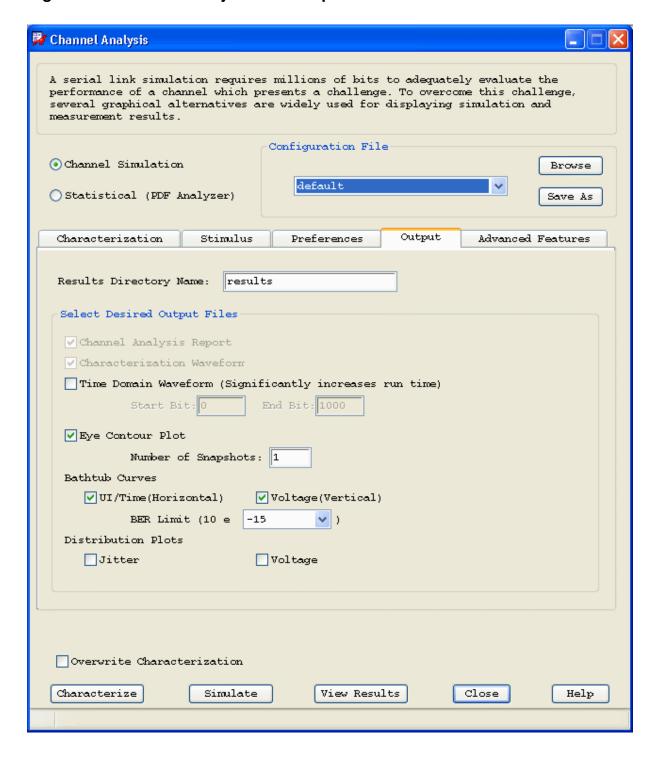
Preferences Tab

Figure 7-8 Channel Analysis GUI: Preferences Tab



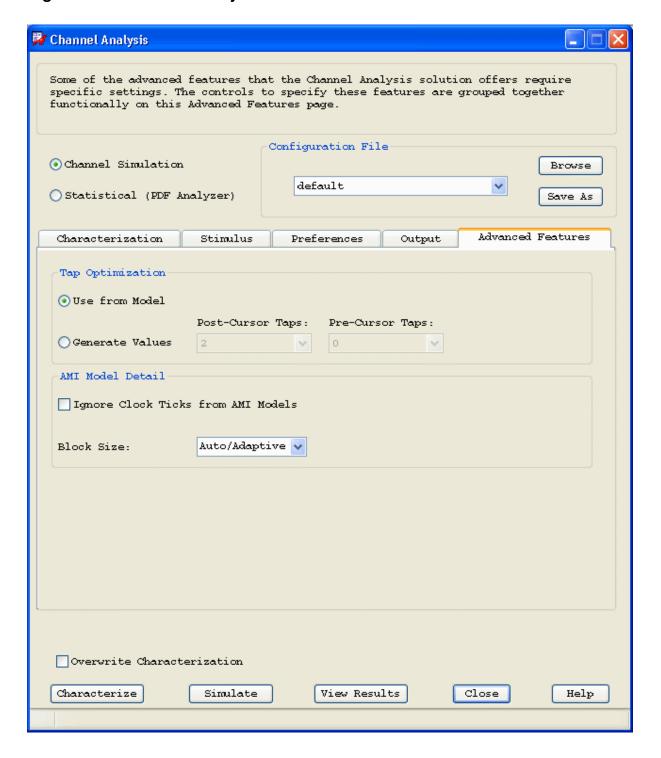
Output Tab

Figure 7-9 Channel Analysis GUI: Output Tab



Advanced Features Tab

Figure 7-10 Channel Analysis GUI: Advanced Features Tab



Incorporating Crosstalk Effects into Channel Analysis

When multiple drivers and receivers are included in the topology, you can include crosstalk effects into Channel Analysis. An example of this kind of topology is shown in Figure 7-11. With this type of multi-receiver topology, it is important that you identify the primary receiver.

In case of multiple driver/receiver pairs, single-ended or differential pair, that are electrically connected to each other through a coupled trace, SigXplorer automatically picks the driver/receiver in the center as the primary channel (net). In case of an even number of driver/receiver pairs any one of the middle pairs can be selected. If there are three differential pairs, the second net is selected as the primary channel.

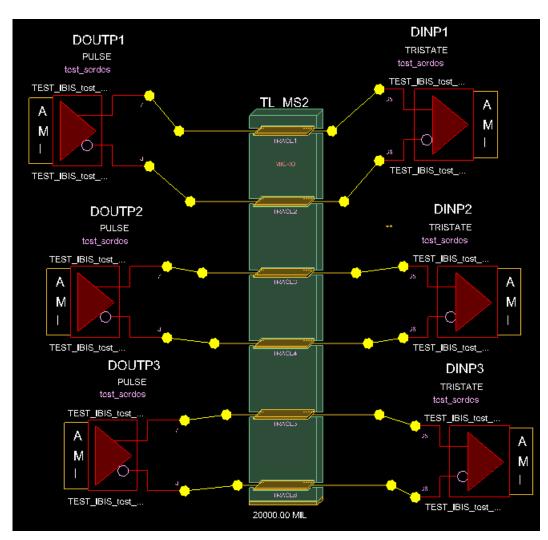


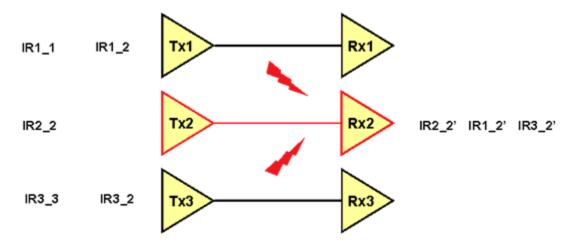
Figure 7-11 Topology with Crosstalk

Serial Link interface

Performing accurate and reliable cross talk simulation for a topology/layout with multiple driver/receiver pairs that are electrically coupled to each other is an important requirement in a high speed environment. The presence of AMI models on each of the drivers and receivers mean that the effect of equalization (or any other algorithmic effect) must be accurately captured in the simulations on a particular victim receiver from adjacent aggressors.

Channel simulation with multiple electrically coupled Tx/Rx pairs is possible with reasonable accuracy. Each channel, aggressors and victim, is characterized individually. Simulations are performed to obtain the waveform results for the victim Rx. To perform the simulation for the victim Rx, the impulse matrix for the channel constitutes the impulse response of the primary victim as well as the crosstalk impulse responses from the aggressors. The crosstalk impulse responses of the aggressors are subjected to the Init functions (in the .ami file) of the aggressors and they can be modified by the Init functions of the aggressors.

AMI parameters decide how a TX/RX AMI model behaves in a simulation. A crosstalk simulation is also affected by a change in the TX AMI parameters for the aggressors and TX/RX AMI parameters of the victim. The crosstalk for AMI models/simulation is illustrated in the following example with three Tx/Rx pairs:



In this example, the middle channel (Tx2/Rx2) is the *victim* channel, while the other two channels (1 and 3) are *aggressor* channels.

Note that five impulse responses are generated here. $IR1_1$, $IR2_2$, and $IR3_3$ represent the primary channel impulse responses for the three channels, while $IR1_2$ and $IR3_2$ represent the impulse responses of the crosstalk channel from Tx1 to Rx2 and Tx3 to Rx2, respectively. The impulse matrix presented to the Init function of Tx1 contains $IR1_1$ and $IR1_2$ in the first and second columns, respectively. Similarly, the impulse matrix for the Init function of Tx3 contain $IR3_3$ and $IR3_2$. Depending on the AMI model, the init functions of the Txs may or may not modify the IRs presented to them. Assuming that they do, the crosstalk IRs will change to $IR1_2$ and $IR3_2$. These two IRs are used to construct the final IR for the victim Rx which will have $IR2_2$, $IR1_2$, and $IR3_2$ in the first, second, and third

Serial Link interface

columns, respectively, of the impulse matrix. Any AMI simulation with this *IR* will incorporate the crosstalk effects of the AMI models as well as the traditional crosstalk.

You can control the way in which stimulus is handled for the neighboring drivers through the *Enable Crosstalk: Aggressor switch mode* setting in the Stimulus tab of the Channel Analysis GUI.

Serial Link interface

Channel Analysis Directory Structure

When you run CA, a channel.run directory is automatically created in your sigxp.run\case0 hierarchy. Output files are derived from your current characterization and are stored accordingly. The outputs of channel simulation are located in:

<working_dir>\sigxp.run\case0\channel.run\<char_name>\char
<working dir>\sigxp.run\case0\channel.run\<char name>\results

Table 7-2 CA Directory Structure

Directory Name	Description
working_dir	Location of topology files
sigxp.run	SigXplorer run directory
case0	1 st (and only) case in sigxp.run
channel.run	Directory for Channel Analysis
<char_name></char_name>	Specific characterization name
char	Location of characterization
results	Location of Channel Analysis output

Additional characterizations result in additional directories that are created parallel to the <char_name> directory.

Allegro SI SigXplorer User Guide Serial Link interface

8

Working with Signal Models and Libraries

About Signal Models

Procuring, developing, and verifying simulation models up front in the high-speed flows is crucial to the success of a design. Today's models come in many different styles and formats. Allegro SI DML (Device Modeling Language) enables you to accurately describe all devices and advanced behaviors.

A DML model refers to a single specific entity. That entity can be a package model, an interconnect model, an Espice model, or a translated IBIS model. It should be noted that an IBIS model can contain a package model within one translated file.

A DML file contains one or more models written in the DML language and is identified by its.dml extension. These model files are used in circuit simulation by analysis tools such as PCB SI and SigXplorer. Models are procured or developed in advance of simulation and used to characterize manufactured components such as ICs, discrete components, and connectors. The Allegro SI simulator requires that simulation models be in DML format for successful simulation. For further details on DML, refer to the <u>Allegro SI Device Modeling Language User Guide</u>.

Introduction to Simulation Models

There are two basic categories of models used to build circuits for simulation.

- Device Models
- Interconnect Models

Device Models

Device models are stored in files with a .dml extension. A device model library consists of a .dml file that contains one or more device models.

The available device models, their contents, and how they are used are described in <u>Table 8-1</u> on page 142.

Figure 8-1 Device Models

DesignLink Cable ESpiceDevice IbisDevice PackageModel AnyI0Cell IbisInput IbisTerminator IbisOutput IbisOutput_OpenPullUp IbisOutput_OpenPullDown IbisI0 IbisIO_OpenPullUp IbisIO_OpenPullDown AnalogOutput BoardModel Connector

Table 8-1 Device Models Supported by Signal Integrity Tools

Model Type	Use and Relationship
Design Link	Used to specify system-level connectivity, like multi-board or advanced package-on-board scenarios.
Cable	Referenced from a system configuration. Models cables interconnecting multiple boards. Can be an RLGC model or SPICE sub-circuits.

Working with Signal Models and Libraries

Model Type	Use and Relationship
ESpiceDevice	Assigned to discrete parts like resistors and capacitors. Contains SPICE sub-circuits.
IbisDevice	Assigned to ICs and connectors. An IbisDevice model for a connector has package parasitics but no IOCell models.
PackageModel	Referenced from an IbisDevice model. Models the package parasitics of the entire component package. Can be an RLGC matrix model or SPICE sub-circuits.
AnyIOCell	Referenced from an IBISDevice model. An IOCell model is used to model driver and receiver buffers at the pin level.
lbisInput	A type of IOCell model. It is a receiver model.
IbisTerminator	Models termination internal to the device pin
IbisOutput	A type of IOCell model. It is a driver model.
IbisOutput_Open PullUp	Driver model with no pullup resistor
lbisOutput_Open PullDown	Driver model with no pulldown resistor
IbisIO	Bidirectional buffer model, which can drive or receive
lbisIO_OpenPull Up	Bidirectional buffer model with no pullup resistor
lbisIO_OpenPull Down	Bidirectional buffer model with no pulldown resistor
AnalogOutput	Models the behavior of an analog device pin
BoardModel	Referenced from a system configuration. Models entire boards for situations in which the physical Allegro database is not available. Contains SPICE sub circuits.
Connector	Used to create interconnect models (iml).

Interconnect Models

Interconnect models are extracted directly from the physical design database and synthesized on demand. Interconnect models are stored in files (.iml) so that they can be reused. The .iml files cover such items as traces and vias.

Working with Signal Models and Libraries

The available interconnect models, their contents, and how they are used are described in and <u>Table 8-2</u> on page 144.

Figure 8-2 Interconnect Models

Trace Coupled Traces Any CPW Single CPW Diff Pair CPW Any Via Any Single Via Any Coupled Via Closed Form Via Narrow Band Via Wide Band Via S-Parameter Single Via Signal/Signal Coupled Vias Signal/Ground Coupled Vias Signal/Power Coupled Vias Stacked Coupled Vias Shape Pin

Table 8-2 Interconnect Models

Model Type	Use and Relationship
Trace	Geometry-based model that represents a single transmission line with no coupling. A Trace can have frequency-dependent loss.
Coupled Traces	Geometry-based model representing coupled lossey transmission lines.
Any CPW	Any model representing a coplanar waveguide (CPW) structure.
Single CPW	Represents a single CPW. It is a two-pin symbol containing no dielectrics.
Diff Pair CPW	Represents a differential pair CPW. It is a four-pin symbol containing no dielectrics.
Any Via	Models the parasitics of a via providing z-axis connectivity between traces.
Any Single Via	
Any Coupled Via	

Allegro SI SigXplorer User Guide Working with Signal Models and Libraries

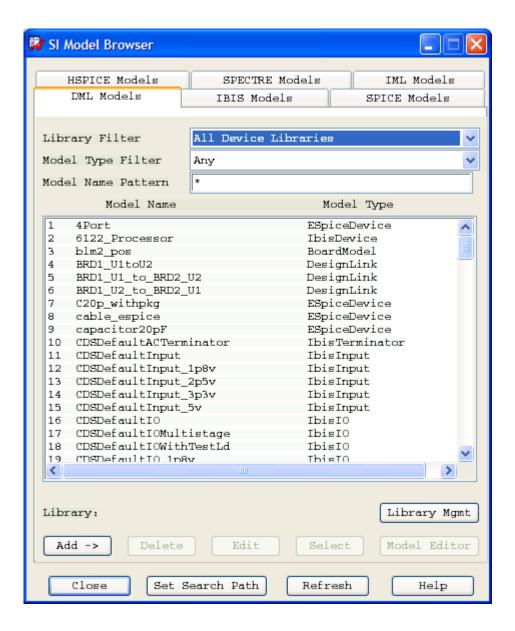
Model Type	Use and Relationship	
Closed Form Via	■ Fast Closed Form	
	This is the most basic form of a via model. It is a static method, formula-generated model.	
	■ Detailed Closed Form	
	A more accurate, static method, formula-generated model created by FSvia.	
Narrow/Wide Band Via	An FSvia-generated narrow band (single frequency-point) or wide band (multiple frequency-points) model containing RLGC values for a range of frequencies, as specified by the user. When generating a Wideband model, FSvia first generates S-Parameters and then creates RLGC values based on those S-Parameters.	
S-Parameter Single Via	An FSvia-generated S-Parameter model containing values for a range of frequencies, as specified by the user	
Signal/Signal Coupled Via	Represents a via model between two signals.	
Signal/Ground Coupled Via	Represents a via model between a signal and a ground component.	
Signal/Power Coupled Via	Represents a via model between a signal and a power component.	
Stacked Coupled Via		
Shape	Models a copper shape encountered in a physical design.	
Pin		

September 2023 145 Product Version 23.1

Managing Device and Interconnect Models

You use the *SI Model Browser* to create and manage your libraries of device and interconnect models, and launch <u>Model Editor</u>. You can also use SI Model Browser to specify which device and interconnect libraries you want the tool to access, as well as the order of library access.

Figure 8-3 SI Model Browser



Working with Signal Models and Libraries

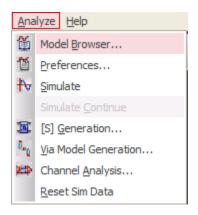
To display SI Model Browser:

† Choose Analyze – Model Browser in SigXplorer.

-or-

† Choose Analyze – Model Browser in PCB SI.

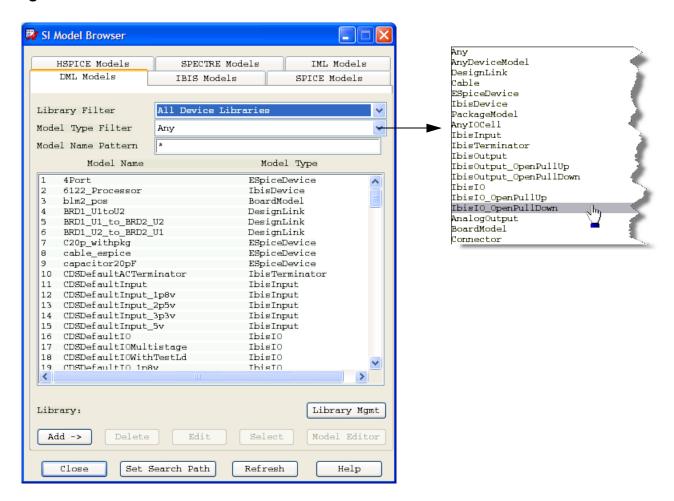
Figure 8-4 Accessing Signal Model Libraries



Consuming Signal Models

As an SI engineer, you deal with many different types of signal models. SigXplorer works with signal models in the DML model format, but can handle the translation in the background. This way you can manage and debug the original signal models in their native formats. You begin the process by accessing the appropriate device file library from the SI Model Browser.

Figure 8-5 SI Model Browser



The SI Model Browser's tabbed interface accommodates the model type that you want to translate, be it IBIS, Spectre, Spice, IML, or HSPICE. From these tabs, you can also edit a model directly in its native format or translate it. Once translated, these models also appear under the DML tab.

Each tab contains a field for filtering the listed models, as well as a button to set the model's library search path and to set its associated file extensions (see Figure 8-6 on page 150).

Working with Signal Models and Libraries

Specifying Library Search Order

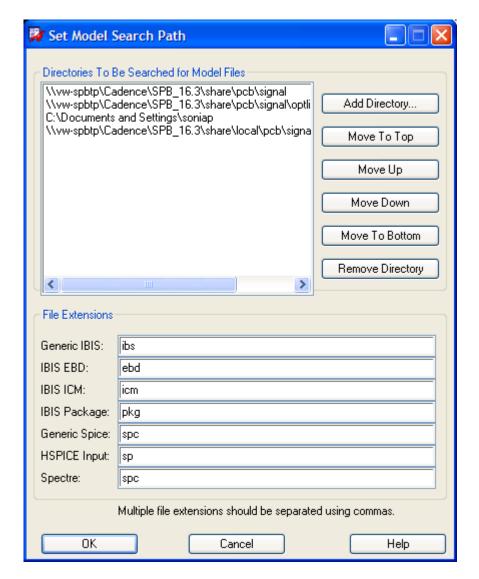
You can specify the directories in which to search for signal models, and their search order in the Set Model Search Path dialog.

To access Set Model Search Path dialog:

→ Click the Set Search Path button in SI Model Browser.

This dialog is used to manage the search path and file extensions for all model formats. You can extend the default file extensions provided by adding others, separating each with a comma.

Figure 8-6 Set Model Search Path dialog



The default search locations include the current project directory and Cadence defaults. You can add a new search directory by clicking the *Add Directory* button. You can also reorder the directories to search for models and remove a directory from the search list.



SigXplorer automatically saves these edits to your local $.\,\mathrm{env}$ file as arguments to the following environment variables:

SI_MODEL_FILE_EXT Signal model file extensions.

Working with Signal Models and Libraries

SI_MODEL_PATH	Search directories for IBIS, Spice, HSPICE, and Spectre signal models.
SI_IGNORE_DML_LIBS	DML libraries to be ignored while performing search.
SI_IGNORE_IML_LIBS	IML libraries to be ignored while performing search.

For example the corresponding entry in the env file for SI_MODEL_PATH is:

set SI_MODEL_PATH = . C:/Workshops/16.6/cm/site/pcb/signal D:/SPB/cds/16.6/share/
pcb/signal D:/SPB/cds/16.6/share/pcb/signal/optlib

These settings support the use of variables in the paths making them more portable. For example:

```
set SI MODEL PATH = . $MY LIB PATH $GLOBAL LIB PATH
```

The variables for MY_LIB_PATH and GLOBAL_LIB_PATH are only expanded when the files are opened and are not stored anywhere in their expanded format. When you edit the search path in the Set Search Path dialog, these variables are expanded.

These path variables are updated based on existing case.cfg files in run directories when you open a pre-16.3 design.

September 2023 151 Product Version 23.1

Setting Working Libraries

The SI_DML_WORKING_LIB and SI_IML_WORKING_LIB Allegro environment variables are used to store the names of the current dml and iml working libraries.

SI_DML_WORKING_LIB	Sets a DML library as the working library. Auto-generated models are stored in the working library.
SI_IML_WORKING_LIB	Sets an IML library as the working library. Auto-generated models are stored in the working library.

You can set the value of these variables to special keywords that will create specific file names. The values these two variables can take are described in the following table:

SI_DML_WORKING_LIB

- user: The dml working library will be named <username>_devices.dml
- host: The dml working library will be named <hostname>_devices.dml
- unique: This option lets a single user have different file names if two different processes are being run in the same directory. Each file name is unique as it will include the process ID.

With the unique option, the dml working library will be named <host_name>_<user_name>_proces
s_id>_devices.dml.

<any other string>: This string defines the name of the dml working library.

Working with Signal Models and Libraries

SI_IML_WORKING_LIB

- user: The iml working library will be named <username>_devices.iml
- host: The iml working library will be named <hostname>_devices.iml
- unique: This option lets a single user have different file names if two different processes are being run in the same directory. Each file name is unique as it will include the process ID.

With the unique option, the dml working library will be named <host_name>_<user_name>_cosess_id>_devices.iml.

<any other string>: This string defines the name of the iml working library.

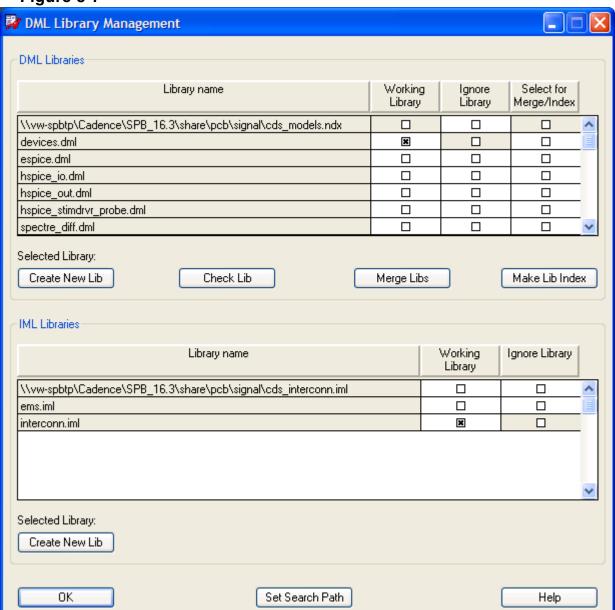
Managing DML Libraries

You use the DML Library Management dialog to manage DML libraries.

To access the DML Library Management dialog:

Click the Library Mgmt button on the DML Models or the IML Models tab of SI Model Browser dialog.

Figure 8-7



Working with Signal Models and Libraries

The DML Library Management dialog provides controls to set the working library, ignore libraries, and create indices.

Using the DML Library Management dialog, you can:

- create a new library and add it to the list of libraries
- Perform a syntax check on a DML library
- specify the working libraries
- create an index for a device model library
- merge two or more device model libraries

As many functions of the *SI Model Browser* are related to *model development*, you should refer to the following if you are an SI librarian:

- Allegro SI Device Modeling Language User Guide
- Allegro SI User Guide

Working with Signal Models and Libraries

Translating Models

This section covers:

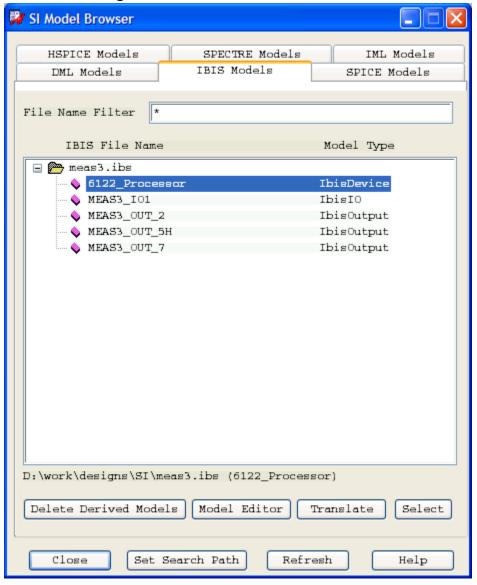
- Translating IBIS and Spice Models
- Translating HSPICE and Spectre Models

Translating IBIS and Spice Models

The process of translating IBIS and Spice models is similar, although IBIS lets you prepend the model's name to the translated DML (see Figure 8-9).

To initiate the translation, select the model under the appropriate tab (IBIS or Spice) and click the *Translate* button.

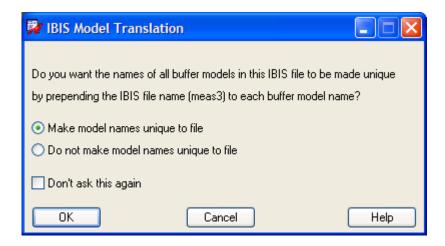
Figure 8-8 Translating Models



A dialog appears prompting you to choose how to handle the model names. IBIS files can be managed on disk in their native format and are automatically translated to DML transparent to the user. If errors are detected during the translation, an error is displayed.

This dialog is used when translating the generic IBIS file. IBIS EBD, ICM, and Package models work differently. The dialog for EBD models gives you the choice of creating either an IBISDevice or Board model. The dialog for an ICM model gives you the choice of creating a connector, blackbox, or package model. Package models are always translated to a DML package model.

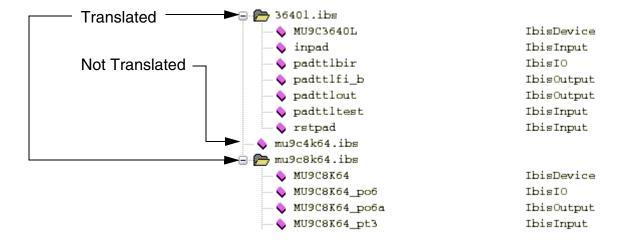
Figure 8-9 Qualifying File Names



At this point you have the option of selecting a buffer model directly from SI Model Browser dialog or a specific pin (packaged buffer model) from the IBISDevice. In either case, after a selection is made in SI Model Browser, you need to click the *Select* button

Once a signal model is translated, its icon is promoted to a folder, with translated DML models shown as children, along with the model's purpose (see <u>Figure 8-10</u> on page 158).

Figure 8-10 Model Translation Nodes (IBIS shown)



To delete a model,

Select the model in the list and click the Delete Derived Models button.

This deletes all the child DML models associated with an IBIS model.

Working with Signal Models and Libraries

If the selected model fails to translate, you are prompted to edit the model. If you choose *Yes*, the model is opened in Model Editor. After you save the edits, the model is re-translated after you close Model Editor.



You can also select model and click the *Model Editor* button to edit the model in its native format.



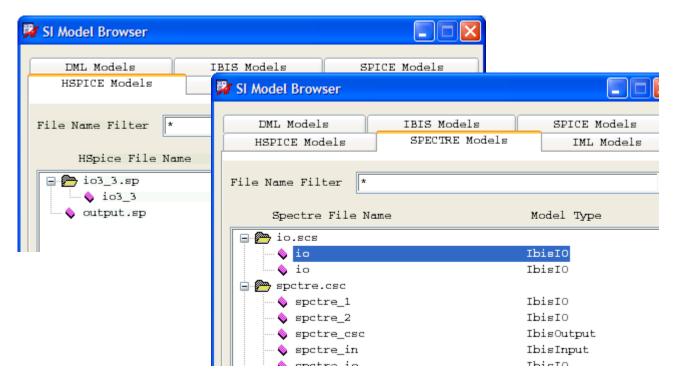
If you edit a DML model (that was translated from an IBIS file) from the DML Models tab, the model is no longer consistent with the data in the IBIS file, and it will be removed from the list of DML files shown under the IBIS tab. It will, however, remain in the list of models shown under the DML Models tab.

Translating HSPICE and Spectre Models

HSPICE and Spectre translations are more involved than IBIS and Spice. SigXplorer's model translation wizard, however, guides you through this translation, step-by-step.

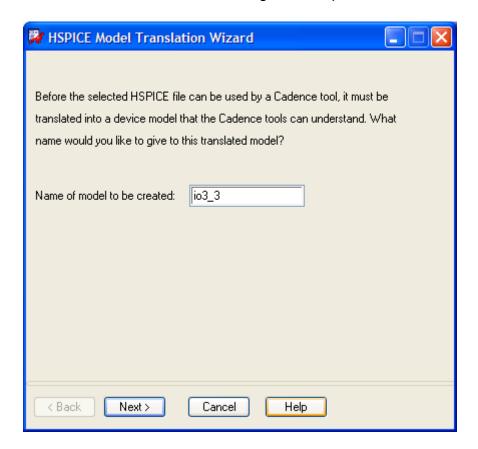
To translate an HSpice or Spectre model:

1. Click the model name in the appropriate tab, HSPICE or Spectre.



2. Click Translate.

A translation wizard starts. The first window gives an option to rename the model.



In the remaining pages of the wizard, you need to do the following:

- Select the type of translation you want to perform: Black Box model or IOCell model.
- Choose the type of IOCell model out of six model types and then select subcircuits in the model. One subcircuit must be selected as the Master and the rest can be selected for inclusion in the model.
- Identify the function of each subcircuit terminal.
- Specify how each Signoise IO cell terminal is to be treated.
- Specify the DC voltage of the IO cell, and the voltage ranges for the input stimulus signal and the Enable signal
- Specify reference values for power, ground, pull up and pull down devices. You can choose to copy from an existing model as well.
- Specify high and low input logic threshold voltages.
- Specify if you want to include any files in the models being created.

Specify if you want to include package parasitics. If you choose Yes, you will need to specify how to define package parasitics.

When the final page of the wizard displays, click *Finish* to translate the model. The translated model appears in the appropriate tabbed page. See Figure 8-12

You might also want to view the models to be created. You can do so by clicking the *View* Model(s) To Be Created button. The model opens in Model Editor.

Figure 8-11 Final Page of the Model Translation Wizard

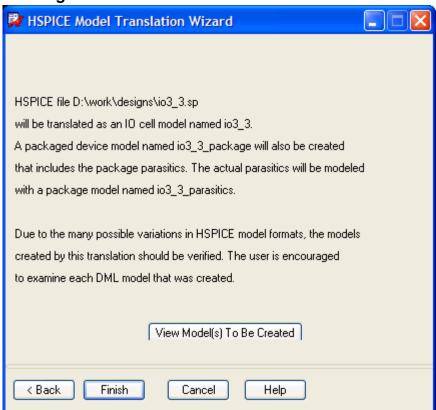
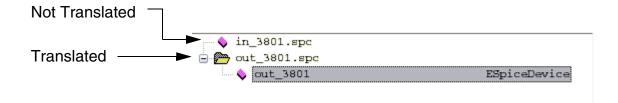


Figure 8-12 Translated Model



9

Device Modeling

IOCell

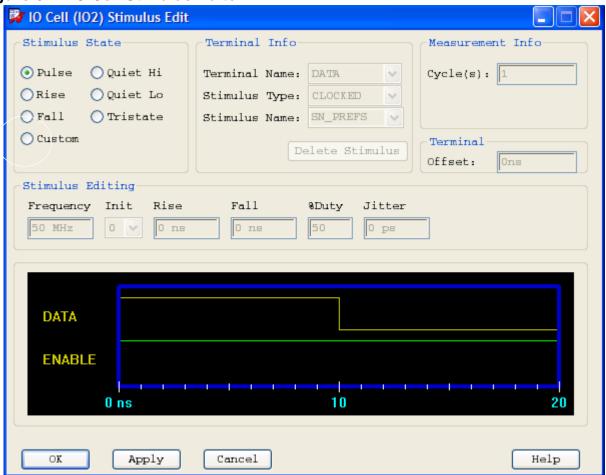
Topics in this chapter include:

- Introduction on page 164
- Viewing the Waveform for a Stimulus on page 165
- <u>Defining Terminal Information</u> on page 166
- <u>Defining Measurement Information for Custom and Tristate Stimuli</u> on page 168
- <u>Defining Terminal Offset and Skew for Custom Stimuli</u> on page 169

Introduction

For both pre-defined and custom stimuli, you use the *IO Cell Stimulus Edit* dialog to change the stimulus associated with an IOCell and view the waveform. You can also define the characteristics of a custom stimulus.

Figure 9-1 IO Cell Stimulus Editor



The stimulus state assigned to the IOCell determines the stimulus state applied to an IOCell during simulation. You choose from six pre-defined stimulus states and a customizable stimulus state.

- Pulse
- Rise
- Fall
- Quiet Hi

Device Modeling

- Quiet Lo
- Tristate
- Custom

The pre-defined stimulus states derive their stimuli from parameters set in the Analysis Preferences dialog. You define the Custom stimulus in the Stimulus Editor. The default stimulus state for an IOCell is Tristate.

You use the IOCell Stimulus Edit dialog to modify the stimulus state associated with an IOCell, or buffer symbol in the canvas. The associated stimulus applies to the IOCell when you perform simulation.

→ To display the IOCell Stimulus Editor, click the stimulus associated with an IOCell symbol.

For more information on the editor, see the <u>SigXplorer Command Reference</u>.



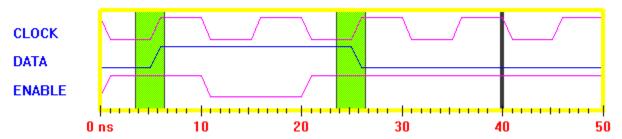
You save and recall stimulus vectors for all IOCell drivers in the topology with the Setup – Vectors command.

When you select *Custom* in the Stimulus State area, you activate all areas for defining the Custom stimulus. With the editing areas active, you can define the Custom stimulus in the Stimulus Editor. The default values for a Custom stimulus populate from parameters set in the Analysis Preferences dialog.

Viewing the Waveform for a Stimulus

Waveforms for each IOCell terminal appear at the bottom section of the Stimulus Editor.

Figure 9-2 The Stimulus Editor Waveform



Device Modeling

For both pre-defined and custom stimuli, a reference data clock waveform aids you in defining data stimuli. The initial frequency of this waveform comes from the frequency specified in the Analysis Preferences dialog.

The following defines the signal color in the Waveform Display:

Yellow Current signal you are editing.
 Red Signal that you cannot edit.
 Green Signal that is editable but is not active.
 Purple bands Setup and hold margins.
 Gray vertical markers Simulation run time.

Defining Terminal Information

Terminal information for an IOCell symbol comes from the IOCell buffer model associated with the IOCell symbol based on the following criteria.

IOCell Type	Terminal
Output (only)	Only the data terminal defines the stimuli.
Bi-directional	Both the Data and Enable terminals define stimuli.
Clocked IO	Clock, Data, and Enable terminals define the stimuli.
MacroModel definition	Each terminal, except for Data and Enable, defines the stimuli named in the PinTerminalsMap of the MacroModel definition.

Frequency and Pattern

For Periodic and Synchronous stimuli, *Frequency* and *Pattern* specify the frequency of the stimulus reference clock and the bit pattern used for the stimulus. For a Synchronous stimulus, click *Random* to generate a random bit pattern of a specified length. The default value for *Frequency* comes from the Clock Frequency Analysis Preference.

Device Modeling

Init, Switch Times, and Switch At

For the Asynchronous stimulus, *Init* and *Switch Times* specify the initial state for the stimulus and the times at which the stimulus switches. Enter a list of switch times separated by spaces.

For the Synchronous stimulus, *Init* and *Switch At* specify the initial state for the stimulus and the point at which the stimulus transitions; on the rising edge, the falling edge, or on both edges.

Tr and Tf

For all stimuli, Tr and Tf display the transition rise and fall times. Tr or Transition Rise Time displays the time it takes the signal to transition from the low state to the high state. Tf or Transition Fall Time displays the time it takes the signal to transition from the high state to the low state.

Rise and Fall

For all stimuli, *Rise* and *Fall* display the transition rise and fall times. *Rise* displays the time it takes the signal to transition from the low state to the high state. *Fall* displays the time it takes the signal to transition from the high state to the low state.

% Duty

For the Clocked stimulus, *%Duty* sets the percentage of time that the clock signal is high in a single clock cycle. For example, *50* represents equal high and low periods of the cycle. The default value for *%Duty* is taken from the Duty Cycle Analysis Preference.

Jitter

For the Clocked stimulus, *Jitter* sets the time period for variations between system clock cycles at an IOCell pin. *Jitter* is the potential for a single-cycle narrowing of the clock period. For example, a *10 ns* cycle with *10 ps* of jitter could result in a potential cycle time of *9.99* to *10 ns*.

In a perfect network, the system clock always arrives exactly on time (one clock period from the end of the previous clock cycle at a given IOCell pin). In reality, the clock may not arrive exactly on time, but may arrive earlier or later than expected.

Device Modeling

Clock jitter describes the variations in clock edges as the clock signal travels through the electronic components in the circuit. For example, for a clock period of *20 ns*, a jitter value of *10 ps*, rise and fall times of *1 ns*, and a *duty cycle of 50%*, the clock edges can fall within the following time ranges:

1st rising edge -0.005ns to 0.005ns 1st falling edge 9.990ns to 10.010ns

Jitter can be coherent and incoherent in the following situations. Jitter is coherent when the clock instances have the same distribution, resulting in identical clock cycles. This is typical of a central clock generator where jitter is shared by all receivers. Jitter is incoherent when clock instances exhibit independent jitter. This is typical of receivers clocked from different sources.

Defining Measurement Information for Custom and Tristate Stimuli

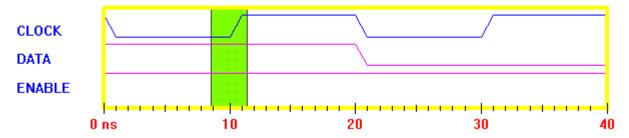
For Custom and Tristate stimuli associated with a clocked IOCell MacroModel, you can set *Cycles*, *Setup* and *Hold* in the Measurement Info area.

- In Cycles, specify the clock pulse at which to make measurements. At a minimum, the simulation runs for the highest specified cycle number. The default value for Cycles propagates from the Measurement Cycle Analysis Preference.
- In Setup, set the desired settle time for the data signal so it can latch on a synchronous device on the next clock cycle. You use Setup to determine if a signal arrives too late.
- In *Hold*, set the time for a signal to remain latched at one synchronous device before launching to a second synchronous device. You use *Hold* to determine if a signal arrives too early.

You use *Setup* and *Hold* to stabilize a data signal at a synchronous device, so that the data signal latches in a predictable state when the clock edge arrives. <u>Figure 9-3</u> illustrates sample *Setup* and *Hold* margins.

Device Modeling

Figure 9-3 Sample Setup and Hold Margins



For a Tristate stimulus not associated with a clocked IOCell MacroModel, you can set only the Measurement Cycle value. In the Measurement Info area, specify the clock pulse at which to make measurements. At a minimum, the simulation runs for the highest specified cycle number. The default value for *Cycles* comes from the Measurement Cycle Analysis Preference.

Defining Terminal Offset and Skew for Custom Stimuli

In the Terminal area, enter the offset value, the launch time for the arrival of the stimulus at the IOCell input pin. The default value for *Offset* comes from the Offset Analysis Preference.

In the Terminal area, enter the skew value, the clock latency for an IOCell. The Skew value shifts the clock stimulus.

Editing a Custom Stimulus

For a Custom stimulus state, you can use the Stimulus Editor to:

- Select the Custom stimulus state, if necessary (in the Stimulus State area)
- Edit the Custom stimulus (in the Stimulus Editing area)
- Specify terminal information (in the Terminal Info area)
- Specify cycles (in the Measurement Info area)
- Specify terminal offset (in the Terminal area)
- View the waveform associated with the Custom stimulus (in the waveform display)

To enter multiple values for simulation sweeping, use the:

■ Linear Range to enter a range of values by specifying Start and Stop and a step size for iterating from the start value to the stop value.

Device Modeling

- Multiple Values to enter a list of values by specifying a list of discrete number values.
- Expression to enter an expression by specifying an expression string composed of operators, functions, and references to other parameters.

Device Modeling

ESPICE Device Models

Topics in this chapter include:

- Introduction on page 172
- Setting Pin Order on page 172

Device Modeling

Introduction

You use multi-terminal ESpice models for simulation to support advanced analysis using externally developed SPICE models. For example, a wire bond model created by an external 3D engine. Symbols for these devices occur dynamically, according to the number of terminals in the model source file. Simulating a topology containing these devices, creates simulator input files, as required, providing the needed circuit builder support.

Setting Pin Order

The pin order of the model defines the location of the port on the blackbox. You can edit the pin order in SigXplorer for better readability in <u>Model Editor</u>.

The following is an example of the text describing the pin order of the ESpice Device model Figure 9-4.

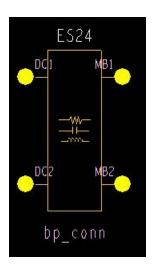
("espice.dml"

(PackagedDevice

(BP_CONN

(ESpice ".subckt BP_CONN DC1 MB1 DC2 MB2 <= this order defines left, right, left, right from top to bottom

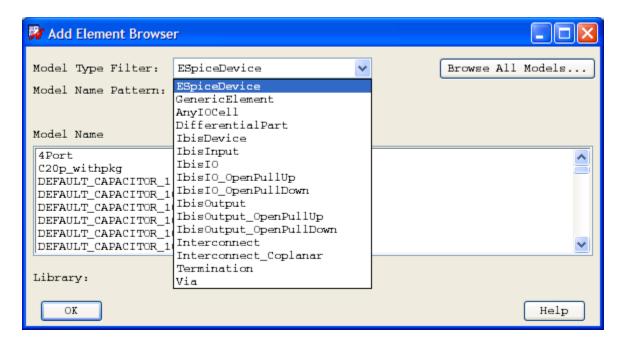
Figure 9-4 Example of pin order on an ESpice Device



Device Modeling

<u>Figure 9-5</u> shows the selection of a user-defined multi-terminal ESpice from the Add Element Browser.

Figure 9-5 Selection of a Multi-terminal ESpice Device in the Add Element Browser

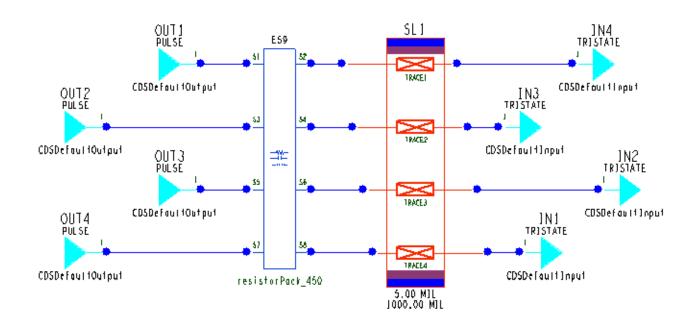


If you assign a multi-pin ESpice device to a part in SI, a subset model generates when extracting. For example, if pins S7 and S8 were in the net, SigXplorer creates an ESpice device, including the two pins. You could then reapply the topology with that subset model.

Figure <u>9-6</u> shows a user-defined multi-terminal ESpiceDevice and its use within a sample topology.

Device Modeling

Figure 9-6 Sample Multi-terminal ESpice Topology



Interconnect Modeling

10

Interconnect Modeling

Topics in this chapter include

- Introduction Etch on page 176
- Adding a Coupled Trace Model on page 181
- Editing a Coupled Trace Model on page 181
- Simulating a Coupled Trace Model on page 183
- <u>Viewing Parameters and Field Solution Results for Trace Models</u> on page 185
- Vias on page 188
 - □ <u>Via Model Types</u> on page 189
 - □ Via Model Generation on page 193
 - □ Padstack-Based Via Extraction on page 194
 - □ Adding Vias on page 198
 - □ Adding Dynamic Vias on page 199
 - □ <u>Via Parameters in SigXplorer</u> on page 201
 - Dynamic Via Parameters in SigXplorer on page 201
 - □ Coupling on page 203

Interconnect Modeling

Introduction - Etch

Coupled trace interconnect models and simulation sweeping in SigXplorer allow exploration of the electromagnetic-coupling behavior of PCB traces.

Coupled trace part models with two to six traces are available from the Add Element Browser for both Microstrip and Stripline layer stackups. As with other part models, coupled trace part models are user-definable. Embedded (dual) microstrip and stripline coupled trace parts are available to support broadside-coupled differential pairs. These parts currently support single traces on adjacent layers.

To determine acceptable parallelism rules, you can perform reflection, crosstalk, EMI, or custom simulation sweeps of the coupled trace part model parameters, including trace width, spacing between adjacent lines, and offset between line centers. To determine appropriate manufacturing tolerances, you can sweep layer stackup parameters (dielectric constant and thickness, and trace width and thickness) to explore potential layer stackup possibilities.

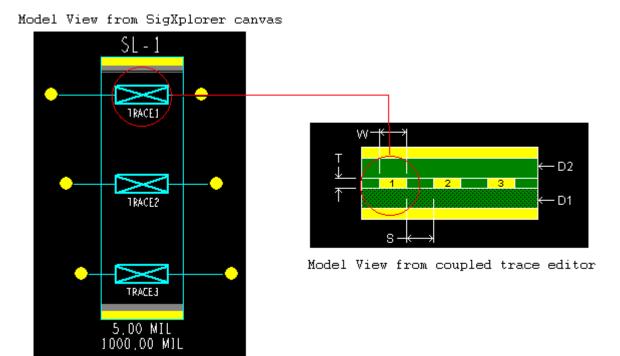
You define stimuli for victim and aggressor net IOCells using the IOCell Stimulus Editor.

Coupled Trace Symbols

Coupled trace symbols appear in the canvas as individual traces enclosed in a bounding rectangle. Colored bands across the top and bottom (yellow bands represent the shield/plane layers while green bands represent the dielectric layers) graphically indicate if the coupled-trace part is microstrip or stripline.

<u>Figure 10-1</u> represents a three-trace stripline geometry coupled trace symbol as viewed from the canvas (stacked vertically) and from the View Trace Model Parameters dialog (shown horizontally).

Figure 10-1 Viewing Trace Model Parameters



To invoke the View Trace Model Parameters dialog, do the following:

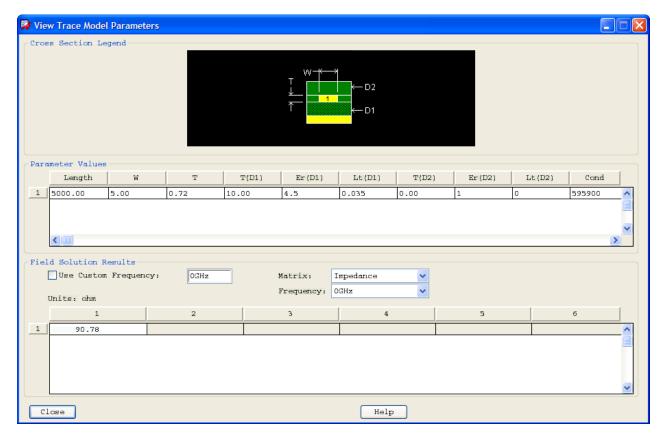
- **1.** Position your cursor over a trace name or one of its values in the Parameters tab of the SigXplorer spreadsheet.
- 2. Right-click to display the View Trace Parameters button and click it.



You can also right-click the trace on the canvas and choose *View Trace Model Parameters* from the pop-up menu to open the View Trace Model Parameters dialog.

Interconnect Modeling

Figure 10-2 View Trace Model Parameters Dialog



From this dialog you can view and explore the following:

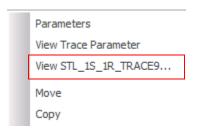
- Cross section view detailing the orientation of the traces and dielectric layers within the trace or coupled trace part model in the stackup
- Parameter values for the trace or coupled trace part model
- Spreadsheet display of field solution data for the trace or coupled trace part model. You can control display of data by selecting the parameter value set, Field Solver Cutoff Frequency and the impedance matrix for which to display data.

Associating a Trace Model

To associate a trace model symbol in the canvas to a specific trace model in the Interconnect library, do the following:

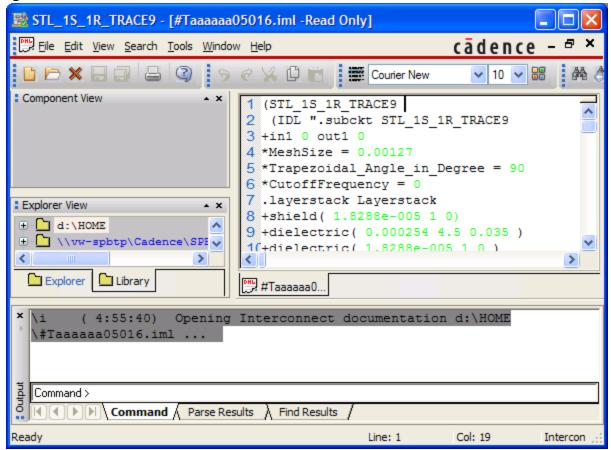
Interconnect Modeling

→ Right-click a trace and select the trace model name from the pop-up menu.



The field solved model for the trace is displayed.

Figure 10-3 Model Editor



Model Editor makes it easy to associate a trace model symbol in the canvas to a specific trace model in the Interconnect library.

Interconnect Modeling

Exploring Topologies Containing Coupled Trace Models

For early topology exploration (pre-part placement), you can select IOCell and coupled trace parts from the Add Element Browser to create a topology in SigXplorer.

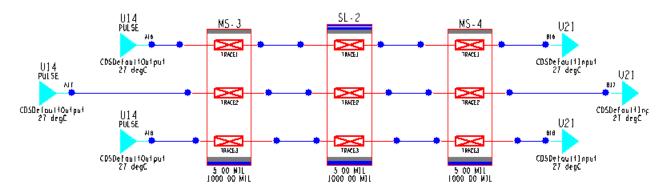
For post-part placement, you can extract a net from a routed board into the canvas, and then replace the interconnect with the appropriate coupled trace models. You can then experiment in the canvas with trace length, spacing and layer stackup parameters to derive a topology that satisfies the target design requirements.

You use a coupled trace symbol to model the crosstalk between lines of different logic levels or families. For example, TTL and ECL. You also explore the crosstalk of up to three differential pairs, whether edge-coupled or broadside-coupled.

Sample Coupled Trace Circuit

This circuit (<u>Figure 10-4</u>) uses three-trace microstrip and stripline coupled traces to model a bus net from one surface-mount IO pin to another. In this example, the signal travels from the top layer, through a stripline layer, back to the top layer.

Figure 10-4 Sample Coupled Trace Circuit



Interconnect Modeling

Adding a Coupled Trace Model

To add a coupled trace model:

- 1. Choose Edit Add Element.
 - The Add Element Browser dialog appears.
- **2.** From the Model Type Filter drop-down list, select *Interconnect*.
- 3. Select the desired coupled trace model and drag it to the canvas for placement.
- **4.** Right-click on the trace model and select *End Add* from the pop-up menu.
- **5.** Click *OK* to close Add Element Browser.

Editing a Coupled Trace Model

For a coupled trace part, you edit the following parameter values in the spreadsheet Parameters tab:

- RefDes for the coupled trace part.
- Thickness and dielectric constant for each dielectric layer.
- Trace spacing, length, width, and thickness.

To modify RefDes

- 1. In the canvas, select the RefDes or part name, above the coupled trace symbol.
 - The Parameters tab opens with the data for the selected coupled trace part expanded and the RefDes in the Attribute column highlighted for editing.
- **2.** Specify the new RefDes and press *Enter*.

The new RefDes replaces the old in both the Attribute column of the spreadsheet and above the part symbol in the canvas.

To modify the thickness or dielectric constant for the dielectric layers

- **1.** Position your cursor over a trace name or one of its values in the Parameters tab of the SigXplorer spreadsheet.
- **2.** Right-click to display the *View Trace Parameters* button, then click the button.

Interconnect Modeling

The Parameters tab in the spreadsheet opens with the data for the selected coupled trace part expanded.

The View Trace Model Parameters dialog opens with the following information:				
Detailed cross-sectional view of the trace model				
Parameter values associated with the trace model				
Parasitic information for the trace model				

3. In the *Value* column of the spreadsheet Parameters tab, click in the cell to the right of the dielectric constant or dielectric layer thickness whose value you want to edit. Then click the icon () that appears to the right in the cell.

The Set Parameter dialog appears for the selected attribute.

- **4.** In the Set parameters dialog, specify the new values.
 - a) To specify one value for a single simulation, use *Single Value* and specify one number value.
 - b) To specify multiple values for simulation sweeping:
 - Use Linear Range to specify a range of values by providing start and stop values and a step size for iterating from the start value to the stop value.
 - Use *Multiple Values* to specify a list of values by providing a list of discrete number values.
 - Use *Expression* to specify an expression by providing an expression string composed of operators, functions, and references to other parameters.
- **5.** In the Set Parameter dialog, click *OK*.

The new parameter values appear in both the canvas and the Parameters tab of the spreadsheet.

The change appears in *Parameter Values* of the View Trace Model Parameters dialog as well. SigXplorer adds a new line of data to the Parameter Values spreadsheet for each parameter value entered.

To view trace parasitics

In the canvas, click the trace length or trace spacing text below the coupled trace symbol.
 The attribute highlights in the spreadsheet.

Interconnect Modeling

- 2. Position your cursor over the attribute in the spreadsheet.
- **3.** Right-click to display the *View Trace Parameters* button, then click the button.

The View Trace Model Parameters dialog opens with parasitic information displayed in the *Field Solution Results* area.

Simulating a Coupled Trace Model

To simulate a coupled trace circuit, the victim net is held at a non-switching (quiet hi or quiet lo) state while the aggressor nets drive the simulation.

To edit the stimulus on the victim net driver

- 1. Click the stimulus state text on the driving IOCell of the victim net.
 - The IOCell Stimulus Editor appears.
- 2. In *Stimulus State*, select a non-switching state (either Quiet Hi or Quiet Lo).

The data displayed in the IOCell Stimulus Editor changes to reflect the new stimulus state. The Stimulus field for the IOCell symbol is also updated in the canvas.

To edit the stimulus on the aggressor nets drivers

Edit the stimulus state associated with each aggressor net driver in turn.

- 1. Click the stimulus state text for a driving IOCell on an aggressor net.
 - The IOCell Stimulus Edit dialog appears.
- **2.** In *Stimulus State*, select an appropriate stimulus state for each driver (Pulse, Rise, Fall, Custom, or Tristate).

The data displayed in the IOCell Stimulus Editor changes to reflect the new stimulus state. The *Stimulus* field for the IOCell symbol updates in the canvas.

To modify simulation parameters

- **1.** If required, use *Analyze Preferences* to display the Analysis Preferences dialog.
- 2. In the Analysis Preferences dialog, specify the required analysis parameters.

The modified analysis parameter values display in the Analysis Preferences dialog. The Cutoff Frequency value also displays in the View Trace Model Parameters dialog.

Interconnect Modeling

To select measurements

- 1. Click to select the Measurements tab.
- **2.** In the Measurements tab, select the Measurements to be made during simulation and the types of simulations to perform.

To perform the simulation

- **1.** Use *Analyze Simulate* to perform the simulation.
- **2.** When prompted, select a receiver of the victim net.
- **3.** If you are performing simulation sweeps, the Sweep Sampling dialog appears. Confirm the information it supplies and click *Continue*.

The Command tab displays messages during the simulation.

When the simulation is complete, the Results tab displays the simulation result data.

Note: Once you have derived the parallelism rules, you can set them (Setup - Constraints) in your target topology and subsequently apply the topology ($File - Update\ Constraint\ Manager$) in Allegro SI to each bit of a bus.

Interconnect Modeling

Viewing Parameters and Field Solution Results for Trace Models

Use the View Trace Model Parameters dialog to display the following information for a trace or coupled trace symbol selected from the canvas:

- Cross section view detailing the orientation of the traces and dielectric layers for the trace or coupled trace part model in the stack up
- Sets of parameter attribute values for the trace or coupled trace model
- Spreadsheet display of field solution data for the trace or coupled trace model.

Viewing Parameter Attribute Values

The *Parameter Values* area displays the sets of parameter attribute values to sweep at simulation time. You set and modify these values through the Parameters tab of the spreadsheet. When you change parameter values from the Parameters tab, the *Parameter Values* area updates.

Exploring Field Solution Data

Selecting one of the numbered parameter attribute value sets that appear in the *Parameter Values* area, calculates and displays the field solution data for that set of parameter attribute values.

You can further explore field solution results for individual parameter sets by selecting or entering field solver cutoff frequencies at which to recalculate field solution data. Select existing cutoff frequencies from the *Frequency* pulldown. Enter new cutoff frequencies in *Field Solver Cutoff Frequency*.

Changes you make to the *Field Solver Cutoff Frequency* while exploring field solution results are local to this dialog. You must establish the *Default Cutoff Frequency* used during simulations from the Analysis Preferences dialog. The Ems2d field solver also uses this value *unless* a different cutoff frequency is specified in the <u>EMS2D Preferences dialog</u>. The *Default Cutoff Frequency* established in the Analysis Preferences dialog is among those listed in the *Frequency* pull-down.

You can also change the spreadsheet display of field solution results by selecting the field solution matrix for which to display data. Use the *Matrix* pull-down menu to select a matrix from one of the following: Capacitance, Inductance, Modal Velocity, Admittance, Near-end

Interconnect Modeling

Coupling, Impedance, and Modal Delay. In addition, when the cutoff frequency is above 0 GHz, you can also select *Linear Resistance* and *Dielectric Conductance*.

To view Cross Section, Trace Model Parameters, and Field Solution Results

- In the canvas, click the trace length or trace spacing text below the coupled trace symbol.
 The attribute highlights in the spreadsheet.
- 2. Position your cursor over the attribute in the spreadsheet.
- **3.** Right-click to display the *View Trace Parameters* button, then click the button.
 - The View Trace Model Parameters dialog appears with the cross section, parameter values, and field solution results for the trace model.
- **4.** In the *Parameter Values* area, click within a spreadsheet row to calculate and display the field solution data for that set of parameter attribute values. Field solution is performed at the Cutoff Frequency displayed in the Field Solver Cutoff Frequency field.
 - The spreadsheet in the Field Solution Results area changes to display the field solution data for the matrix displayed in the Matrix field.

To explore Field Solution Results

You explore different field solutions by changing the cutoff frequency and displaying different matrices.

1. Use the Matrix pull-down menu to change the data displayed in the Field Solution Results spreadsheet.

The following choices are available for all cutoff frequencies:

Impedance, Capacitance, Inductance, Modal Velocity, Admittance, Near-end Coupling, and Modal Delay. At cutoff frequencies above 0 GHz, Dielectric Conductance and Linear Resistance are also available.

The Field Solution spreadsheet changes to display the new matrix. The *Units* field above the spreadsheet displays the units used for the spreadsheet data.

2. Use the *Frequency* pull-down to select an existing cutoff frequency or enter a new value in *Field Solver Cutoff Frequency*.

The field solver recalculates for the selected parameter values and cutoff frequency. The spreadsheet displays the field solution for the selected matrix.

Interconnect Modeling

The new cutoff frequency value is added to the *Frequency* menu. Changes to cutoff frequency made in this dialog are local and are not preserved or used for simulations. Use the Analysis Preferences dialog to set the cutoff frequency used for simulation.

Interconnect Modeling

Vias

Topics covered in this section:

- Introduction Vias on page 189
- <u>Via Model Types</u> on page 189
- Net Extraction and Via Models on page 192
- <u>Via Model Generation</u> on page 193
- Padstack-Based Via Extraction on page 194
- Adding Vias on page 198
- Adding Dynamic Vias on page 199
- Via Parameters in SigXplorer on page 201
- <u>Dynamic Via Parameters in SigXplorer</u> on page 201
- Coupling on page 203
- <u>Via Model Formats</u> on page 204

Interconnect Modeling

Introduction - Vias

For multi-gigahertz designs, it is critical to model via structures accurately over a very high frequency range. Vias often represent some of the most significant discontinuities on PCB, package, and IC structures. Given their inherent 3D nature, they can cause severe signal integrity and EMI issues. In addition to signal degradation on the host net, via excitation of waveguide modes can propagate and radiate energy to neighbor nets and into space as well.

The via modeling capability currently available in SigXplorer is accurate well into the GHz frequency range.

The electrical via model formats include:

- Narrowband
- Wideband
- Scattering parameters (S-parameters)

Via model types include:

- Single vias
- Coupled vias signal, signal-and-ground, and signal-and-power

In SigXplorer, you can:

- create via models in SigXplorer
- add them as parts to a topology, perform what-if simulations,
- analyze the results using SigWave before committing to a PCB layout.

Important

Plated-through holes (PTHs) associated with component pins in Allegro (for example, PTHs for a backplane connector) are *not* seen as *vias* and are *not* automatically extracted into SigXplorer. You must add these structures manually using the Via Model Generator and include them for simulation accuracy.

Via Model Types

In addition to single vias, SigXplorer lets you generate and add coupled vias. The three general types are

■ Signal-and-signal

Interconnect Modeling

- Ground-and-signal
- Power-and-signal

Note: Power-and-signal vias require an external voltage source.

Coupled via symbols are distinguished from single signal via symbols, as shown below.

Figure 10-5 Single Signal Via Symbol

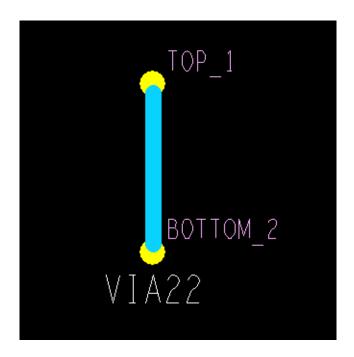
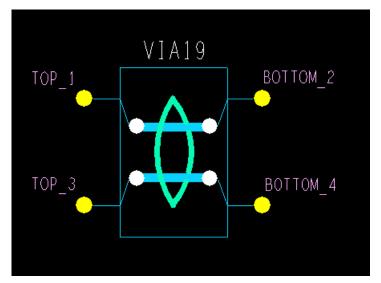
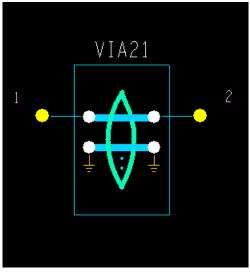


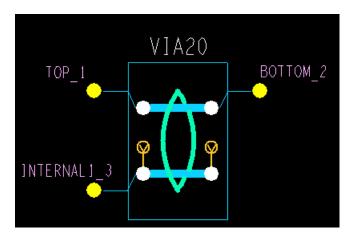
Figure 10-6 Coupled Via Symbols



Signal-and-signal Via



Ground-and-signal



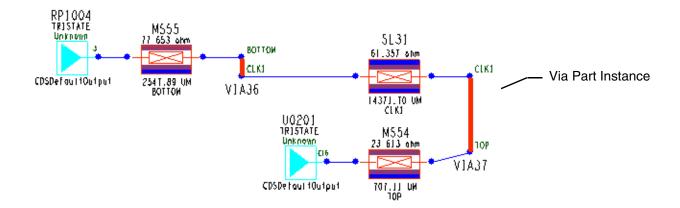
Power-and-signal Via

Interconnect Modeling

Net Extraction and Via Models

When you extract a net topology from your PCB design into SigXplorer, any Closed Form via models associated with the interconnect are displayed in the canvas as via part instances, as shown in <u>Figure 10-7</u> on page 192. Once available in SigXplorer, these via models can be upgraded interactively to one of the other available via model formats (S Parameter, Wideband or Narrowband) and used for advanced exploration. For further details, see the procedure for editing via models in the <u>SigXplorer Command Reference</u>.

Figure 10-7 Extracted Topology with Vias



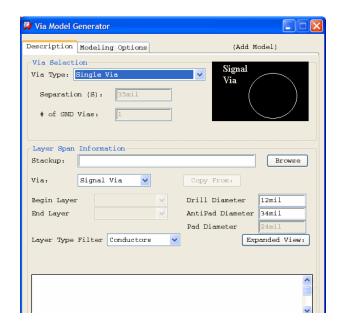
Interconnect Modeling

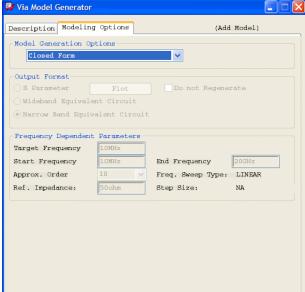
Via Model Generation

You can modify an existing via model or create one from scratch using the Via Model Generator dialog shown in Figure 10-8.

Note: Before you create a new via model, be sure that the library you want to add it to is designated as the *working* library. For details on how to set the working interconnect library, refer to the procedures for working with libraries in the <u>SigXplorer Command Reference</u>.

Figure 10-8 Tabbed Via Model Generator Dialog





To access the Via Model Generator dialog

→ Choose Analyze – Via Model Generation.

For information on how to create or edit a via model, refer to the via modeling procedures in the *SigXplorer Command Reference*.

You can also add a via which is not pre-solved to a specified model. You can bypass the Via Model Generation process and directly add a single or coupled via on the canvas.

Interconnect Modeling

Padstack-Based Via Extraction

A drill and pad data defining a via can be modified at any point in SigXplorer. This eliminates the need to translate or convert data between different tools. SigXplorer supports padstack-based via extraction. All the dimensions of a drill, pad, and anti-pad come from the padstack instead of a real drawing on the board.

In PCB SI, the padstack data is available as library items, initially stored as external pad files. Use this option to import the padstack data, which defines the pad for vias and other padstacks. The ability to import and export pad data from PCB SI and SigXplorer lets you exchange edited pads amongst all the tools.

SigXplorer includes the *Via Padstack Manager* dialog to create, edit, import, and export via pad stacks. Use the Via Padstack Manager dialog to manage padstack-based via extractions.

- **1.** Right-click a net on the board and choose *View Topology* from the pop-up menu to extract the net.
- **2.** In SigXplorer, choose *Setup Manage Via Padstacks*.

The *Via Padstack Manager* is displayed.

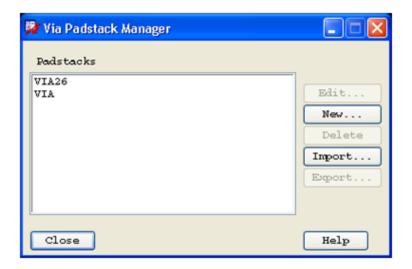


Table 10-1 Via Padstack Manager

Field Description

Padstacks Lists the available padstacks.

Interconnect Modeling

Field Description

Edit Opens the Padstack Designer dialog where you can edit the

selected padstack and save it to the design or to a library.

New Helps you create a new padstack and save it to the design.

When you click *New*, you are prompted to specify a name

for the padstack.



The specified padstack name is added to the list of padstacks. You can then select the new padstack name from the list and click *Edit* to edit the padstack in the Padstack Designer dialog.

Delete Deletes the selected padstack.

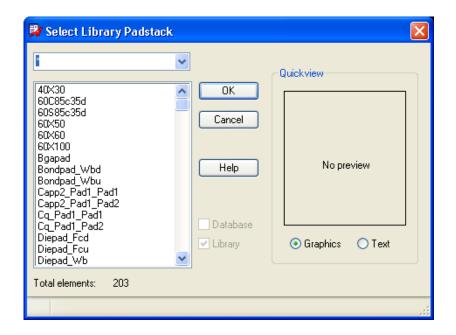
Interconnect Modeling

Field

Import

Description

Use this option to import the padstack data. It opens the Select Library Padstack dialog, which lists all the available library padstacks, whether the padstacks are used in the current design or not. You can choose a library padstack from the list.



Export

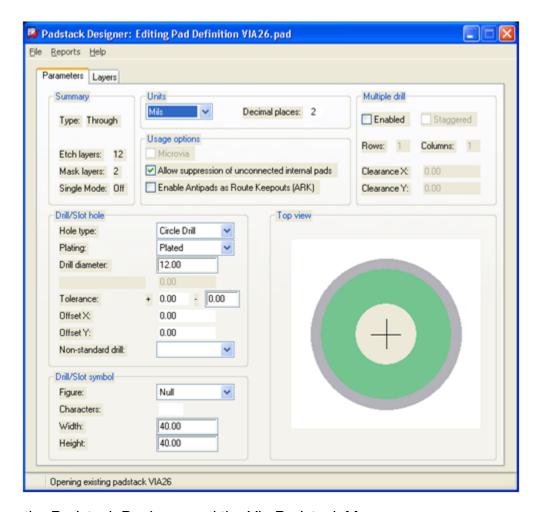
Use this option to export the padstack data as a .pad file, which can be imported in PCB SI.

The Via Padstack Manager shows a via extracted from the board file and the new default via in SigXplorer (VIA).

3. Select a via from the list, and click the *Edit* button to launch the Padstack Designer used in Allegro.

Interconnect Modeling

Padstack Designer lets you create and edit padstacks and save them to your design, to a library, or to both at once. You define the pad size and shape for all etch/conductor and nonetch/conductor mask layers in the Padstack Editor.



4. Close the Padstack Designer and the Via Padstack Manager.

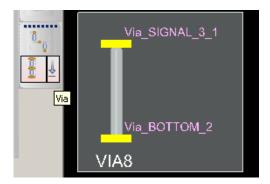
Note: The extracted via models and padstacks are stored in a new directory sigxp.lib in the same directory in which the .brd file resides.

Interconnect Modeling

Adding Vias

Compared to previous releases, now adding a via is an easier and faster process. You no longer need to go through the *Via Model Generator* (VMG) to create a model or search the list of existing model that fit the need. Unlike previous releases, instead of adding a via model, you add a via, which may not be pre-solved to a specific model.

1. Select the via icon in the SigXplorer toolbar

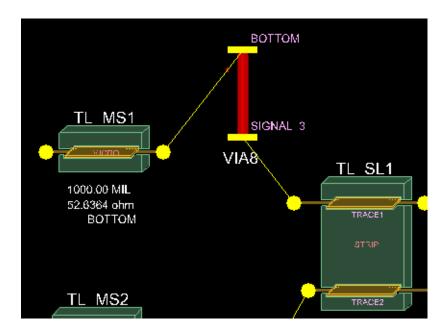


A new via is added with two nodes, that is two connection points, on the canvas. When a via is added, the two nodes are not tied to any specific layer as they are supposed to take on the properties of the connected nodes. The default label of the nodes is Layer1 and Layer2.

2. Click between one of the yellow nodes of the via and a pin on a trace model to connect the new dynamic via to one of the trace elements in the canvas.

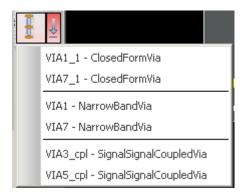
Interconnect Modeling

The corresponding layer on the via is changed to match the layer of the connected trace model.



Adding Dynamic Vias

You can re-use already solved via models in SigXplorer in a topology. Such vias are called *dynamic vias*. The Via toolbar icon has a pulldown that lists all the existing solved via models that exist in the interconnect libraries. These solved via models can be selected and added to the design. Hovering over the entries provides a tooltip with details of the model.



When you select the via toolbar icon a dynamic via is added, which can be placed directly on the canvas. When a dynamic via model is added to the canvas, the model is locked to the via and cannot be changed.

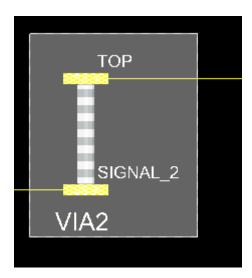
Note: For dynamic vias, the structure is always created on the fly and checked in the library.

Interconnect Modeling

To add a dynamic via in SigXplorer, a layerstack needs to be present in the topology otherwise the Add Element Browser is launched. When a topology is extracted from a .brd file, the stackup is automatically extracted. You can also create or import a layerstack using the *Manage layerStacks* command.



When a topology is extracted from Allegro, the layerstack of that board is automatically imported in the topology. Dynamic vias do not have bounding box. Vias with associated geometry or a solved model have a bounding box.



Interconnect Modeling

Via Parameters in SigXplorer

Each dynamic via has the following parameters associated with it:

- model: The via model associated with the via. A via without any model as yet has UNMODELED as a model. Once solve, the name of the model is used.
- **viaOutputFormat:** The format with which the model was solved. If no model exists yet, the format is Unknown.
- viaPadstack: The name of an available padstack. This parameter is a pulldown list showing the available padstack files on disk and in the library.
- viaTopLayer: The top-most layer of the via drill.
- viaBottomLayer: The bottom-most layer of the via drill.



Dynamic Via Parameters in SigXplorer

Apart from the parameters listed in <u>Via Parameters in SigXplorer</u> on page 201, a coupled via includes two additional parameters,

via name with which it is coupled

Interconnect Modeling

■ distance between the two vias

☐ VIA2	
CoupledVia	VIA3
CouplingDistance	35.00 MIL
model	UNMODELED
viaOutputFormat	
viaPadstack	VIA
viaTopLayer	TOP
viaBottomLayer	воттом
□ VIA3	
CoupledVia	VIA2
CouplingDistance	35.00 MIL
model	UNMODELED
viaOutputFormat	
viaPadstack	VIA
viaTopLayer	TOP
viaBottomLayer	ВОТТОМ

Interconnect Modeling

Coupling

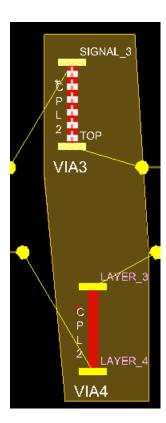
In 16.6, you can create coupled vias with a few clicks. To create coupled vias, do the following steps:

1. Select the two vias on the canvas to be coupled, right-click and choose *Couple* from the pop-up menu.



2. Specify the distance between the two vias and click *OK*.

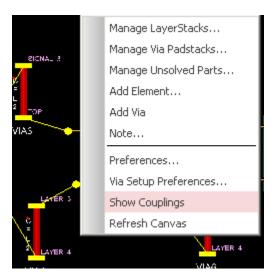
The coupled vias share a common label (CPL2) on the left hand side indicating which coupling pair it belongs to.



Interconnect Modeling

You can also toggle between the *Show Couplings* and *Hide Couplings* command in the pop-up menu. This command shows/hides a yellow bounding box around each set of coupled vias.





Note: Make sure that each of the coupled vias has at least one connection to another part of the topology

Via Model Formats

S-Parameter Format Details

- This is the most accurate via format. It should accurately capture the via behavior over the entire frequency range.
- Expect slower performance compared the circuit-based formats as more processing is required.
- Start Frequency for MGH applications is recommended at 10MHz. If DC convergence issues occur, you can drop to 1MHz (but no lower than 0.1MHz).
- End Frequency should be about 2/t_rise (1/t_rise minimum). Go up to 5/t_rise for greater accuracy, similar to when you use a fine waveform resolution like 5ps or 10ps.
- No. of Freq Points should be 128 points for most via models (this is the default value)

Note: If you include S-Parameter via models in larger S-Parameter circuits, their accuracy must be similar to that of the final circuit.

Interconnect Modeling

S-Parameter Settings Example

Edge Rate	Start Freq.	End Freq.	Bandwidth	No. of Freq. Points
100 ps	10 MHz	20GHz	20 GHz	128

Wideband Equivalent Circuit Details

- Start Frequency for MGH applications is recommended at 0MHz.
- End Frequency should be about 20 GHz.
- Leaving *Approx Order* set to 10 is recommended. You can increase it to 12 if *End Frequency* goes beyond 20GHz for improved accuracy.

Note: Setting *Approx Order* greater than 15 is not recommended.

The narrowband model is derived from the *Target Frequency*.

- There is some loss of accuracy compared to the S Parameter format. However, simulation time is significantly faster.
- Convergence issues are possible if the frequency range is stretched too far.

Narrowband Equivalent Circuit Details

	Use a target frequency that is near the middle of the energy content.
	A good rule of thumb is $1/(1000$ *risetime). For a driver with 100ps rise times, a target frequency of 10MHz is recommended.
	If the <i>Target Frequency</i> is too high, then low frequency (DC losses) are dramatically overestimated.

- If the *Target Frequency* is too low, then high frequency effects (skin effect and dielectric loss) are underestimated. However, these are small effects in a via.
- This is the least accurate of the via model formats. However, it is very stable and simulates very quickly.

Allegro SI SigXplorer User Guide Interconnect Modeling

11

Model Solving

This chapter covers the following topics:

- Overview
- Solving Models
 - Managing Unsolved Parts
 - O Solving in a Batch

Model Solving

Overview

In a pre-16.6 release, when you extract a net to SigXplorer, all the structures are automatically solved in Allegro SI and then passed to SigXplorer. At times, the layerstack of the extracted structure might differ from the real layerstack in terms of the voids in a plane layer or shapes on the conducting layer. In such cases, the structure needs to be re-solved in SigXplorer. At other times, field solution in SigXplorer takes a long time to run and often runs when not needed.

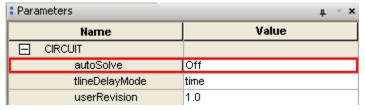
Allegro PCB SI provides support for on-demand trace model solving using Bem2D and Ems2D. However, unlike previous releases, now compulsory model solving during extraction from PCB SI is eliminated. The vias and trace models are unsolved when extracted from PCB SI and no impedance values are reported for trace models after extraction if no matched models are found in the existing working IML library.

autoSolve

The autoSolve parameter when set to On automatically calls the Solver when you make changes in the parameters of a trace in the spreadsheet, for example.

The *autoSolve* parameter at the circuit level is set to Off, by default. As a result, during extraction, no solving is triggered except for FSVia. FSVia models are always solved during extraction.

Figure 11-1 The autoSolve Parameter



However, for the commands which require a field solution, such as Simulate, Generate S-Parameters, and Transform to Constraint Manager, the default status of the *autoSolve* parameter is overridden and models are produced.

Model Solving

Solving Models

Models can only be solved using one of the following methods if the *autoSolve* parameter is set to Off by default:

- Running a simulation
- Using the Manage Unsolved Parts command
- Using the Solve Batch Mode command

Managing Unsolved Parts

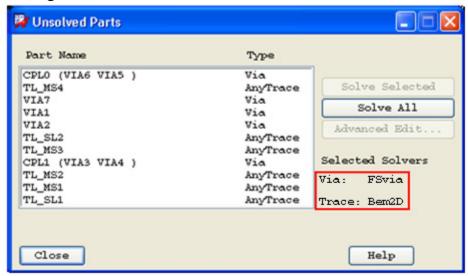
The Manage Unsolved Parts command helps you manage all the unsolved parts including vias and traces. The command launches the Unsolved Part dialog which lists all the parts that have not been solved.

To solve a part, do the following:

- 1. Specify trace solver preferences:
 - **a.** Choose *Analyze Preferences* or right-click on the canvas and choose the *Preferences* command from the pop-up menu.
 - **b.** Click Simulation Parameters.
 - **c.** Choose the appropriate trace solver from the Solver list, *EMS2D* or *Bem2D*.
 - **d.** For EMS2D, click the *Solver Preferences* button and specify EMS2D-specific preferences.
 - e. Close the dialogs.
- 2. Specify via solver preferences:
 - **a.** Choose *Analyze Via Setup Preferences* or right-click on the canvas and choose the Via Setup Preferences command from the pop-up menu.
 - **b.** In the Via Model Setup dialog, ensure that *FSvia* is selected.
 - **c.** Click *OK* to close the dialog.
- **3.** Right-click on the canvas.
- **4.** Choose the *Manage Unsolved Parts* command.

The Unsolved Parts dialog appears.

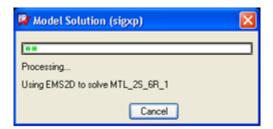
Figure 11-2 Unsolved Parts



The Part Name column lists unsolved parts, while the Type column shows the type of the part, such as via or trace. The currently selected solver for via and trace are also displayed. For example, in <u>Figure 11-2</u> on page 210, FSVia is selected to solve the Vias, while BEM2D is used to solve the traces.

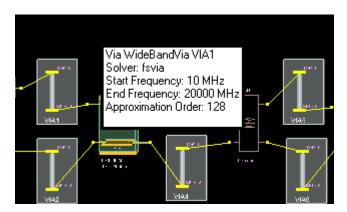
Note: All the parts in the design appear in this dialog if there is no solved model associated with the extracted geometry found in the interconnect model library. If you run the Solver for one of the vias or traces, it is possible that the geometry matches one or more of the other elements. If so, the next time you launch this dialog, it may show fewer parts than expected.

- **5.** You can perform one of the following actions in this dialog.
 - **a.** Select one or multiple part name(s) and, click Solve Selected to solve an individual part.
 - **b.** Click Solve All to solve all the parts in one go.
- 6. Click Solve All.



Model Solving

When solved, the tooltip on the via/part on the canvas displays details of the solved part:



Solving in a Batch

You can also solve traces and all vias using the Solve Batch command. Use this command to solve a single part in order to see the impedance, for example, or to create a model in the library with the current parameters.

→ Right-click on an unsolved part and choose the Solve Batch Mode (<solver name>) command.

Allegro SI SigXplorer User Guide Model Solving

S-Parameters

12

S-Parameters

Topics in this chapter include:

- Introduction on page 214
- <u>S-Parameter Generation</u> on page 214
- Time Domain Analysis on page 218
- Typical Use Models on page 222

S-Parameters

Introduction

Scattering parameters (S-parameters) are mathematical expressions used to define the relationships of traveling waves between ports of a black box. When a signal enters one port, with other terminated ports, S-parameters describe how the traveling waves transmit to and reflect from the various ports of the black box. S-parameters are the reflection and transfer coefficients for the network. S-parameters can characterize the behavior of these structures over a wide frequency range.

S-parameters are used to:

- Analyze frequency characteristics of a complex network.
- Represent a complex network with a single black box.
- Incorporate S-parameter lab measurements in simulations with other circuit elements.

Substituting an S-parameter model for a topology or elements of a topology is not always the best option, because they:

- Are behavioral models, so they lose physical association with the topology.
- Depend on measurement techniques or generation input parameters.
- Are slower to simulate, because they require more processing, depending on the simulator and how much data is in the model.

S-Parameter Generation

Use SigXplorer for S-parameter generation to:

■ Evaluate channel loss in the frequency domain to determine if the topology meets the loss budget.

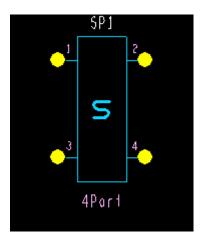


Experiment with the frequency range and number of frequency points to gauge different responses. For example, using higher End Frequency and more Frequency Points improves accuracy (at the cost of slower performance). See example <u>Viewing Frequency Response Using S-Parameters</u> on page 222

■ Create an ESpice black box model of the S-parameter data for use in Time Domain Analysis.

S-Parameters

Figure 12-1 S-Parameter Model with 4 Ports (Maximum of 12 Ports Allowed)



Defining Ports

You can define ports for all diodes, IOCells, non-zero voltage sources, and other nodes of interest. Voltage sources without ports become part of the S-parameter black box model. Non-zero voltage sources and IOCells without ports are open circuited during S-parameter generation. If there are no defined ports, an error message appears, and S-parameter generation aborts.

You define ports in the <u>S-Parameter Generation</u> dialog.

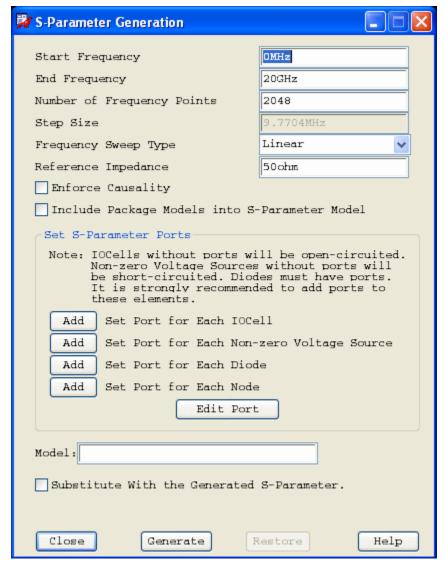
To define ports, do the following:

1. Choose Analyze – [S] Generation...

The <u>S-Parameter Generation</u> dialog is displayed.

- 2. Click *Add* to automatically generate ports for:
 - □ IOCells
 - □ Non-zero voltage source
 - □ Diodes
 - □ Nodes

Figure 12-2 S-Parameter Generation



For automatic port setting, set port names with a Refdes_PinNumber which you can change later in the Port Editing dialog.

For manual port setting, enter the port name for each port. The ports appear on the SigXplorer canvas as you edit them.



Automatically set ports when you want to look at the loss end frequency of the whole channel. To only focus on a portion of the topology, manually place the ports.

S-Parameters



If you want to place ports at a node in the middle of a topology, someplace other than at IOCells and sources, isolate the item (that you are trying to capture as S-params) from the rest of the circuit to avoid including them in the black box model.

See <u>S - Parameter Generation Dialog</u> for detailed information on the various options in this dialog.

S-Parameters

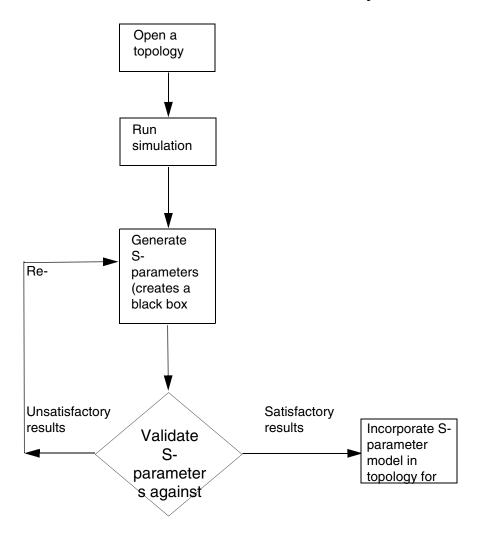
Time Domain Analysis

S-parameter black boxes provide a complete description of the behavior of a given network as seen at its ports, enabling time domain analysis (TDA) of a circuit. The circuit simulator uses the black boxes without knowing the topology of the network.

You can use S-parameters for TDA to:

- Incorporate measured data for known or fixed elements in the signal path for simulations. For example, a legacy backplane.
- Provide a black box model for a complex section of topology for use in simulation by another user. For example, a package vendor provides the black box model to a system engineer.

Figure 12-3 S-Parameter Validation Flow for Time Domain Analysis





When using S-parameters for time domain analysis:

- □ Follow the usage recommendations for Start Frequency, End Frequency, and number of points, as described following this tip.
- □ Use Linear sweep; not Logarithmic.
- □ Ensure that via models support the requested S-parameter bandwidth, if they exist in the topology.

S-Parameters



The recommended Start Frequency is $0 \, \text{MHz}$. The end frequency should be about 2/t_rise, such as you use for fine waveform resolutions of 5 or 10 ps. The number of frequency points should be a power of 2, with a frequency step of about $10 \, \text{MHz}$.

S Parameter Settings Example

Edge Rate	Start Freq.	End Freq.	Bandwidth	Freq. Step	No. of Freq. Points
100 ps	0 MHz	20GHz	20 GHz	10 MHz	2048

After generating the DML ESpice model for the S-parameter data, use the S-parameter black box in the same way that you use an ESpice black box. The S-parameter black box use model is as follows:

- Generate DML models for the S-parameter data, as shown in <u>Generating an S-Parameter Black Box</u> on page 224
- Load the DML library that contains the S-parameter models, if it is not present.
- Add the S-parameter black box part to the canvas. Use *Add Part* and then select an ESpice device that contains S-parameter data.
- Connect any element supported in SigXplorer to the S-parameter black box (including non-linear IBIS I/O buffers, transmission lines, lumped elements) and simulate.
- Edit the simulation preferences, if necessary, and validate the simulation results against the source topology.

The S-parameter black box symbol automatically appears when you select an S-parameter DML model from the $Add\ Part$ menu. The S tag that appears in the middle of the symbol represents the S-parameter black box, as shown in Figure 12-1 on page 215.

The ESpice device model name and the outer .subckt name for the black box must be the same. The maximum number of ports of the S-parameter data is twelve. The number of terminals of the generated symbol is equal to the model's subckt terminal count (which is equal to the number of ports). The black box terminal names are the same as the outer .subckt terminal names in the DML model and appear on the symbol from left-to-right, top-to-bottom.

S-Parameters



To control the order of the terminals on the SigXplorer canvas, edit the outer .subckt terminal names in the DML model, and then map the outer .subckt terminals to the corresponding inner .subckt terminals when you instantiate the inner .subckt.

Typical Use Models

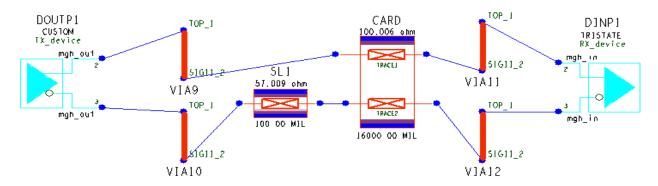
Viewing Frequency Response Using S-Parameters

One of the primary benefits of using S-parameters is the ability to plot them and examine the loss exhibited by the interconnect. This example is a typical use model.

1. In SigXplorer open a topology similar to Figure 12-4.

The backplane and receiving card appear in detail.

Figure 12-4 Source Topology



- **2.** Choose *Analyze Preferences*.
- **3.** In the *Simulation Parameters* tabbed page, set the *Waveform Resolution* to 10 ps.
- **4.** Set the *Default Cutoff Frequency* to 10GHz.

/Important

Change the Default Cutoff Frequency to avoid modeling a lossless case.

5. Choose Analyze – [S] Generation...

The <u>S-Parameter Generation</u> dialog appears.

6. Click *Add* next to the *Set Port for each IOCell* option.

The ports automatically appear in the topology with names.

S-Parameters

7. Specify the following values:

Start Frequency 1 Hz

End Frequency 10 GHz

Frequency Points 1024

Model 16inch

8. Click Generate.

The S-Parameter Generation log appears.

- **9.** Examine the Port Index to determine which port numbers to look at to see the transmission.
- **10.** In SigWave, turn off *Re*, *Im*, and *Ph*. Turn on *Ma* (magnitude).
- **11.** Click the *push pin icon* to keep these settings.
- **12.** Turn off all sub-items in SigWave and turn on the transmission plot per the port index.
- **13.** Put a vertical marker at 4GHz and zoom in at the crossing point.

The loss is greater than the loss budget of 10dB. The simple solution is to reduce the trace length.

- **14.** In SigXplorer, close the S-Parameter Generation dialog.
- **15.** Change the length of the coupled trace from 16inches to 10inches (*Parameters tab*).
- **16.** Click Analyze [S] Generation...

The S-Parameter Generation dialog appears.

- 17. Enter 10 inch in the Model field.
- **18.** Click *Generate* to re-generate the S-parameters.
- **19.** In SigWave, overlay the two waveforms and compare.

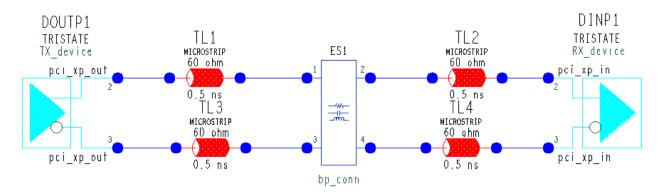
The trace length now meets the loss budget.

Generating an S-Parameter Black Box

You generate an ESpice Device model black box to replace a topology, or some elements of the topology, for use in what-if situations.

1. In SigXplorer, open an existing topology, as seen in Figure 12-5.

Figure 12-5 Topology without Generated S-Parameters



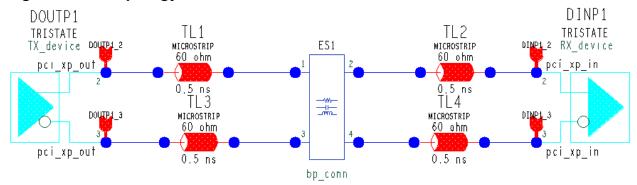
2. Choose Analyze – [S] Generation...

The S-Parameter Generation dialog appears.

3. Click Add next to the Set Port for each IOCell option.

The added ports appear in the canvas, as seen in Figure 12-6.

Figure 12-6 Topology with Ports on IOCells

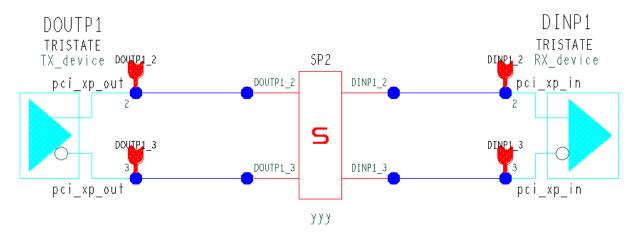


- 4. Select the Substitute with the Generated S-Parameter option.
- 5. Click Generate.

The original topology updates with the generated S-parameter black box, as seen in Figure 12-7.

S-Parameters

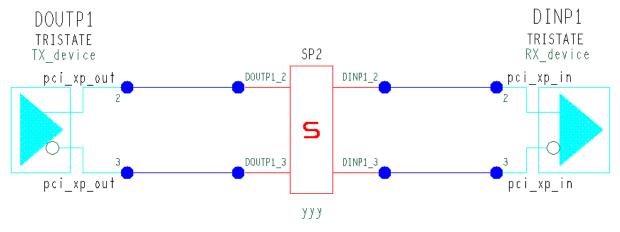
Figure 12-7 Generated S-Parameter Black Box



6. Click Close.

The dialog closes and all ports disappear from the topology. See <u>Figure 12-8</u>. The new S-parameter model appears in the working DML library as a Touchstone file.

Figure 12-8 Updated Topology



Allegro SI SigXplorer User Guide S-Parameters

Custom Measurements

13

Custom Measurements

Topics in this chapter include:

- Introduction on page 228
- Measurement Expressions on page 229
- Exporting and Importing Custom Measurements on page 233
- Custom Measurement Editor Message Reference on page 233

Custom Measurements

Introduction

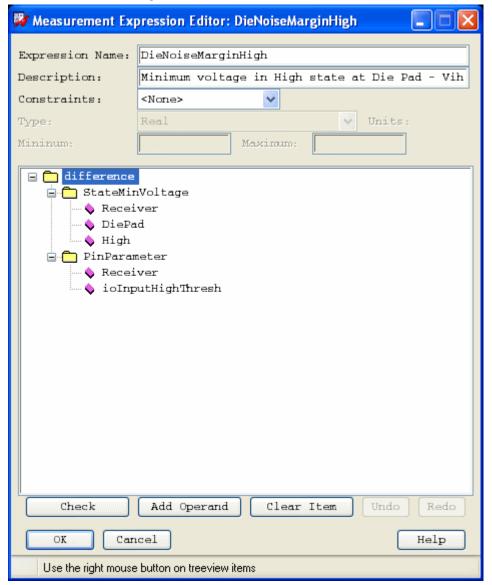
By defining and evaluating custom measurements, you can obtain new data from signal integrity simulations. Customized expressions provide the simulation data that fits your requirements.

You use the Measurement Expression Editor to build syntactically correct measurement expressions. In a custom measurement expression, you use parameter substitution, math functions, predefined measurements, and references to other custom measurement expressions you create. You evaluate the measurement expressions during simulation.

Note: You can only have one Measurement Expression Editor dialog open at a time.

Measurement Expressions

Figure 13-1 Measurement Expression Editor



Use this dialog to create and modify customized measurement expressions for SigXplorer. When you open the Measurement Expression Editor to edit an existing expression, the name of the expression appears in both the Expression Name field and in the title bar. For more information about the editor, see the <u>SigXplorer Command Reference</u>.

Custom Measurements

Number

Enter literal numbers in custom measurement expressions in decimal or scientific notation. They can have units or Spice scaling suffixes (f, p, n, u, m, k, meg, g, t), but they cannot include white space. The units.dat file defines usable unit suffixes.

Reference to another measurement expression

Reference standard and user-defined measurements by their measurement expression names. When you select from the tree view MEASUREMENT_TBD, or any other placeholder that you replace with a measurement, the pull-down menu includes all standard measurements available in the Reflection, Crosstalk, and EMI sections of the Measurements tab, as well as all currently available custom measurement expressions. User-defined custom measurements appear alphabetically, following the standard measurements.

Note: To avoid recursive expressions, the measurement you are currently editing does not appear on the list.

Pin parameter reference

Obtain numeric data from the library definitions of pins and IOCells available in measurement expressions. You access the data using the PinParameter function, which has the following arguments:

- PIN TBD
- PARAMETER TBD

Note: The values for some parameters are sensitive to the current Fast/Typical/Slow settings for the pin.

Waveform measurement function call

Specify the waveform function by pin and node name. Pin names are:

- Receiver name of the measured receiver pin
- Driver name of the active driver pin
- Strobe name of the strobe pin associated with the receiver
- "comp.pin" exact pin name in dot notation (use double quotes)

Custom Measurements

Math function call

Specify the following math functions to perform calculations. All arguments are numeric.

- Min Function return is the lesser of one or more values.
- Max Function return is the greater of one or more values.
- Sum Function return is the sum of two or more values.
- Difference Function return is the difference between two or more values.
- Product Function return is multiples of two or more values.
- Quotient Function return is the division of two or more values.
- Abs Function return is the absolute value of the input argument.

Note: In functions, all arguments evaluate as either a single number or as NA. Run mode ignores NA returns from functions and appears as NA in the simulation results data.

Function calls introduce hierarchy by calling nested arguments.

The following table lists the standard measurements that can be referenced by name in measurement expressions. These same standard measurements appear on the Measurements tab of the spreadsheet.

Measurement	Туре	Description
Crosstalk	Voltage	Maximum voltage excursion on crosstalk victim net. (Crosstalk measurement)
NoiseMargin	Voltage	Minimum of NoiseMarginHigh or NoiseMarginLow (Reflection measurement)
NoiseMarginHigh	Voltage	Minimum noise margin (voltage) in the high state (Reflection measurement)
NoiseMarginLow	Voltage	Vilmax minus the maximum noise margin (voltage) in the low state (Reflection measurement)
SettleDelay	Time	Maximum of SettleDelayRise and SettleDelayFall (Reflection measurement)

Allegro SI SigXplorer User Guide Custom Measurements

Time	Final time to settle high above Vihmin minus BufferDelayRise (Reflection measurement)	
Time	Final time to settle low below Vilmax minus BufferDelayFall (Reflection measurement)	
Time	Minimum of SwitchDelayRise and SwitchDelayFall (Reflection measurement)	
Time	First time to switch low below Vihmin minus BufferDelayFall (Reflection measurement)	
Time	First time to switch high above Vilmax minus BufferDelayRise (Reflection measurement)	
Voltage	Maximum voltage seen in High state (Reflection measurement)	
Voltage	Minimum voltage seen in the Low state (Reflection measurement)	
Time	Calculated transmission line propagation delay (Reflection measurement)	
Frequency	Frequency of the excitation pulse (EMI measurement)	
0 or 1	Monotonic switching check of Rising and Falling edges (Reflection measurement)	
0 or 1	Monotonic switching check of Rising edge (Reflection measurement)	
0 or 1	Monotonic switching check of Falling edge (Reflection measurement)	
0 or 1	First Incident Switching check of Rising edge (Reflection measurement)	
0 or 1	First Incident Switching check of Falling edge (Reflection measurement)	
Time	Buffer Delay for Rising edge (Reflection measurement)	
Time	Buffer Delay for Falling edge (Reflection measurement)	
Voltage	Peak to Peak voltage of the excitation (EMI measurement)	
	Time Time Time Time Voltage Voltage Time Frequency 0 or 1 0 or 1 0 or 1 1 or 1 Time Time Time	

Custom Measurements

RiseTime	Time	Minimum of the rise and fall times of the excitation (EMI measurement)
PeakEmission	DBuV/m	Peak Radiated Electric Field dBuV/m (EMI measurement)
PeakFrequency	Frequency	Frequency at which PeakEmission occurs (EMI measurement)
EMIStatus	0 or 1	PASS/FAIL check of EMI regulation compliance (EMI measurement)

Exporting and Importing Custom Measurements

You save custom measurements as part of the topology where you created them. In order to use the custom measurement expressions with another topology, you must export the custom measurement expressions for the first topology to a text file. You can then import the text file to another topology, where you can edit the individual expressions.

Custom Measurement Editor Message Reference

When you check a custom measurement expression during an editing session, the following error and warning messages appear:

ERROR: 'VALUE_TBD' must be replaced with a valid value.

Probable Cause: There are _TBD placeholders in the expression.

Suggested Solution: Replace the indicated placeholder with a valid argument.

ERROR: 'VoltageAtTime' argument 3 must be a number, measurement name, parameter name, or function call

Probable Cause: You entered an invalid numeric function argument. You probably imported a corrupted custom measurement expression file.

Suggested Solution: Replace the invalid argument with a number, or with a legal measurement name, parameter name or function call.

ERROR: 'FooBar' is not a recognized parameter or measurement name

Probable Cause: The referenced parameter or measurement, FooBar, does not exist. You probably imported a corrupted custom measurement expression file.

Custom Measurements

Suggested Solution: The check operation verifies that you only use valid and available parameters and measurements in expressions. Verify that the parameter or measurement is not gone, and that the name is spelled correctly.

ERROR: Unable to convert '3.25smoots' to a number

Probable Cause: The argument 3.25smoots appears to be a number, but it is not.

Suggested Solution: Anything that starts off looking like a number is parsed as a number.

ERROR: 'factorial' is not a recognized function name

Probable Cause: The first word following a left parenthesis must be a function name.

Suggested Solution: Enter a valid function name or remove the parenthesis character.

ERROR: First argument to 'CrossingTime' function must be a pin designator

Probable Cause: This error can occur when an expression that is specific to one topology (for example, it uses explicit pin names) is used in another topology.

Suggested Solution: This check is made for all waveform function calls. Modify the expression so that its arguments reflect the topology you are using it with.

ERROR: Third argument to 'CrossingTime' function must be a number

Probable Cause: The expression contains a parameter or function call in a position where only a number is valid.

Suggested Solution: Replace the parameter or function call with a number.

WARNING: No pins with 'input' trace used in 'CrossingTime' function

Suggested Solution: Special nodes defined in MacroModels will apply only to pins that use that MacroModel. The evaluator returns nil for other pins. This warning tells when a node is not found.